

# PCA9460

## 13-channel power management integrated circuit (PMIC) for ultra-low power applications

Rev. 3.4 — 10 January 2024

Product data sheet

## 1 General description

The PCA9460 is a single chip Power Management IC (PMIC) designed to support ultra-low-power applications where standby power and overall power consumption of power management IC is critical. The PCA9460 is designed to be paired with i.MX 8ULP processor which enables such key applications. It provides power supply solutions for low power wearable application where size and efficiency are critical.

The PCA9460 comes equipped with four buck regulators, five LDOs and additional load switches. This design offers the most flexible configuration for i.MX 8ULP or other processors to enable the ultra-low-power system design. Each buck regulator has been designed with ultra-low I<sub>q</sub> current to reduce standby current. Two buck regulators support smart Dynamic Voltage Scaling (DVS), which allows the system designed to set the right voltage on the processors the PCA9460 is powering. This process minimize power consumption that is controlled through the PMIC\_STBY\_REQ pin or MODE[2:0] pins. Five LDOs have 300 nA low quiescent current. One LDO is available for SNVS core power supply, one 250 mA LDO is to regulate to low output voltage from buck regulator output. Three 250 mA LDOs supply power to the processor and peripheral devices. Four 150 mΩ load switches switch power for peripheral devices. These switches can be configured as an LED driver with two different blink modes.

The PCA9460 is offered in a 42-bump wafer-level CSP package, 2.86 mm x 2.46 mm, 0.4 mm pitch.

## 2 Features and benefits

Ultra-low-power system design for long battery life or green offline performance using:

- Four buck regulators
  - Two 1 A buck regulators
  - Two 1 A buck regulator with DVS
  - Low I<sub>q</sub> (1.5 μA at low power mode, 5.5 μA at normal mode)
- Five linear regulators
  - One 250 mA NMOS LDO
  - Three 250 mA PMOS LDO
  - 10 mA SNVS LDO
  - Built-in active discharge resistor
- Four Load Switches with active discharge resistor to allow easy connect/disconnect of multiple system rails
  - 150 mΩ R<sub>dson</sub>
  - ON/OFF control in different modes
  - Configurable to LED driver with two blink patterns
- Power control IO for intelligent system design
  - Power ON/OFF control
  - Standby/Run mode control
  - Smart DVS control
- Flexible power ON/OFF sequence



13-channel power management integrated circuit (PMIC) for ultra-low power applications

- Fm+ 1 MHz I<sup>2</sup>C Interface allows continuous communication with the host
- ESD protection
  - Human Body Model (HBM) : ± 2000 V
  - Charged Device Model (CDM) : ± 500 V
- 7 x 6 bump array, 0.4 mm pitch, WL-CSP, 2.86 mm x 2.46 mm enables a small solution size

### 3 Applications

- Ultra-low-power portable devices
  - eReader
  - Tablet
  - Watch
  - Portable headset
  - Handheld printer/scanner
  - Bike computer

### 4 Ordering information

Part number	Orderable part number	Topside marking	Temperature range (TA)	Processor and DDR Memory Platform	Package		
					Name	Description	Version
PCA9460AUK	PCA9460AUKZ	N9460A	-40 °C to +85 °C	Ideal for i.MX 8ULP + LPDDR4	WLCSP42	Wafer Level Chip-Scale package; 42 bumps; 2.86 mm x 2.46 mm x 0.525 mm body (backside coating included), 0.4 mm pitch	<a href="#">SOT1459-7</a>
PCA9460BUK	PCA9460BUKZ	N9460B		Ideal for i.MX 8ULP + LPDDR4X			
PCA9460CUK	PCA9460CUKZ	N9460C		Ideal for i.MX 8ULP + LPDDR3			

### 5 Internal block diagram

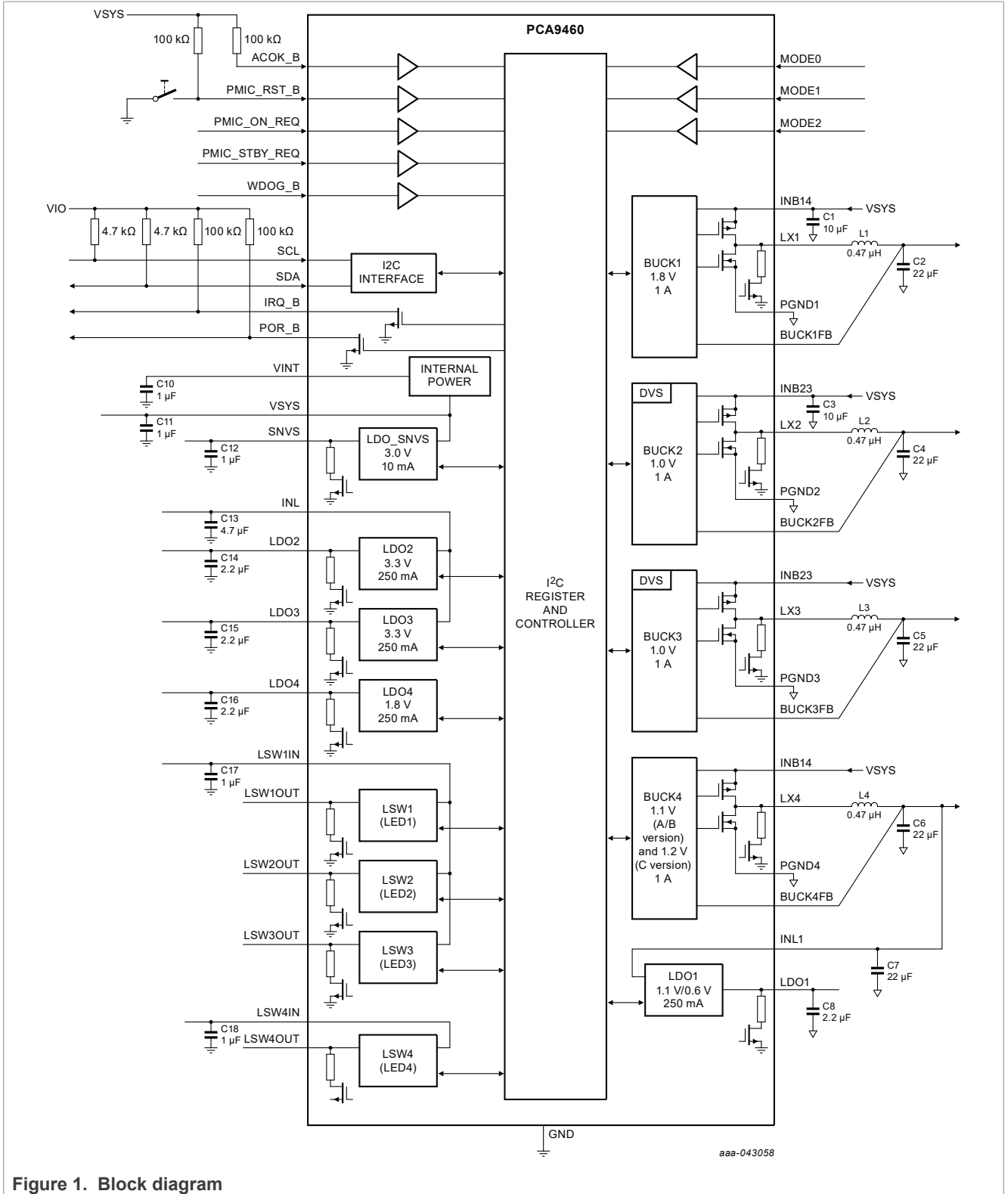


Figure 1. Block diagram

## 6 Pinning information

### 6.1 Pinning

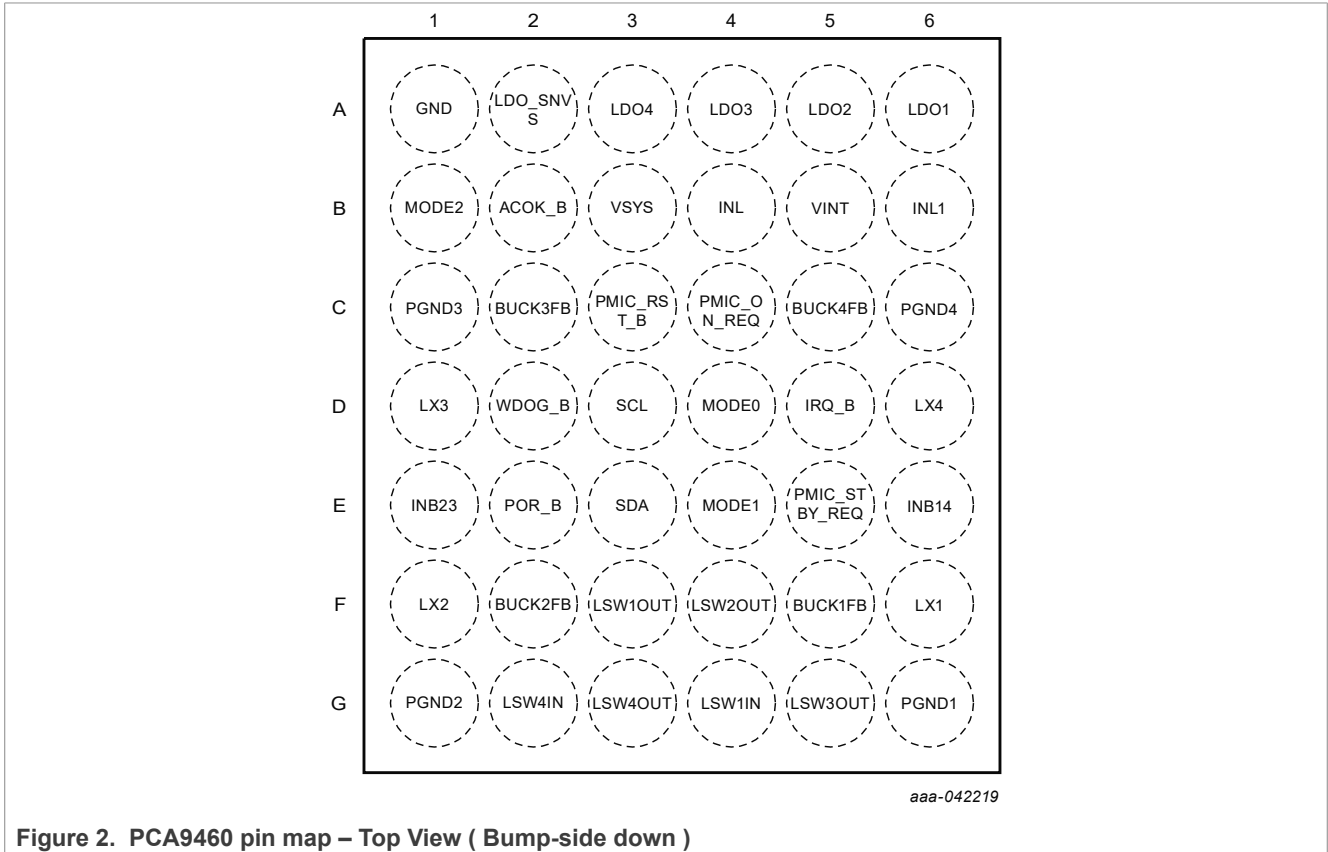


Figure 2. PCA9460 pin map – Top View ( Bump-side down )

### 6.2 Pin description

Table 1. Pin description

Symbol	Pin	Type	Description
MODE0	D4	DI	Digital MODE0 input pin
MODE1	E4	DI	Digital MODE1 input pin
MODE2	B1	DI	Digital MODE2 input pin
ACOK_B	B2	DI	PMIC ON signal
PMIC_RST_B	C3	DI	PMIC reset input pin. Once it is asserted low, PMIC performs cold reset.
POR_B	E2	DO	Power On reset output pin. Open drain output requiring external pull up resistor.
PMIC_ON_REQ	C4	DI	PMIC ON input from Application processor. When it is asserted high, the device starts power on sequence.
PMIC_STBY_REQ	E5	DI	Standby mode input from Application processor. When it is asserted high, device enters STANDBY mode.
SCL	D3	DI	I <sup>2</sup> C serial clock pin
SDA	E3	DIO	I <sup>2</sup> C serial data pin
WDOG_B	D2	DI	Watchdog reset input from application processor

## 13-channel power management integrated circuit (PMIC) for ultra-low power applications

Table 1. Pin description...continued

Symbol	Pin	Type	Description
IRQ_B	D5	DO	PMIC interrupt pin, Open drain output requiring external pull up resistor
INB14	E6	P	Buck 1 / Buck 4 input pin, bypass with 10 $\mu$ F
LX1	F6	P	Buck 1 switching node
PGND1	G6	P	Buck 1 Power ground
BUCK1FB	F5	AI	Buck 1 feedback pin
INB23	E1	P	Buck 2 / Buck 3 input pin, bypass with 10 $\mu$ F
LX2	F1	P	Buck 2 switching node
PGND2	G1	P	Buck 2 Power ground
BUCK2FB	F2	AI	Buck 2 feedback pin
LX3	D1	P	Buck 3 switching node
PGND3	C1	P	Buck 3 Power ground
BUCK3FB	C2	AI	Buck 3 feedback pin
LX4	D6	P	Buck 4 switching node
PGND4	C6	P	Buck 4 Power ground
BUCK4FB	C5	AI	Buck 4 feedback pin
VSYS	B3	P	Internal power input. Bypass with a 1 $\mu$ F to Ground
LDO_SNV5	A2	P	LDO_SNV5 output pin, bypass with 1 $\mu$ F to Ground
INL	B4	P	LDO2/LDO3/LDO4 power input pins, bypass with a 4.7 $\mu$ F to Ground
LDO2	A5	P	LDO2 output. Bypass with a 2.2 $\mu$ F to Ground
LDO3	A4	P	LDO3 output. Bypass with a 2.2 $\mu$ F to Ground
LDO4	A3	P	LDO4 output. Bypass with a 2.2 $\mu$ F to Ground
INL1	B6	P	LDO1 input pins, bypass with a .2.2 $\mu$ F to Ground
LDO1	A6	P	LDO1 output. Bypass with a 2.2 $\mu$ F to Ground
LSW1IN	G4	P	Load Switch input pin. Bypass with 1 $\mu$ F to Ground
LSW1OUT	F3	P	Load Switch output pin, if LSW1 is configured to LED driver, LSW1OUT is current source for LED
LSW2OUT	F4	P	Load Switch output pin. if LSW2 is configured to LED driver, LSW2OUT is current source for LED
LSW3OUT	G5	P	Load Switch output pin. if LSW3 is configured to LED driver, LSW3OUT is current source for LED driver
LSW4IN	G2	P	Load Switch input pin. Bypass with 1 $\mu$ F to Ground
LSW4OUT	G3	P	Load Switch output pin. if LSW4 is configured to LED driver, LSW4OUT is current source for LED
VINT	B5	P	Internal power supply output, bypass with 1 $\mu$ F to GND
GND	A1	P	Analog ground pin

## 7 Functional description

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### 7.1 Features

The PCA9460 is a power management integrated circuit (PMIC) designed to be the primary power management for NXP processors, 8ULP.

- Four buck regulators
  - Two 1A buck regulators
  - Two 1A buck regulator with DVS
  - Built-in active discharge resistor
  - Low I<sub>q</sub> ( 1.5 μA at low power mode, 5.5 μA at normal mode )
- Five linear regulators
  - One 250 mA NMOS LDO
  - Three 250 mA PMOS LDO
  - Built-in active discharge resistor
  - 10 mA SNVS LDO
- Four load switches with active discharge resistor
  - 150 mΩ R<sub>dson</sub>
  - ON/OFF control in different modes
  - Configurable to LED driver with two blink patterns
- Power control IO
  - Power ON/OFF control
  - Standby/Run mode control
  - Smart DVS control
- Flexible power ON/OFF sequence
- Fm+ 1 MHz I<sup>2</sup>C Interface
- ESD protection
  - Human Body Model (HBM) : +/- 2000 V
  - Charged Device Model (CDM) : +/-500 V
- 6 x 7 bump array, 0.4 mm pitch, WL-CSP, 2.86 mm x 2.46 mm

7.2 Functional diagram

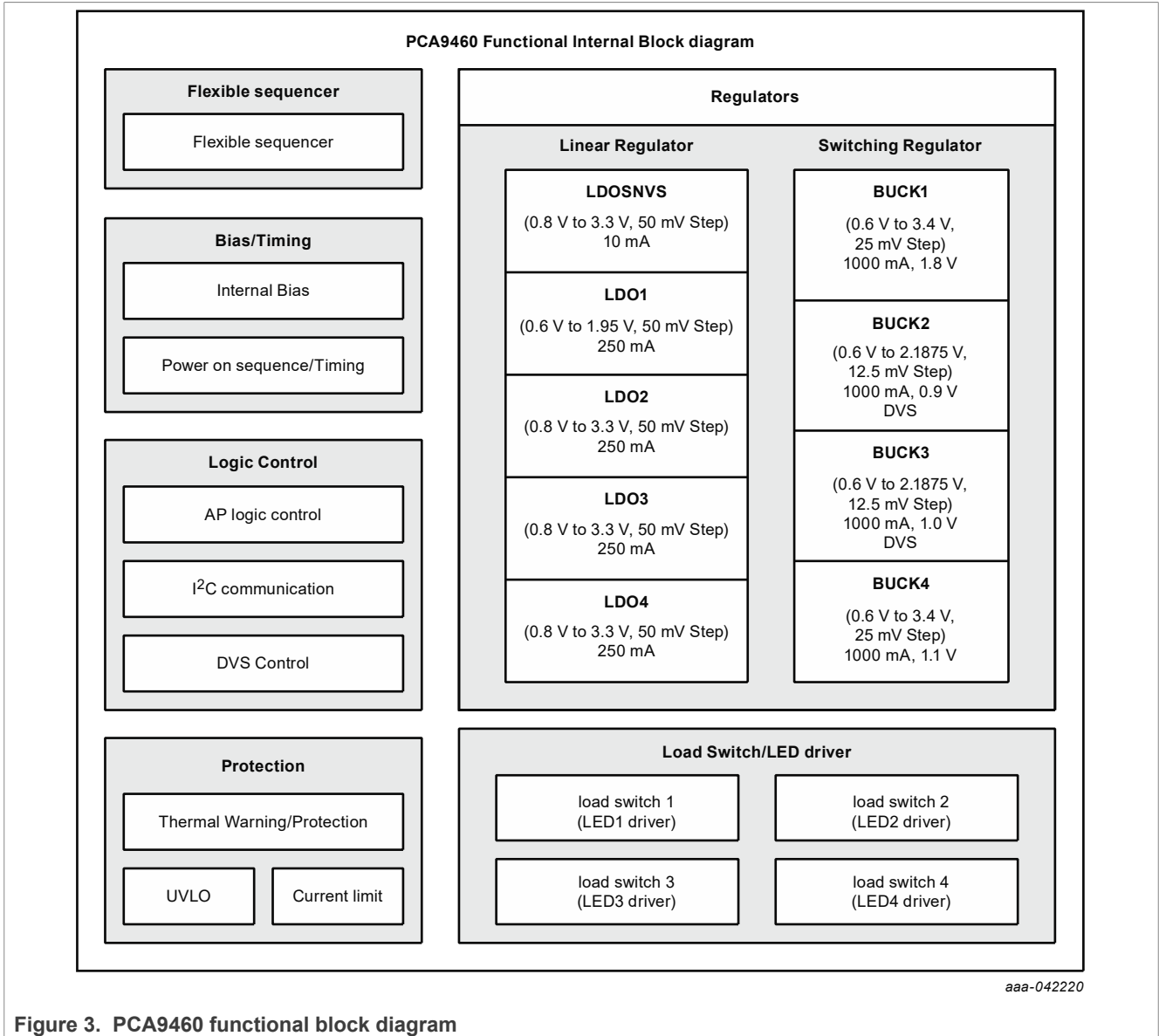


Figure 3. PCA9460 functional block diagram

7.3 PCA9460 version

The PCA9460 can be configured to each regulator default voltage and start-up sequence from the internal OTP configuration. [Table 2](#) shows each OTP configuration for all devices.

Table 2. OTP configuration

PCA9460A = i.MX 8ULP + LPDDR4; PCA9460B = i.MX 8ULP + LPDDR4X; PCA9460C = i.MX 8ULP + LPDDR3

Address	Register	PCA9460A	PCA9460B	PCA9460C	Description
0x01	OTP_VER	0x02	0x11	0x21	PCA9460A - Rev. 2 ; PCA9460B - Rev. 1 ; PCA9460C - Rev. 1
0x0A	PWR_SEQ_CTRL	0x06			2 ms TON_STEP & 8 ms TOFF_STEP
0x0C	SYS_CFG2	0x71			2 sec ONKEY timer; Normal Power Mode; 2.85 V VSYS UVLO
0x10	BUCK1CTRL	0x39			Normal mode; Enable Active Discharge Resistor ; Buck 1 ON at RUN state
0x11	BUCK1OUT	0x30			1.8 V
0x14	BUCK2CTRL	0x79			25 mV/2 μs DVS speed; Normal mode; Enable Active Discharge Resistor; Buck 2 ON at RUN state
0x15	BUCK2OUT_DVS0	0x20			1.0 V
0x1F	BUCK2OUT_MAX_LIMIT	0x38			1.3 V
0x21	BUCK3CTRL	0x79			25 mV/2 μs DVS speed; Normal mode; Enable Active Discharge Resistor; Buck 3 ON at RUN state
0x22	BUCK3OUT_DVS0	0x20			1.0 V
0x2C	BUCK3OUT_MAX_LIMIT	0x38			1.3 V
0x2E	BUCK4CTRL	0x39			Normal mode; Enable Active Discharge Resistor ; Buck 4 ON at RUN state
0x2F	BUCK4OUT	0x14	0x18		PCA9460A & PCA9460B = 1.1 V ; PCA9460C = 1.2 V
0x30	LDO1_CFG	0x9D			LDO1 Auto Cout; 15 mΩ out trace compensation; Normal mode; LDO1 ON at RUN state
0x31	LDO1_OUT	0x8A	0x80	0x8C	PCA9460A = 1.1 V ; PCA9460B = 0.6 V ; PCA9460C = 1.2 V
0x32	LDO2_CFG	0x11			Enable Active Discharge Resistor ; LDO2 ON at RUN state
0x33	LDO2_OUT_L	0x32			3.3 V on LDO2 when LDO2_VSEL = Low
0x34	LDO2_OUT_H	0x14			1.8 V on LDO2 when LDO2_VSEL = High
0x35	LDO3_CFG	0x11			Enable Active Discharge Resistor ; LDO3 ON at RUN state
0x36	LDO3_OUT	0x32			3.3 V
0x37	LDO4_CFG	0x11			Enable Active Discharge Resistor ; LDO4 ON at RUN state
0x38	LDO4_OUT	0x14			1.8 V
0x39	LDOSNVS_CGF	0xEC			Enable Active Discharge Resistor ; Always ON mode ; 3.0 V output
0x40	LSW1_CTRL	0x11			Load Switch mode; Enable Active Discharge; Load SW1 ON at RUN State
0x41	LSW2_CTRL	0x11			Load Switch mode; Enable Active Discharge; Load SW2 ON at RUN State
0x42	LSW3_CTRL	0x11			Load Switch mode; Enable Active Discharge; Load SW3 ON at RUN State
0x43	LSW4_CTRL	0x11			Load Switch mode; Enable Active Discharge; Load SW4 ON at RUN State



7.4 Power states

PCA9460 has six power states: OFF, SNVS, RUN, PWRDN, PWRUP and FAULT\_SD. Figure 4 shows the state transition diagram showing the conditions to enter and exit each state.

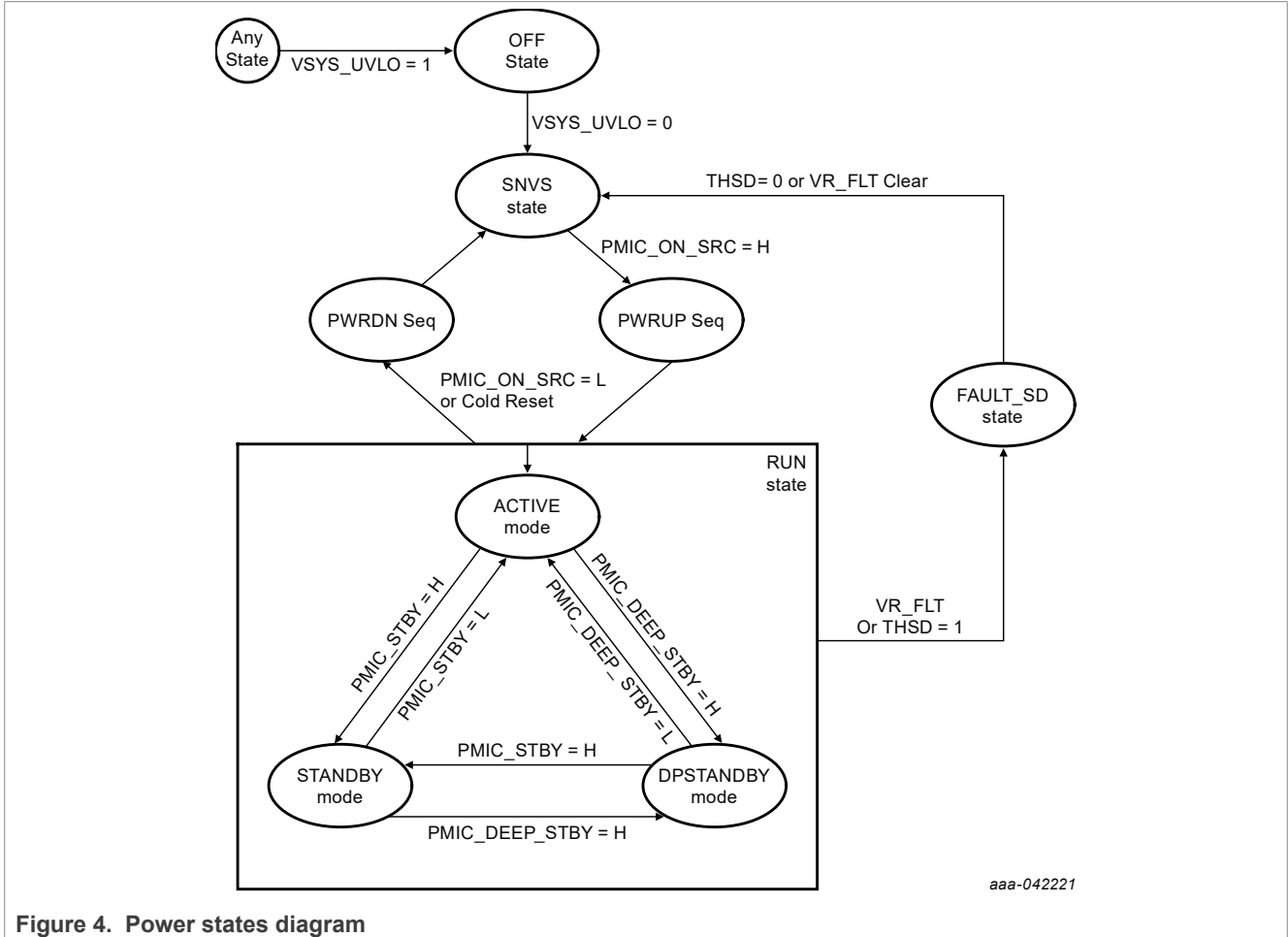


Figure 4. Power states diagram

7.4.1 Off state

PCA9460 enters OFF state from any state when  $VSYS$  falls below  $V_{SYS\_UVLO}$  threshold. All regulators including LDO\_SNVS are off, and all registers get reset in the state.

7.4.2 SNVS state

PCA9460 enters SNVS ( Secure Non-Volatile Storage mode ) when  $VSYS$  exceeds  $VSYS\_UVLO$  rising threshold. LDO\_SNVS is turned on within  $t_{SNVS}$ . After turning LDO\_SNVS on, it monitors power on source signals to move to PWRUP state.

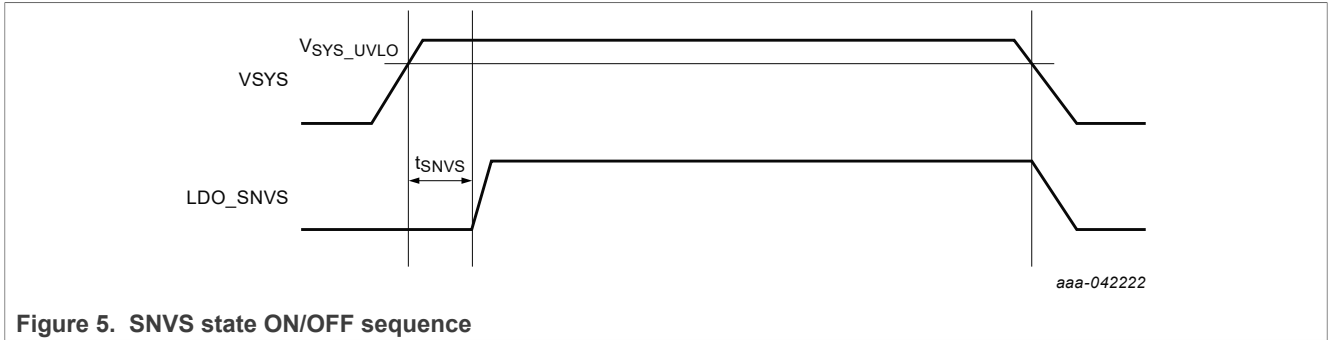


Figure 5. SNVS state ON/OFF sequence

Time	Description	Value	Comment
$t_{SNVS}$	Maximum time to enable LDO_SNVS from VSYS UVLO detected	20 ms	

7.4.3 PWRUP state

7.4.3.1 Power ON sources

When internal signal, PMIC\_ON\_SRC, is asserted high in SNVS state, it starts powering up regulators with pre-defined power ON sequence. PMIC\_ON\_SRC signal is generated by below three signals.

- PMIC\_ON\_REQ after its debounce time
- PMIC\_RST\_B after its ONKEY debounce time. (It can be masked in PWR\_SEQ\_CTRL register)
- ACOK\_B after its debounce time → OTP option to be disabled. (It can be masked in PWR\_SEQ\_CTRL register)

Figure 6 show the block diagram how PMIC\_ON\_SRC is generated.

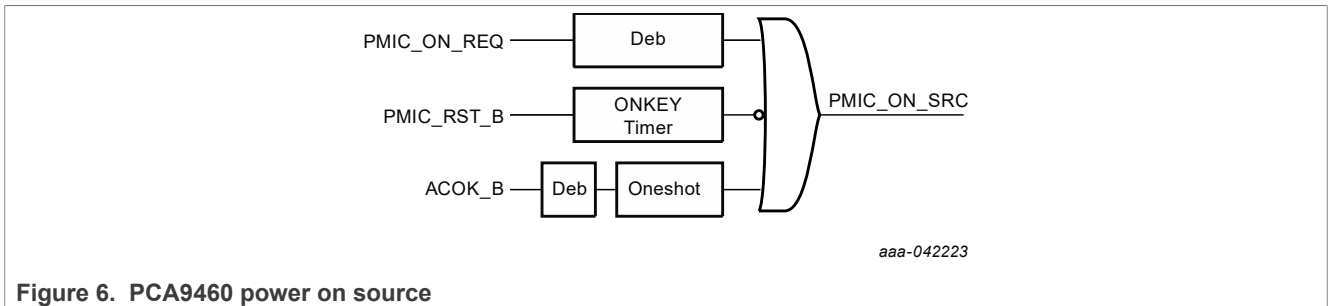


Figure 6. PCA9460 power on source

When ACOK\_B signal is configured as Power on source in PWR\_SEQ\_CTRL register, One shot signal is generated from the falling edge of ACOK\_B and the signal is maintained high for  $t_{ACOK\_B\_Oneshot}$ . If PMIC\_ON\_REQ pin is asserted high before one shot timer is expired, PMIC is kept powered on. If not, PCA9460 takes power-off sequence after one shot timer.

ACOKB\_S status bit in INT1\_STATUS register is updated after its debounce timer,  $t_{ACOK\_B\_DEB}$ .

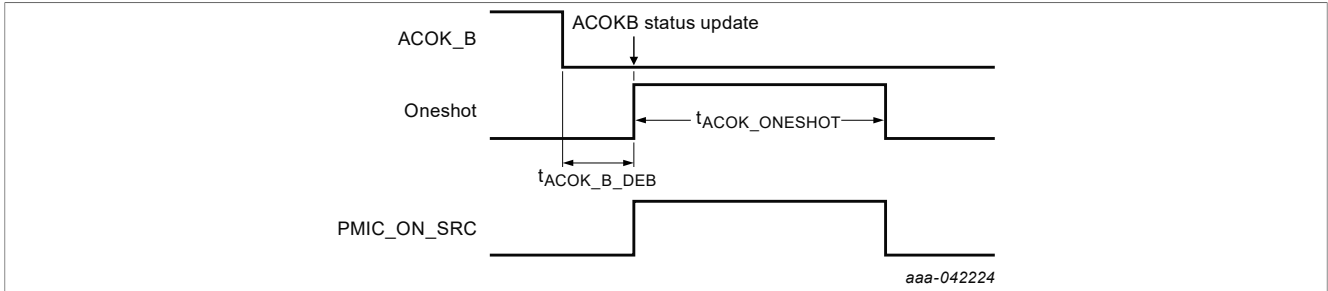


Figure 7. ACOK\_B timing

PMIC\_RST\_B pin is used to turn on PCA9460 at SNVS state or to make PMIC reset at RUN state after detecting PMIC\_RST\_B falling edge. PMIC\_RSTB\_S status bit in INT1 STATUS register is updated in debounce time,  $t_{DEB\_PMIC\_RST\_B}$ , after falling edge detection.

When PMIC\_RST\_B falls low at SNVS state, then it starts counting timer. After ONKEY timer expired, ONKEY\_S status bit is updated and PMIC\_ON\_SRC signal is generated if PMIC\_RST\_B pin is configured to power on source in PWR\_SEQ\_CTRL register. PMIC\_ON\_SRC is generated by PMIC\_RST\_B pin only when PCA9460 is in SNVS state. If ONKEY timer is expired at RUN state, only ONKEY\_S bit is updated.

When PMIC\_RST\_B pin falls low at RUN state and RESETKEY timer is expired, RESETKEY\_S status bit is updated and perform reset function configured in RESET\_CTRL register after  $t_{RESET\_WAIT}$ , which is for AP to determine to proceed reset or not. For detail reset behavior, refer to [Section 7.5](#).

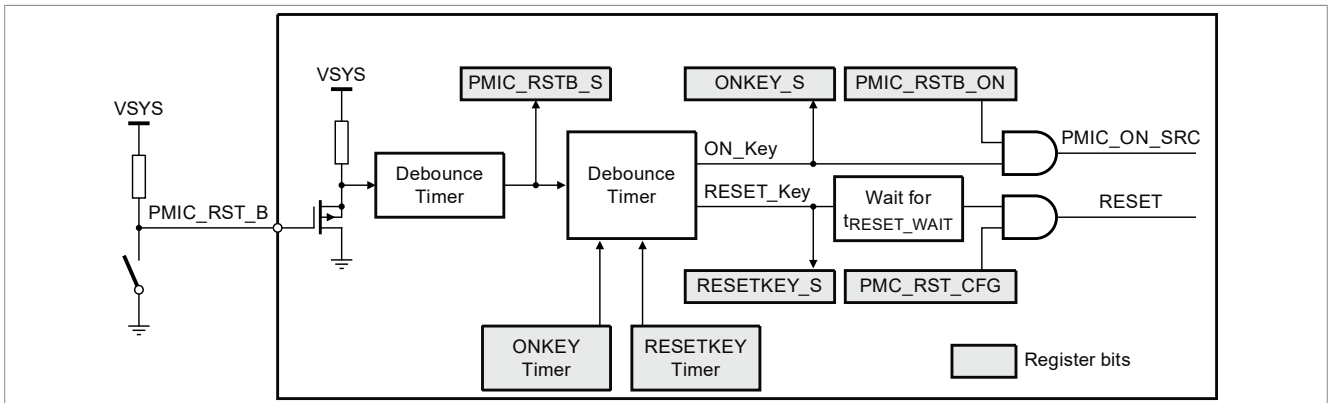


Figure 8. PMIC\_RST\_B block diagram

7.4.3.2 Power ON sequence

PCA9460 supports flexible power sequencer which power-on sequence can be pre-programmed in OTP.

When PMIC\_ON\_SRC is asserted high, PUD\_T1 group is turned on at first in  $t_{ON\_STEP}$  after PMIC\_ON\_SRC is high. The next group, PUD\_T2 is turned on in  $t_{ON\_STEP}$  after POK of PUD\_T1 group regulator(s) is high. If the POK doesn't come up within  $t_{POK\_EXP}$ , then the POK is ignored and the next group is turned ON in  $t_{ON\_STEP}$ . This power on sequence ended up releasing POR\_B pin high impedance in  $t_{RSTB}$  after the last group, PUD\_T16 regulator is turned ON. PUD group which any regulator is not assigned, the next PUD group is turned on in  $t_{ON\_STEP}$ .

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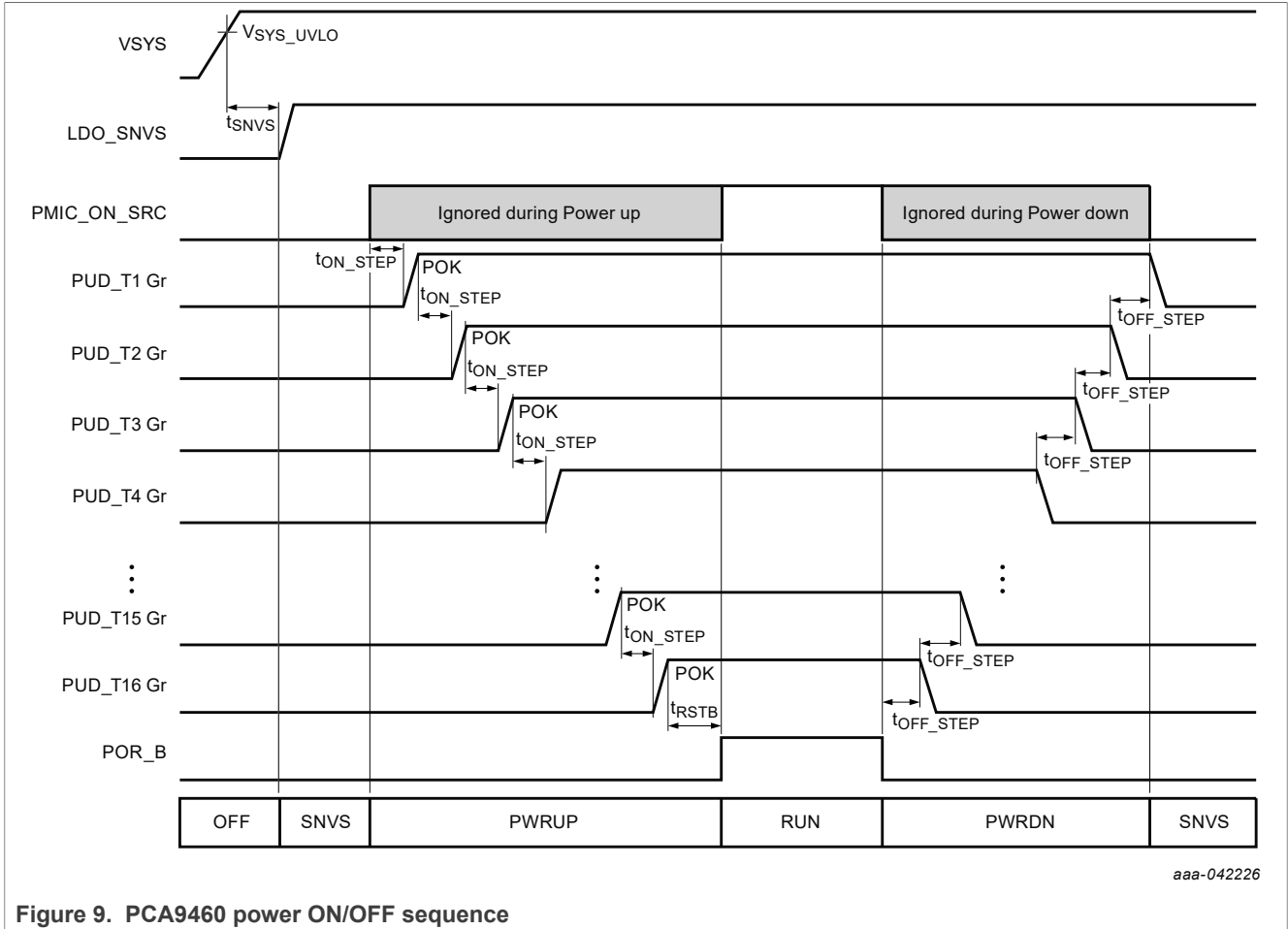


Figure 9. PCA9460 power ON/OFF sequence

Table 3. Power up sequence

Regulator	PCA9460A	PCA9460B	PCA9460C
BUCK1	T8, 1.8 V	T8, 1.8 V	T8, 1.8 V
BUCK2	T10, 1.0 V	T10, 1.0 V	T10, 1.0 V
BUCK3	T11, 1.0 V	T11, 1.0 V	T11, 1.0 V
BUCK4	T11, 1.1V	T11, 1.1V	T11, 1.2V
LDO1	T14, 1.1V	T14, 0.6V	T14, 1.2V
LDO2	T9, 3.3 V	T9, 3.3 V	T9, 3.3 V
LDO3	T12, 3.3 V	T12, 3.3 V	T12, 3.3 V
LDO4	T12, 1.8 V	T12, 1.8 V	T12, 1.8 V
LSW1	T13	T13	T13
LSW2	T10	T10	T10
LSW3	T15	T15	T15
LSW4	T9	T9	T9

**7.4.4 PWRDN state**

When PMIC\_ON\_SRC is asserted low in RUN state, PCA9460 enters PWRDN state, where it starts with pulling down POR\_B, and then turning off each power rail in t<sub>OFF\_STEP</sub> and is transitioned to SNVS state.

**7.4.5 RUN state**

PCA9460 enters RUN state after PWRUP state. If PMIC\_ON\_SRC is asserted low, PCA9460 is transitioned to PWRDN state. When Cold reset event is triggered in RUN state, it is transitioned to PWRDN state. Regulator fault or Thermal shutdown happens in this state, it is transitioned to FAULT\_SD state.

There are three kinds of modes in RUN state, ACTIVE, STANDBY and DPSTANDBY modes, depending on PMIC\_STBY\_REQ pin and STANDBY\_CFG bit in SYS\_CFG1 register.

Internal signals to change modes are generated as below.

1. PMIC\_STBY = PMIC\_STBY\_REQ pin when STANDBY\_CFG = 0b  
PMIC\_STBY is set high only when PMIC\_STBY\_REQ pin is high and STANDBY\_CFG bit is 0b.
2. PMIC\_DEEP\_STBY = PMIC\_STBY\_REQ pin when STANDBY\_CFG = 1b  
PMIC\_DEEP\_STBY is set high only when PMIC\_STBY\_REQ pin is high and STANDBY\_CFG bit is 1b.

Each regulator and load switch have enable configuration bits to turn on each mode.

00b = OFF

01b = ON at RUN State

10b = ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY

11b = ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

**7.4.5.1 ACTIVE mode**

When PCA9460 enters RUN state from PWRUP state, it enter ACTIVE mode at first. And then it transitions to STANDBY mode or DPSTANDBY mode depending on PMIC\_STBY or PMIC\_DEEP\_STBY signal.

**7.4.5.2 STANDBY mode**

PCA9460 is transitioned to STANDBY mode when PMIC\_STBY is high. PMIC\_STBY is determined by PMIC\_STBY\_REQ pin when STANDBY\_CFG bit in SYS\_CFG1 register is set to 0b. PCA9460 move to ACTIVE mode when PMIC\_STBY\_REQ pin is low. It transitioned to DPSTANDBY mode when STANDBY\_CFG bit is changed to 1b.

**7.4.5.3 DPSTANDBY mode**

PCA9460 is transitioned to DPSTANDBY ( Deep Standby) mode when PMIC\_DEEP\_STBY is high. PMIC\_DEEP\_STBY is determined by PMIC\_STBY\_REQ pin when STANDBY\_CFG bit in SYS\_CFG2 register is set to 1b. PCA9460 move to ACTIVE mode when PMIC\_STBY\_REQ pin is low. It transitioned to STANDBY mode when STANDBY\_CFG bit is changed to 0b.

**Table 4. States Summary**

State	Mode	VSYS	PMIC_ON_SRC	STANDBY_CFG bit	PMIC_STBY_REQ
OFF	—	VSYS < V <sub>SYS_UVLO</sub>	X	X	X
SNVS	—	VSYS > V <sub>SYS_UVLO</sub>	Low	X	X
RUN	ACTIVE	VSYS > V <sub>SYS_UVLO</sub>	High	X	Low

Table 4. States Summary...continued

State	Mode	VSYS	PMIC_ON_SRC	STANDBY_CFG bit	PMIC_STBY_REQ
RUN	STANDBY	$V_{SYS} > V_{SYS\_UVLO}$	High	0b	High
RUN	DPSTANDBY	$V_{SYS} > V_{SYS\_UVLO}$	High	1b	High

X : Don't care

7.4.6 FAULT\_SD state

PCA9460 has two Fault shutdown sources.

1. Thermal shutdown: Transition to SNVS state after FAULT\_SD state

When junction temperature reaches  $T_{J\_SHDN}$ , it enters FAULT\_SD state after  $t_{FLT\_THSD}$ , where all regulators are turned off immediately after pulling down POR\_B. It stays at FAULT\_SD until junction temperature falls below  $T_{J\_SHDN}$ . When the temperature drops below  $T_{J\_SHDN}$ , then it transitions to SNVS state.

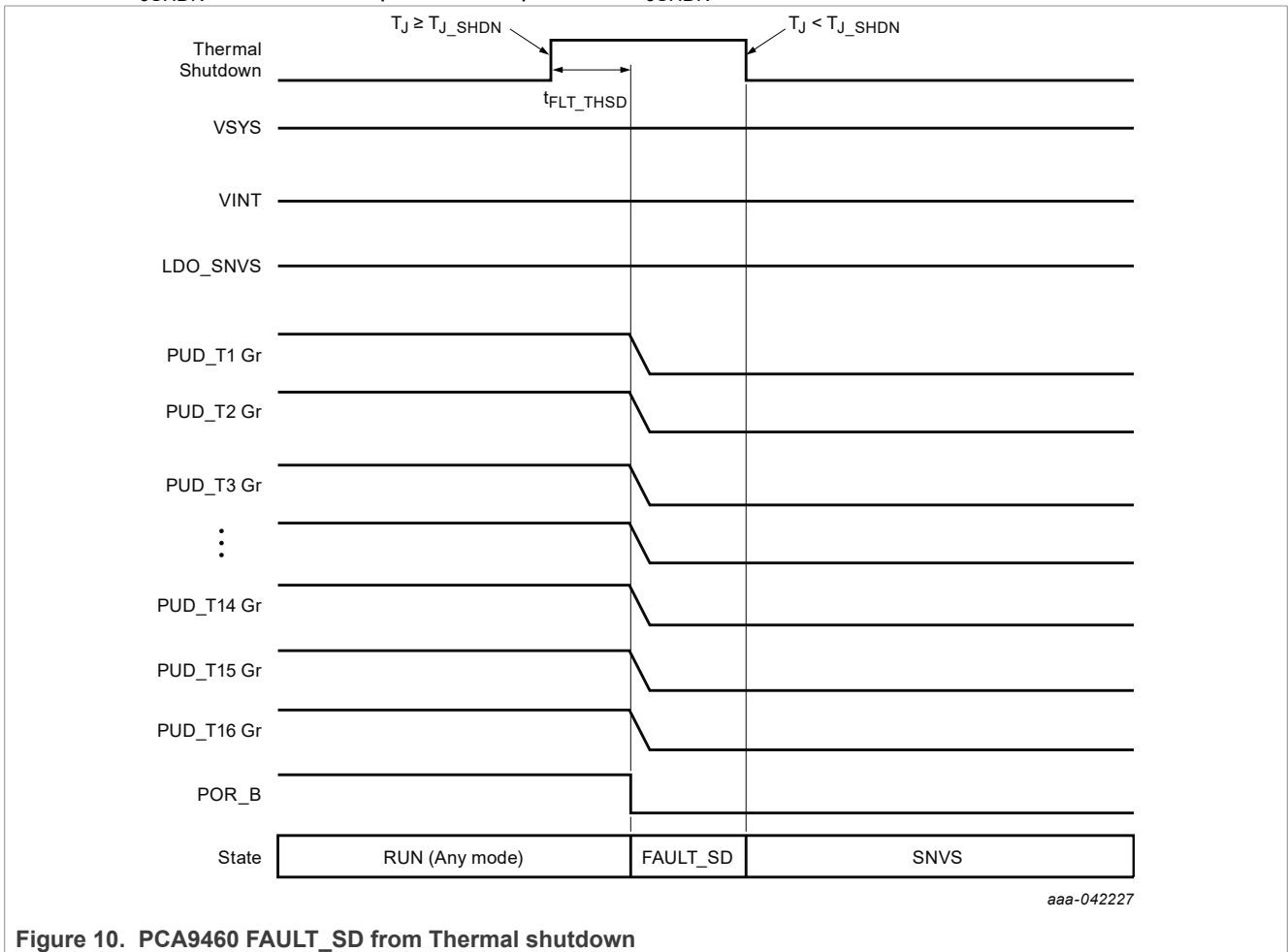


Figure 10. PCA9460 FAULT\_SD from Thermal shutdown

Table 5.

Time	Description	Value	Comment
$t_{FLT\_THSD}$	Time to reset released from Fault event	20 $\mu$ s	

2. Voltage regulator fault in RUN state: Transition to FAULT\_SD state in  $t_{FLT\_SD\_WAIT}$  after Fault is detected and then transition to SNVS state in  $t_{FLT\_SD\_STAY}$

VR Fault status bit in INT1\_STATUS register is latched to "1" when corresponding regulator voltage falls below POK threshold for  $t_{DEB\_POKB}$ .

If the fault status bit is masked in VRFLT1\_MASK register, PCA9460 doesn't enter FAULT\_SD state, instead, PCA9460 stays at RUN state. If the fault register bit is unmasked, it starts  $t_{FLT\_SD\_WAIT}$  timer. Application processor can determine to enter FAULT\_SD state by masking the VR Fault status bit in VRFLT1\_MASK registers before the timer expires. PCA9460 enter FAULT\_SD state when the timer is expired. PCA9460 stays at FAULT\_SD state for  $t_{FLT\_SD\_STAY}$  and moves to SNVS state from FAULT\_SD mode after  $t_{FLT\_SD\_STAY}$ .

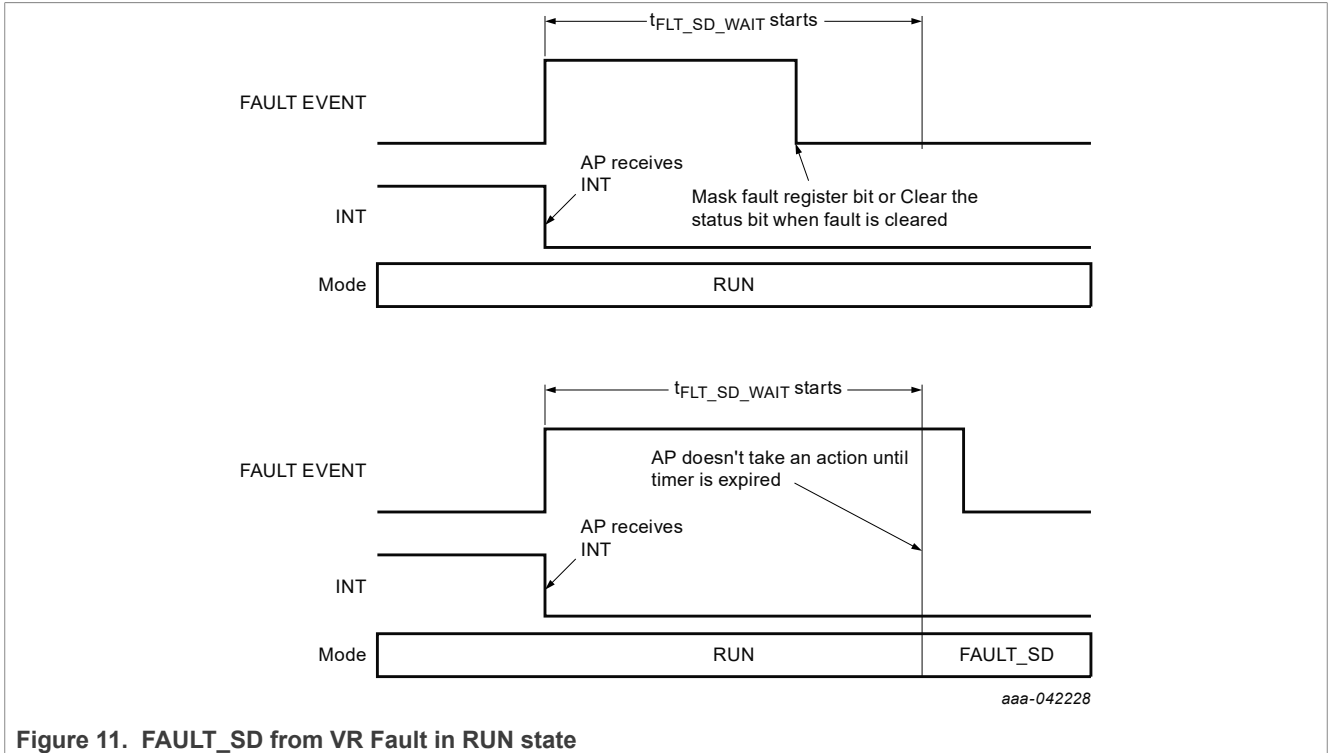


Figure 11. FAULT\_SD from VR Fault in RUN state

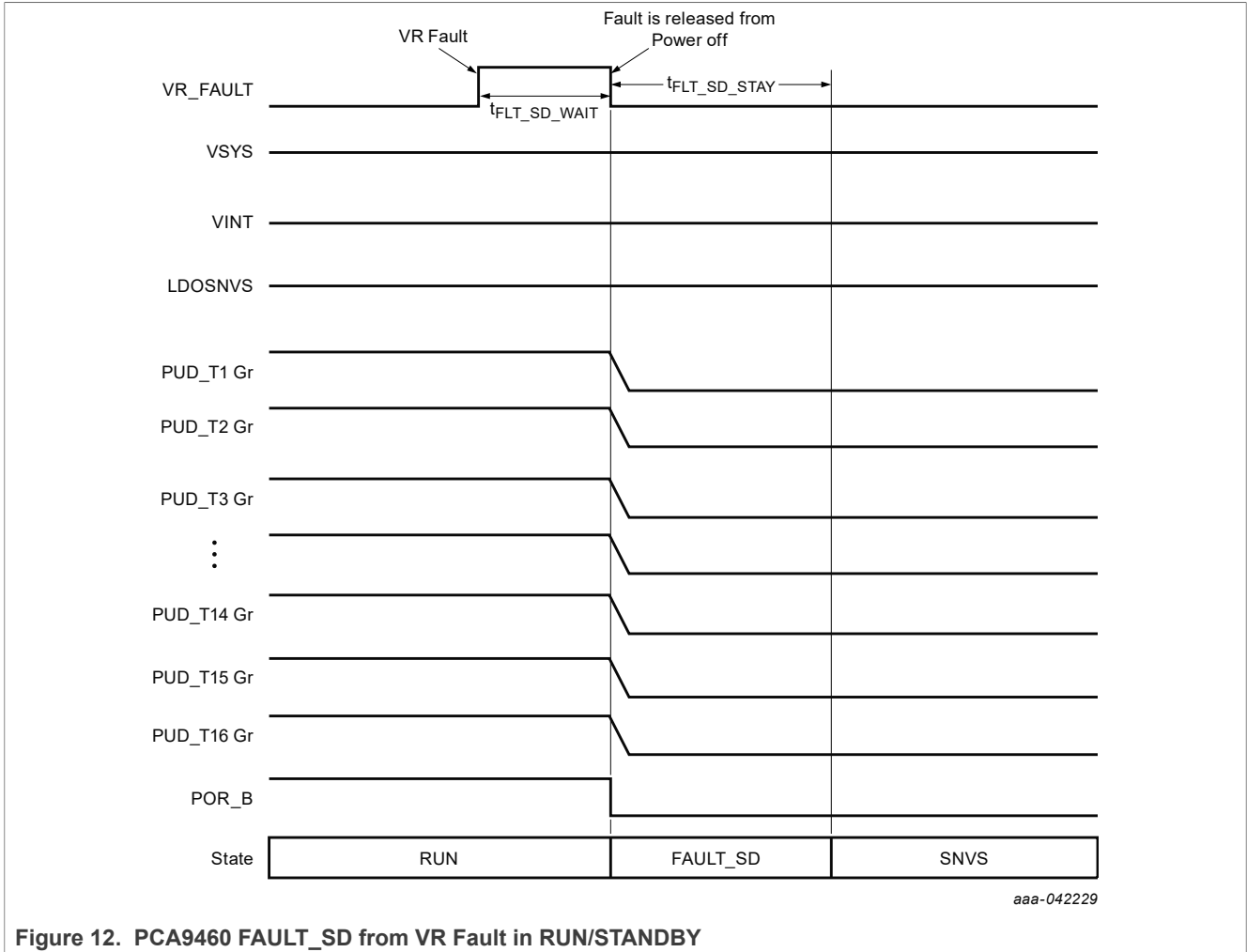


Figure 12. PCA9460 FAULT\_SD from VR Fault in RUN/STANDBY

Table 6. FAULT\_SD description

Time	Description	Value	Comment
t <sub>FLT_SD_WAIT</sub>	VR Fault wait time to enter fault shutdown	100 ms	20 μs, 100 ms option
t <sub>FLT_SD_STAY</sub>	Time to stay at Fault_SD state	100 ms	

### 7.5 PMIC reset

The PCA9460 PMIC has three reset inputs, WDOG\_B pin, PMIC\_RST\_B pin and I<sup>2</sup>C reset bit, The reset is executed only at RUN state.

The reset behavior is configured in 0x08 RESET\_CTRL register for WDOG\_B pin and PMIC\_RST\_B pin. I<sup>2</sup>C reset behavior is configured in 0x09 SW\_RST register.



Table 7. PMIC Reset description

0x08 – RESET_CTRL				Reset Type	S
Bit	Name	Type	Reset	Description	
7 to 6	WDOG_B_CFG	R/W	00	When WDOG_B is asserted to L, PMIC behavior <b>00b = WDOG_B reset is disabled</b> 01b = Warm Reset, POR_B pin is asserted low for $t_{RSTB}$ 10b, 11b = Cold Reset, All voltage regulators are recycled	
5 to 4	PMIC_RST_CFG	R/W	10	When PMIC_RST_B is asserted to L, PMIC behavior 00b = PMIC_RST_B reset is disabled 01b = Warm Reset, POR_B pin is asserted low for $t_{RSTB}$ <b>10b, 11b = Cold Reset, All voltage regulators are recycled</b>	
0x09 – SW_RST				Reset Type	O
Bit	Name	Type	Reset	Description	
7 to 0	SW_RST_KEY	R/W	0x00	Software reset register. This register is read back to "0x00" right after writing the value. <b>0x00 = No action</b> 0x05 = Reset O-type registers to default value 0x09 = Reset O-type registers and S-type registers 0x14 = Cold reset (Power recycle all regulators ) 0x35 = Warm Reset (Toggle POR_B for $t_{RSTB}$ ) 0xEE = PMIC digital reset ( Debug purpose only ) Others = Forbidden	

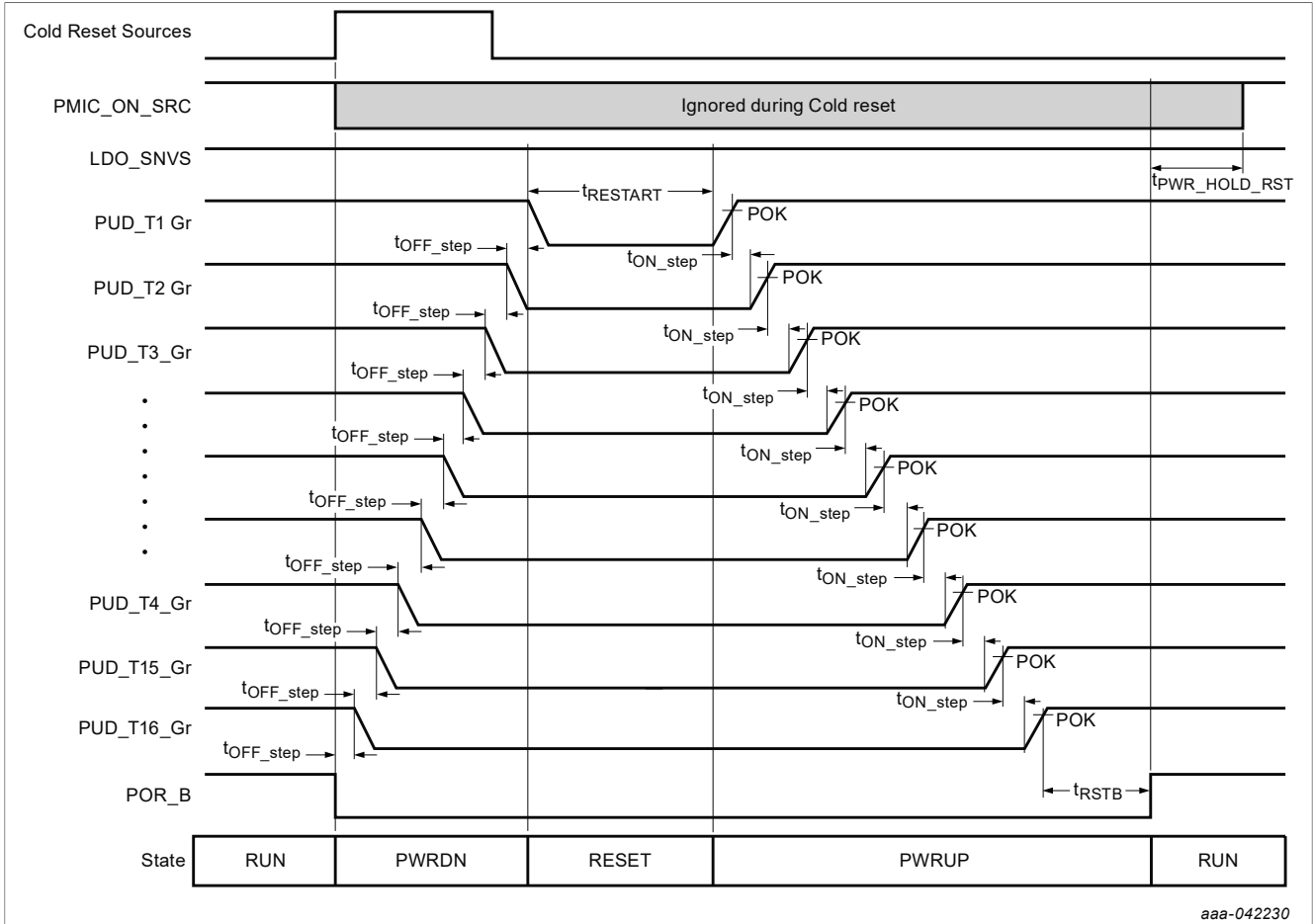
WDOG\_B is asserted low, PCA9460 gets reset depending on WDOG\_B\_CFG bit configuration. When the bits are set to 2b00, the reset by WDOG\_B pin is disabled. If the bits are set to 2b01, warm reset is performed, where pulling POR\_B low for  $t_{RESET}$  and reset I<sup>2</sup>C O type registers to default value keeping power rails remaining ON. After reset, WDOG\_B pin must be released high to get another reset from WDOG\_B falling edge.

When PMIC\_RST\_B is asserted low and it stays low for RESETKEY timer configured in SYS\_CFG1 register, PCA9460 waits for  $t_{RESET\_WAIT}$  after issuing RESETKEY interrupt. If application processor doesn't disable reset by writing 00b in PMIC\_RST\_CFG bits, then PCA9460 gets reset depending on PMIC\_RST\_CFG bits configuration. When the bits are set to 2b00, any reset by PMIC\_RST\_B pin is disabled. If the bits are set to 2b01, warm reset is performed, in which pulling POR\_B low for  $t_{RESET}$  and reset I<sup>2</sup>C O type registers to default value keeping power rails remaining ON. After reset, PMIC\_RST\_B pin must be released high to get another reset from PMIC\_RST\_B falling edge.

Cold reset event is generated by either of I<sup>2</sup>C reset, WDOG\_B falling edge or PMIC\_RST\_B falling edge after debounce time. Once it is detected, POR\_B is pulled low and takes power down sequence. PCA9460 stays at RESET for  $t_{RESTART}$  and then start power on sequence even though WDOG\_B pin is still low.

Figure 13 shows cold reset behavior. From any cold reset signal from either of PMIC\_RST\_B, WDOG\_B or I<sup>2</sup>C, it starts with power down sequence and stays off for  $t_{RESTART}$ . It automatically proceed power ON sequence and then enters RUN state. PMIC\_ON\_SRC is ignored for  $t_{PWR\_HOLD\_RST}$  after entering RUN state. If PMIC\_ON\_SRC doesn't come up until  $t_{PWR\_HOLD\_RST}$  is expired, then PCA9460 is turned off.

13-channel power management integrated circuit (PMIC) for ultra-low power applications



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Figure 13. PCA9460 Cold reset

Table 8. PCA9460 Cold reset description

Time	Description	Value	Comment
tRESTART	Time to power ON seq from end of power OFF seq during cold reset	250 ms	
tPWR_HOLD_RST	Time to hold power-on after reset	100 ms	

Figure 14 shows warm reset behavior. From any warm reset signal from either of PMIC\_RST\_B, WDOG\_B or I<sup>2</sup>C, it makes POR\_B toggled for tRESET and all O type registers get reset. PMIC\_ON\_SRC is ignored for tPWR\_HOLD\_RST after entering RUN state as like cold reset behavior.

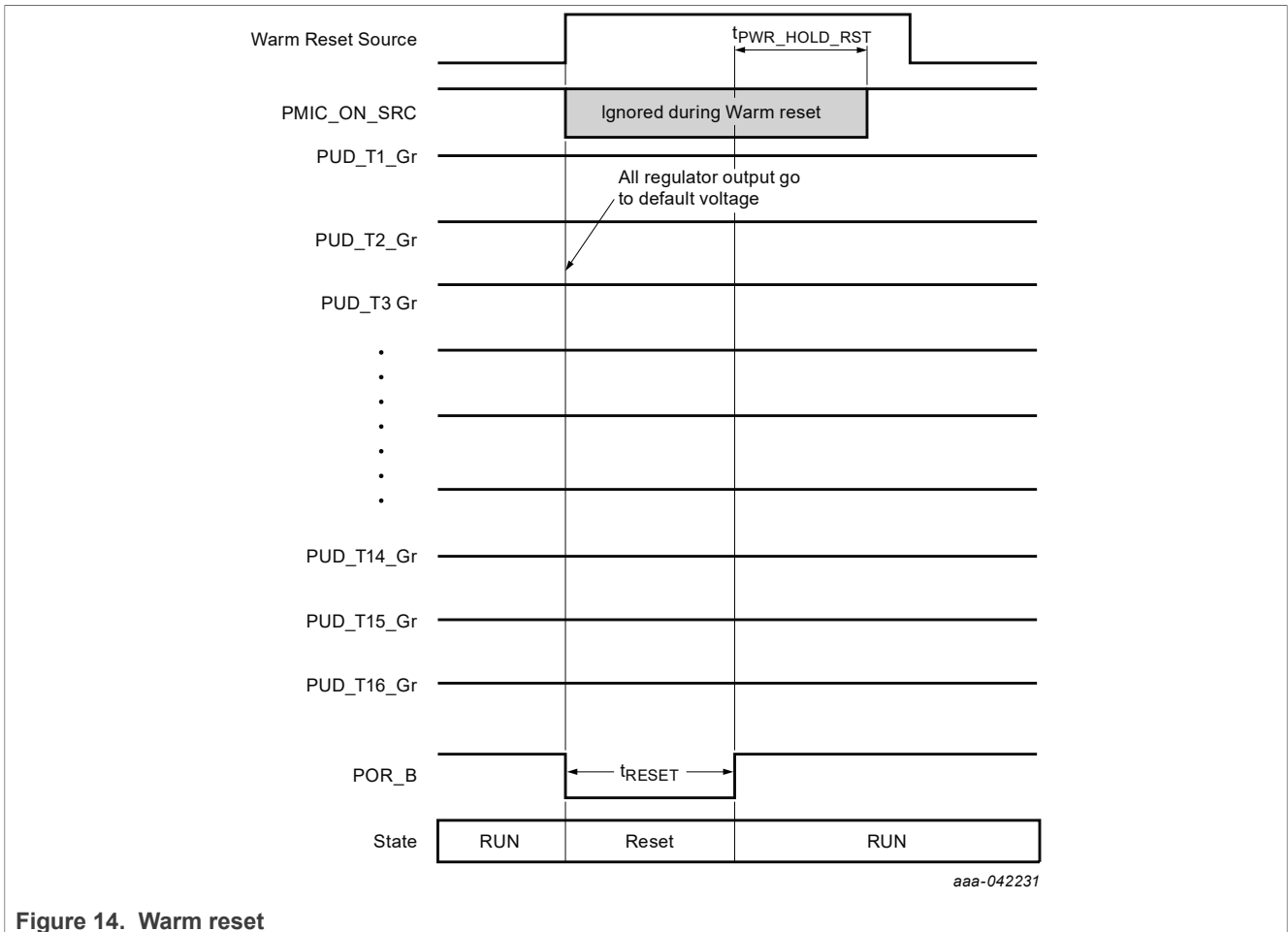


Figure 14. Warm reset

Table 9. Warm reset description

Time	Description	Value	Comment
$t_{RESET}$	POR_B low time at Warm reset	20 ms	

## 7.6 Regulator summary

The PCA9460 PMIC features four high efficiency low quiescent current buck regulators, four LDO regulators and low iq SNVS LDO to supply voltages for the application processor and peripheral devices.

### 7.6.1 BUCK regulator

The PCA9460 has four high-efficiency low Iq buck regulators. Each buck regulator features soft start and over-current protection. Buck regulator operates in two modes, PFM and PWM mode. Each buck regulator operates in PFM(Pulse Frequency Modulation) mode at light load that generates a single switching pulse to ramp up the inductor current and recharge the output capacitor, followed by a sleep period where most of the internal circuits are shutdown to achieve lowest operating quiescent current. During this time, the load current is supported by the output capacitor. The duration of the sleep period depends on the load current and the inductor peak current.

In PFM Mode, the switching frequency varies linearly with the load current. At medium and high load conditions, the device enters automatically PWM (Pulse Width Modulation) mode and operates in continuous conduction

mode with a nominal switch frequency  $f_{sw}$  of typically 2 MHz. The boundary between PWM and PFM mode is when the inductor current becomes discontinuous.

When the Bx\_FPWM bits (Bit 2) on the BUCKxCTRL registers are set to 1, the buck regulator operates in only PWM mode, regardless of load current.

Internal active discharge resistor is installed in each buck regulator output to discharge voltage on output capacitors when regulator is off. It is configurable through the I<sup>2</sup>C register using Bx\_AD bit (Bit 3) on BUCKxCTRL registers.

[Table 10](#) shows buck regulator summary.

**Table 10. PCA9460 Buck Summary**

Buck#	Input pin	Default VOUT [V]	VOUT range [V]	Step size [mV]	Default ON/OFF	Current rating [mA]
BUCK1	INB14	1.8	0.6 to 3.4	25	ON	1000
BUCK2	INB23	1.0	0.6 to 2.1875	12.5	ON	1000
BUCK3	INB23	1.0	0.6 to 2.1875	12.5	ON	1000
BUCK4	INB14	[1]	0.6 to 3.4	25	ON	1000

[1] PCA9460A and PCA9450B: 1.1 V, PCA9460C: 1.2 V

BUCK1 and BUCK4 output voltages are programmable from 0.60 V to 3.40 V in 25 mV steps. This is done by setting the B1\_OUT[6:0], and B4\_OUT[6:0] bits on registers BUCK1OUT and BUCK4OUT respectively. [Table 108](#) shows the output voltage coding for these regulators.

BUCK2 and BUCK3 output voltages are programmable from 0.60 V to 2.1875 V in 12.5 mV steps. Setting Bx\_DVS\_CTRL bits to 00b, DVS is controlled by Bx\_DVS0[6:0] bits on BUCKxOUT\_DVS0 register through I<sup>2</sup>C. [Table 107](#) shows the output voltage coding for these regulators.

### 7.6.1.1 ON/OFF control

Each buck regulator can be turned ON/OFF through I<sup>2</sup>C or PMIC\_STBY\_REQ pin, which can be configured in each Bx\_ENMODE bits in BUCKxCTRL register.

- BxENMODE = 00b : the buck regulator is forcedly OFF
- BxENMODE = 01b : the buck regulator is ON in RUN state ( ACTIVE / STANDBY / DPSTANDBY mode )
- BxENMODE = 10b : the buck regulator is ON in ACTIVE or STANDBY mode and it is OFF in DPSTANDBY mode
- BxENMODE = 11b : the buck regulator is ON in ACTIVE mode and it is OFF in STANDBY or DPSTANDBY mode

### 7.6.1.2 Dynamic voltage scaling

BUCK2 and BUCK3 support dynamic voltage scaling (DVS) through MODE[2:0] pins or PMIC\_STBY\_REQ pin depending on Bx\_DVS\_CTRL bits in BUCK23\_DVS\_CFG2 register.

**Table 11. 0x13 – BUCK23\_DVS\_CFG2**

Reset Type: 0

Bit	Name	Type	Reset	Description
7 to 6	B2_DVS_CTRL	R/W	00	BUCK2 DVS Control <b>00b = DVS control BUCK2OUT_DVS0 Reg through I<sup>2</sup>C</b> 01b = DVS control through PMIC_STBY_REQ pin

Table 11. 0x13 – BUCK23\_DVS\_CFG2...continued

Reset Type: 0

Bit	Name	Type	Reset	Description
				10b = DVS control through MODE[2:0] pins in ACTIVE mode and the voltage set to BUCK2OUT_STBY when PMIC_STBY_REQ = H 11b = DVS control through MODE[2:0] pins in RUN state
5 to 4	B3_DVS_CTRL	R/W	00	BUCK3 DVS Control <b>00b = DVS control BUCK3OUT_DVS0 Reg through I<sup>2</sup>C</b> 01b = DVS control through PMIC_STBY_REQ pin 10b = DVS control through MODE[2:0] pins in ACTIVE mode and the voltage set to BUCK3OUT_STBY when PMIC_STBY_REQ = H 11b = DVS control through MODE[2:0] pins in RUN state
3 to 0	RSVD	R/W	0000	Reserved

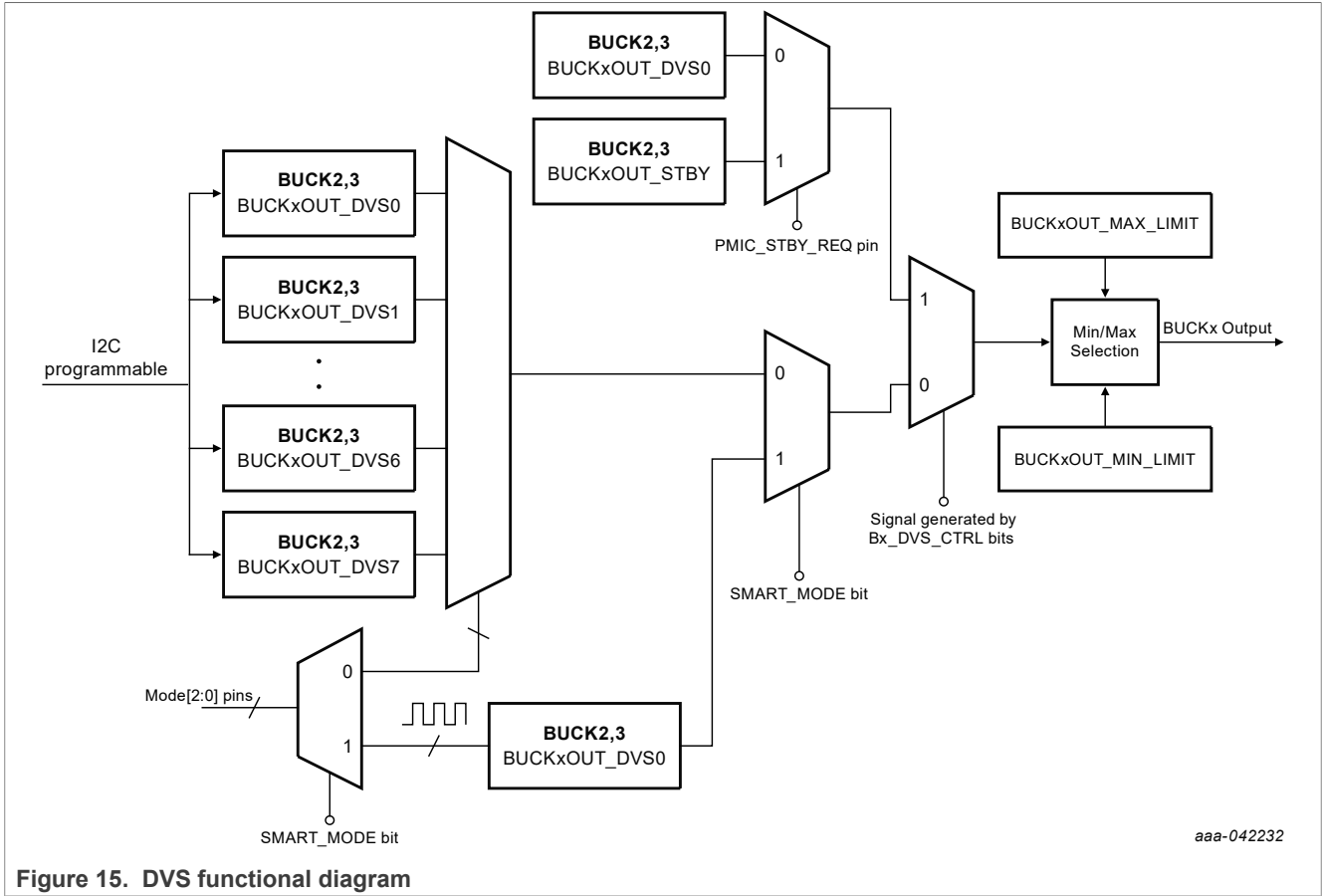
When Bx\_DVS\_CTRL bits are set to 00b, DVS is controlled by Bx\_DVS0 bits on the BUCKxOUT\_DVS0 register through I<sup>2</sup>C. If BUCKxOUT\_DVS0 register is overwritten with different voltage through I<sup>2</sup>C, the output voltage is changed accordingly without ramping up/down.

When the Bx\_DVS\_CTRL bits are set to 01b, the buck regulator output voltage is determined by BUCKxOUT\_DVS0 and BUCKxOUT\_STBY registers through PMIC\_STBY\_REQ pin.

When the bits are set to 10b, the output voltage is controlled by MODE[2:0] pins in ACTIVE mode ( PMIC\_STBY\_REQ pin = L) and the voltage is set to BUCKxOUT\_STBY register in STANDBY mode or DPSTANDBY mode ( PMIC\_STBY\_REQ pin = H), where MODE[2:0] pins should not be changed.

When the bits are set to 11b, the buck voltage is always controlled by MODE[2:0] pins.

[Figure 15](#) shows DVS function block diagram and [Table 12](#) show how buck voltage is determined by MODE[2:0] pins.



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Figure 15. DVS functional diagram

Table 12. MODE[2:0] pins configuration

I <sup>2</sup> C bits		PMIC MODE pins			Buck output voltage
SMART_MODE	MODE2_EN	MODE2	MODE1	MODE0	
0	X	0	0	0	BUCKxOUT_DVS0
0	X	0	0	1	BUCKxOUT_DVS1
0	X	0	1	0	BUCKxOUT_DVS2
0	X	0	1	1	BUCKxOUT_DVS3
0	X	1	0	0	BUCKxOUT_DVS4
0	X	1	0	1	BUCKxOUT_DVS5
0	X	1	1	0	BUCKxOUT_DVS6
0	X	1	1	1	BUCKxOUT_DVS7
1	0	X	0	0	No voltage Change
1	0	X	0	1	Decrement by Bx_DVS_DN mV, select BUCK through BUCK_SEL bit
1	0	X	1	0	Increment by Bx_DVS_UP mV, select BUCK through BUCK_SEL bit
1	0	X	1	1	No voltage Change
1	1	0	0	0	No voltage Change

Table 12. MODE[2:0] pins configuration...continued

I <sup>2</sup> C bits		PMIC MODE pins			Buck output voltage
SMART_MODE	MODE2_EN	MODE2	MODE1	MODE0	
1	1	0	0	1	Decrement BUCK2 by Bx_DVS_DN mV
1	1	0	1	0	Increment BUCK2 by Bx_DVS_UP mV
1	1	0	1	1	No voltage Change
1	1	1	0	0	No voltage Change
1	1	1	0	1	Decrement BUCK3 by Bx_DVS_DN mV
1	1	1	1	0	Increment BUCK3 by Bx_DVS_UP mV
1	1	1	1	1	No voltage Change

When SMART\_MODE bit in BUCK23\_DVS\_CFG1 register is set to 0b, MODE[2:0] pins are used to select buck DVS output voltage configuration, BUCKxOUT\_DVSx registers, which should be pre-configured by application processor. PCA9460 detects the first level change among MODE[2:0] pins, 3 internal clock later, the output voltage is updated. The maximum latency of these MODE pins is specified to t<sub>MAX\_DIFF</sub>.

Figure 16 shows DVS operation through MODE[2:0] pins when SMART\_MODE bit is set to 0b.

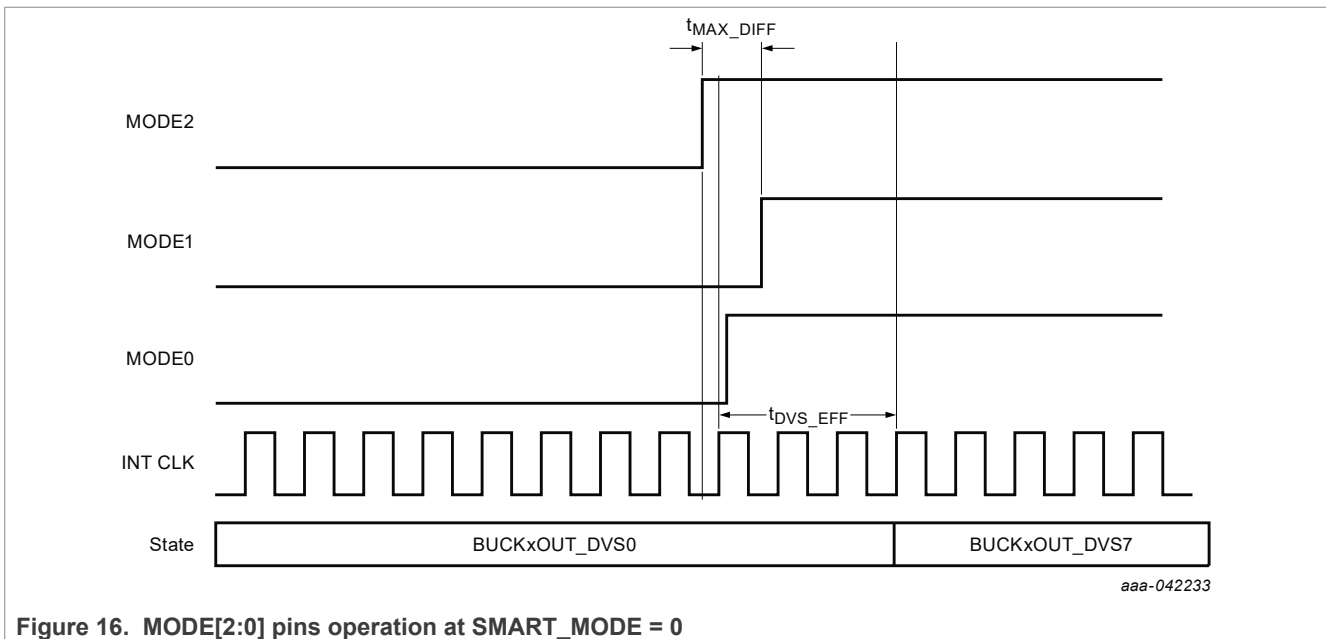


Figure 16. MODE[2:0] pins operation at SMART\_MODE = 0

When SMART\_MODE is set to 1b and MODE2\_EN bit is set to "0", MODE2 pin is ignored in DVS function, MODE1 pin is used to increase buck regulator as much as Bx\_DVS\_UP bit by issuing one pulse. And MODE0 pin is used to decrease buck regulator as much as Bx\_DVS\_DN bit by issuing one pulse. The pulse width is controlled through MODE\_PULSE bit (bit 3) of the BUCK23\_DVS\_CFG1 register. Buck regulator should be selected through BUCK\_SEL bit in this mode. Whenever the voltage is updated through MODE pin, the voltage is updated in BUCKxOUT\_DVS0 register so as application processor can check the current output voltage setting. When both pin has same logic level, then the buck voltage is not changed.

When SMART\_MODE is set to 1b and MODE2\_EN bit is set to 1b, MODE2 pin is used to select BUCK regulator to be increased or decreased through MODE1 and MODE0 pins.

Figure 17 shows DVS operation through MODE[2:0] pins when SMART\_MODE bit is set to 1b.

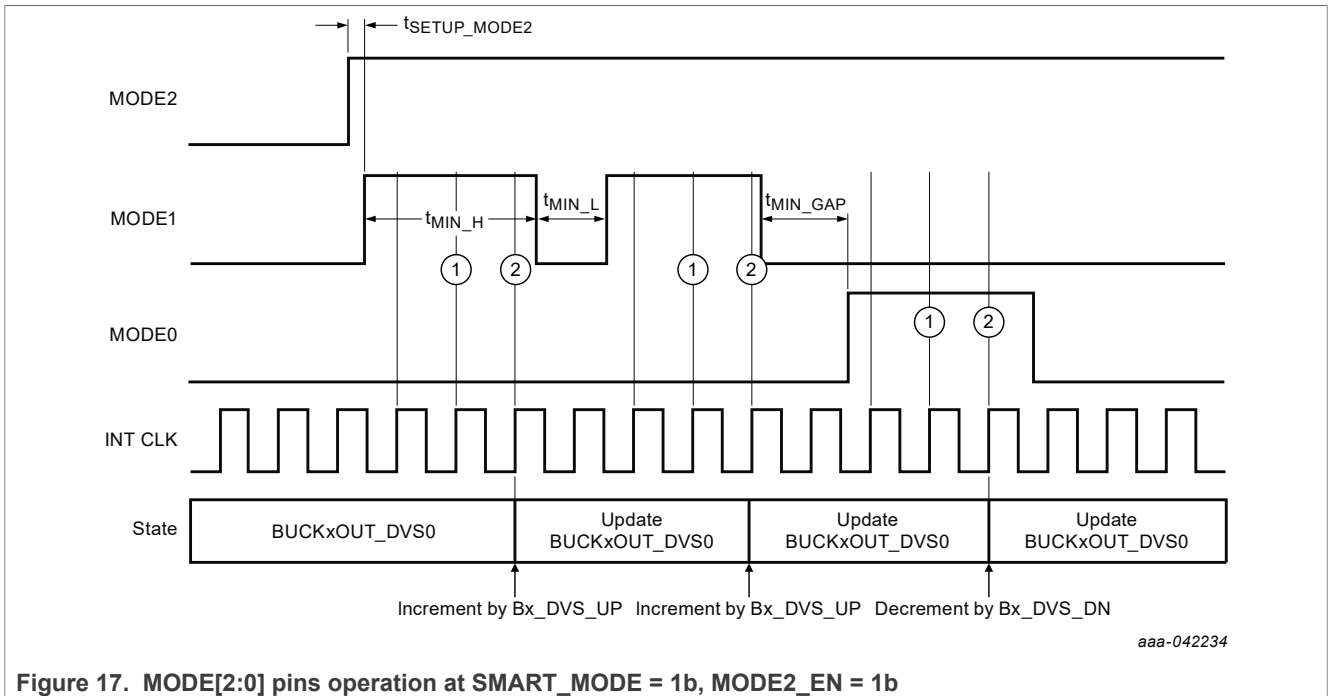


Figure 17. MODE[2:0] pins operation at SMART\_MODE = 1b, MODE2\_EN = 1b

MODE pins control requirements in SMART\_MODE = 1b are:

1. MODE2 pin should be set within  $t_{SETUP\_MODE2}$  before MODE1 or MODE0 pin is toggled
2. High Pulse hold time should be longer than  $t_{MIN\_H}$
3. Low pulse hold time should be longer than  $t_{MIN\_L}$
4. When MODE1 pin is toggled after MODE0 pin toggled and vice versa, it should be longer than  $t_{MIN\_GAP}$ .
5. Once detecting high pulse, the voltage is updated in BUCKxOUT\_DVS0 register after two internal clocks.
6. Either MODE1 or MODE0 pin stay high, the buck regulator voltage is updated only once after two clocks.

The programmable voltage ramp-up and ramp-down are applied during the DVS voltage transition. The ramp rate is configured by Bx\_RAMP[7:6] bits in each BUCKxCTRL registers.

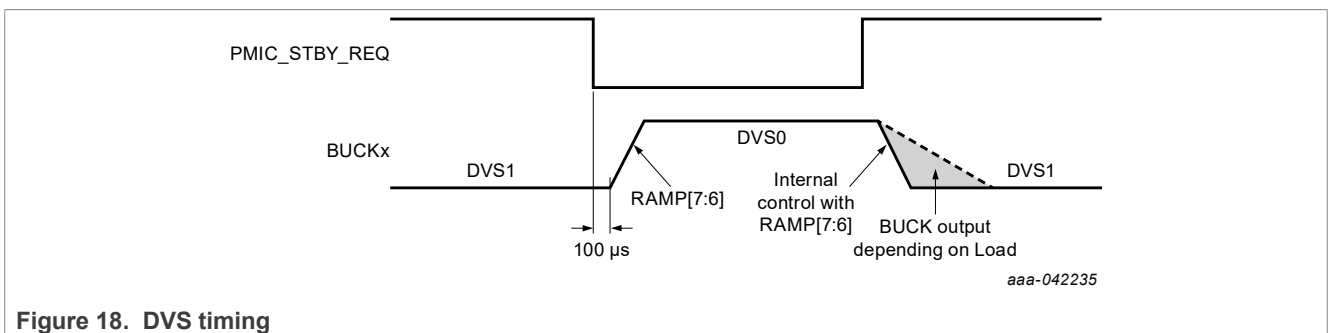
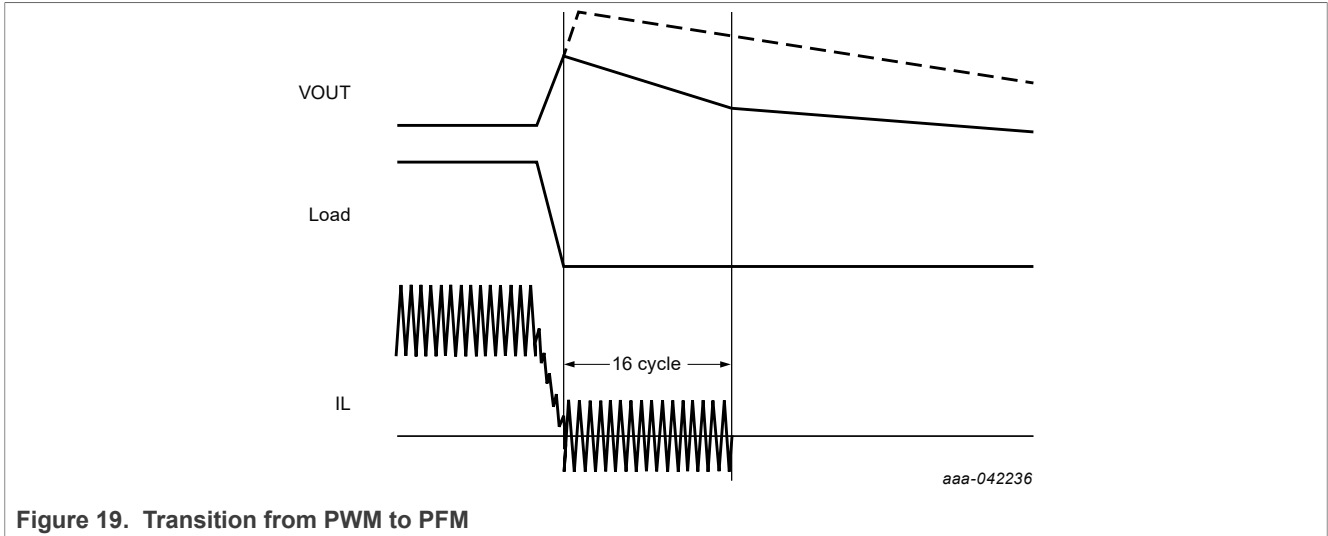


Figure 18. DVS timing

### 7.6.1.3 Overshoot improvement from PWM to PFM mode transient

The load transient response in PWM mode is improved compared to PFM mode, since the converter reacts faster on the load step and actively sinks energy on the load release. PCA9460 Buck regulator automatically enters PWM mode for 16 cycles after a heavy load release in order to bring the output voltage back to the regulation level faster. After 16 cycles of PWM mode, it automatically returns to PFM mode.





7.6.1.4 Low power mode

If BUCK is configured in low power mode, it turns internal circuitry off to minimize quiescent current. The current is limited to IOUT\_Max in Low Power Mode. BUCK2 and BUCK3 DVS feature also disabled in this mode. Therefore, low power mode should be used carefully not to exceed IOUT\_Max current.

Each buck regulator has low power mode configuration bits in BUCKx\_CTRL register.

Table 13. Low power mode

BUCK_CTRL				Reset Type	O
Bit	Name	Type	Reset	Description	
5 to 4	Bx_LPMODE	R/W	11	BUCK power mode 00b = Automatic transition mode 01b = Low power mode at STANDBY mode and DPSTANDBY mode 10b = Low power mode at DPSTANDBY mode <b>11b = Normal mode</b>	

If Bx\_LPMODE bits are set to 00b, the buck regulator runs automatic transition mode between low power mode and normal mode depending on load current. When it is set to 01b, buck operates in normal mode at ACTIVE mode and in low power mode at STANDBY mode and DPSTANDBY mode. If it is set to 10b, the buck is in low power mode only at DPSTANDBY mode.

7.6.1.5 BUCK output limiting

Application processor may accidentally write higher voltage than absolute maximum voltage rating of its power input, it may cause significant damage on application processor. PCA9460 has registers to limit the maximum voltage to prevent such an incident.

BUCK2 and BUCK3 maximum / minimum output are limited by BUCKxOUT\_MAX\_LIMIT and BUCKxOUT\_MIN\_LIMIT registers, respectively. Even if Buck output is configured to higher than the limit voltage configured in BUCKxOUT\_MAX\_LIMIT registers or lower than the min limit voltage configured in BUCKxOUT\_MIN\_LIMIT registers, the actual buck output is clamped to the limiting voltage set by BUCKxOUT\_MAX\_LIMIT or BUCKxOUT\_MIN\_LIMIT registers.

### 7.6.2 LDO

The PCA9460 has five low quiescent LDOs. LDO\_SVNS is supposed to supply SNVS core in application processor. This LDO features ultra-low quiescent current, 0.25  $\mu$ A typical, since it is always ON when VSYS is valid. Each LDO is fully controlled through its respective LDOxCFG and LDOx\_OUT registers. LDOxCFG registers enable the user to individually set the LDO configuration and enable and set the operational mode on each regulator using Lx\_ENMODE bits [1:0]. While LDOx\_OUT registers enable the user to individually set the output voltage according to [Table 113](#) for LDO1; [Table 118](#) for LDO2; [Table 125](#) for LDO3; and [Table 130](#) for LDO4.

Users can set LDO1 into Low Power Mode by setting the L1\_LPMODE [1:0] bits on LDO1\_CFG register (0x30).

The internal active discharge resistor is installed in each LDO regulator output to discharge voltage on output capacitors when the regulator is off. It is configurable through I<sup>2</sup>C register using the following:

- L1\_AD bit (bit 7) on LDO1\_OUT (0x31)
- Lx\_AD bit (bit 4) on LDO2\_CFG (0x32), LDO3\_CFG (0x35), and LDO4\_CFG (0x37)

Table 14. LDO summary (PCA9460A)

LDO#	Input pin	Default VOUT (V)	VOUT range (V)	Step size (mV)	Default ON/OFF	Current rating (mA)
LDO1	INL1	[1]	0.6 to 1.95	50	ON	250
LDO2	INL	3.3	0.8 to 3.3	50	ON	250
LDO3	INL	3.3	0.8 to 3.3	50	ON	250
LDO4	INL	1.8	0.8 to 3.3	50	ON	250
LDO_SVNS	VSYS	3.0	0.8 to 3.3	50	ON	10

[1] PCA9460A: 1.1 V, PCA9460B:0.6 V, PCA9460C: 1.2 V

The LDOSNVNS regulator is fully controlled through the LDOSNVNS\_CFG register. Users can enable/disable the internal active discharge resistor using LSNVS\_AD bit (Bit 7); enable/disable the regulator using LS\_ENMODE bit (bit 6); and use the L\_SNVNS\_OUT bits [5:0] to set the output voltage according to [Table 133](#).

### 7.6.3 Regulator protection

Each regulator output voltage configuration register is protected by lock key. Unlock key must be written with 01011100 (0x5C) to UNLOCK\_KEY [7:0] bits in REG\_LOCK (0x4E) register before updating the registers. Below are protected registers.

1. BUCK output configuration registers : BUCK1OUT, BUCK4OUT
2. BUCK2, 3 Min/Max output configuration registers : BUCK2OUT\_MAX\_LIMIT, BUCK2OUT\_MIN\_LIMIT, BUCK3OUT\_MAX\_LIMIT, BUCK3OUT\_MIN\_LIMIT.
3. LDO output configuration registers : LDO1\_OUT, LDO2\_OUT\_L, LDO2\_OUT\_H, LDO3\_OUT, LDO4\_OUT

### 7.6.4 Current limit protection

In case a regulator exceeds the current limit (ILIM parameter for the BUCK regulators or ILIMIT for the linear regulators) of each target, the output of the regulator will fall below POK (Output Power good) threshold caused by overcurrent limit, then VRFLT1\_INT register will generate an interrupt and system transitions to Fault\_SD state. Please refer to “Voltage regulator fault in RUN state” fault source in [Section 7.4.6 "FAULT\\_SD state"](#) for details.

7.7 Load switch and LED driver

PCA9460 integrates four 150mΩ PMOS switch configurable to Load switch or LED driver through I<sup>2</sup>C.

When an LSWx\_CFG bit in LSW\_CFG register is set to 0b, the LSW is configured as Load switch. It is controlled by each LSWx\_EN bits in LSW\_EN\_CTRL register, which provides ON/OFF control automatically in different modes. When it is enabled, it soft-starts to reduce inrush current.

Table 15. Load SW Enable table

LSWx_EN	SNVS State	RUN state		
		Active Mode	STANDBY	DPSTANDBY
00	OFF	OFF	OFF	OFF
01	OFF	ON	ON	ON
10	OFF	ON	ON	OFF
11	OFF	ON	OFF	OFF

When an LSWx\_CFG bit is set to 1b, the LSW is configured as LED driver, and its behavior is determined by LEDx\_CFG registers including enable mode and brightness configuration.

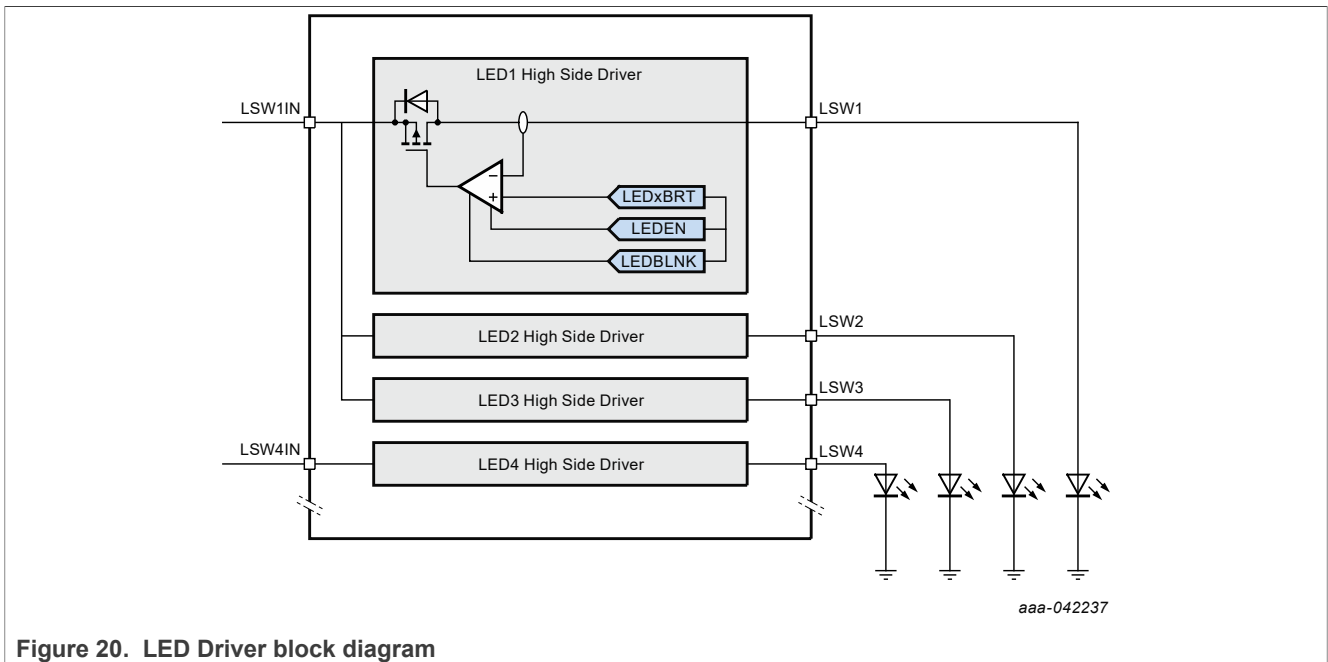


Figure 20. LED Driver block diagram

Each LED channel can be assigned to one of constant ON, blinking pattern 1 and blinking pattern 2. Constant ON is to turn ON LED with configured LED brightness until it is forcedly off though I<sup>2</sup>C.

PCA9460 supports two independent blink patterns which is generated by each LEDRAMP register and LEDBLNK register. The Blink pattern always start with OFF time, and then ramp up to I<sub>LED\_BRT</sub> by increasing PWM duty cycle from 0 % to 100 % configured in LEDRAMP register. The ramp up time is determined by PWM duty step size(Px\_UP\_STEP) and delay time(Px\_UP\_DLY). Once the current reach the target, the LED channel stays for T<sub>ON</sub>. a blink pattern ends up with Ramping down by decreasing PWM duty cycle from 100 % to 0 % configured in LEDRAMP register. The ramp down time is determined by PWM duty step size(Px\_DN\_STEP) and delay time(Px\_DN\_DLY). This pattern is repeated until any LED channel doesn't select the pattern any longer. Update on the pattern like brightness change or ON/OFF time change during a BLINK mode takes place in next period.

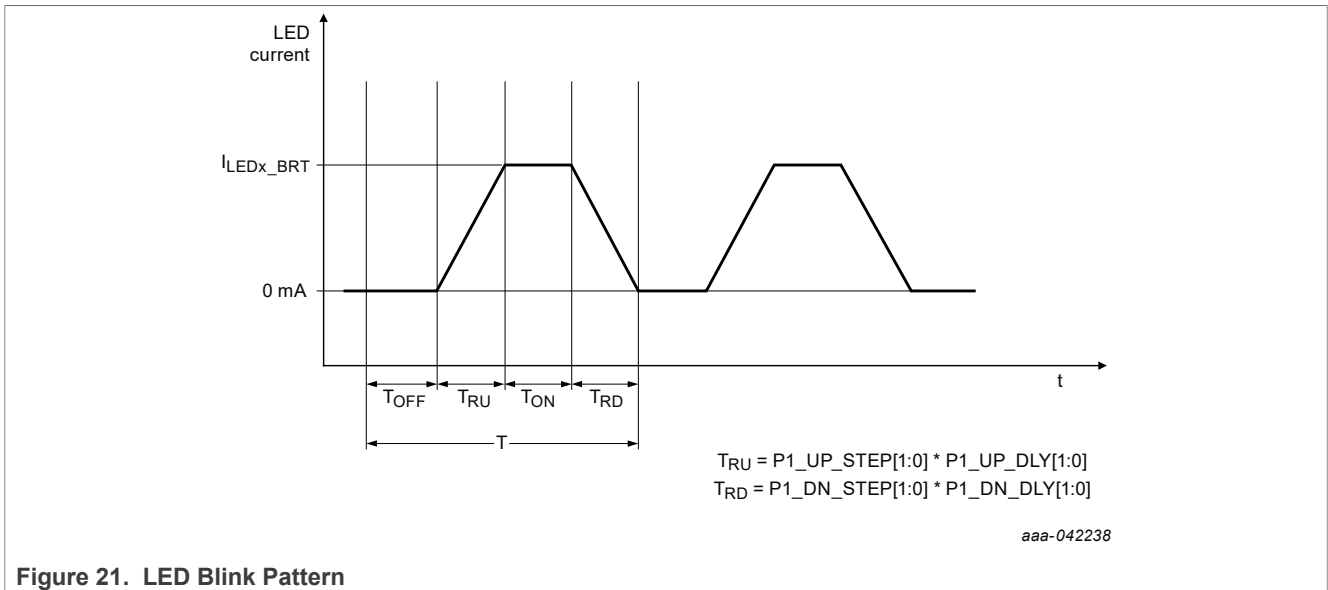


Figure 21. LED Blink Pattern

## 7.8 Mode selection

### 7.8.1 MODE0, MODE1, MODE2

MODE[2:0] pins are purposed to control DVS( Dynamic voltage scaling ) for BUCK 2 and BUCK3 by default. Those pins can be configured to control LDO2 voltage selection or each load switch ON/OFF through MODEPIN\_CFG register as well.

If any MODE pin is configured to any bits other than 00b in MODEPIN\_CFG register, the internal MODE pin in DVS control block is set low. For example, if MODE2\_CFG bits are configured to 001b, then MODE2 pin is used to control LDO2 voltage selection, and the pin in DVS control block is set low.

If any MODE pin is not configured to LDO2 voltage selection, internal LDO2\_VSEL is set low.

Load switch which is not configured to any MODE pin is controlled by only I<sup>2</sup>C register bits, LSWx\_EN[1:0] bits.

Table 16. 0x0D – MODEPIN\_CFG

Reset Type: 0

Bit	Name	Type	Reset	Description
7 to 6	MODE0_CFG	R/W	00	MODE0 pin configuration <b>00b = DVS control</b> 01b = LDO2 voltage selection 10b = LSW1 ON/OFF control 11b = LSW4 ON/OFF control
5 to 3	MODE1_CFG	R/W	000	MODE1 pin configuration <b>000b = DVS control</b> 001b = LDO2 voltage selection 010b = LSW1 ON/OFF control 011b = LSW2 ON/OFF control 100b = LSW3 ON/OFF control 101b-111b = LSW4 ON/OFF control
2 to 0	MODE2_CFG	R/W	000	MODE2 pin configuration <b>000b = DVS control</b>

Table 16. 0x0D – MODEPIN\_CFG...continued

Reset Type: 0

Bit	Name	Type	Reset	Description
				001b = LDO2 voltage selection
				010b = LSW1 ON/OFF control
				011b = LSW2 ON/OFF control
				100b = LSW3 ON/OFF control
				101b-111b = LSW4 ON/OFF control

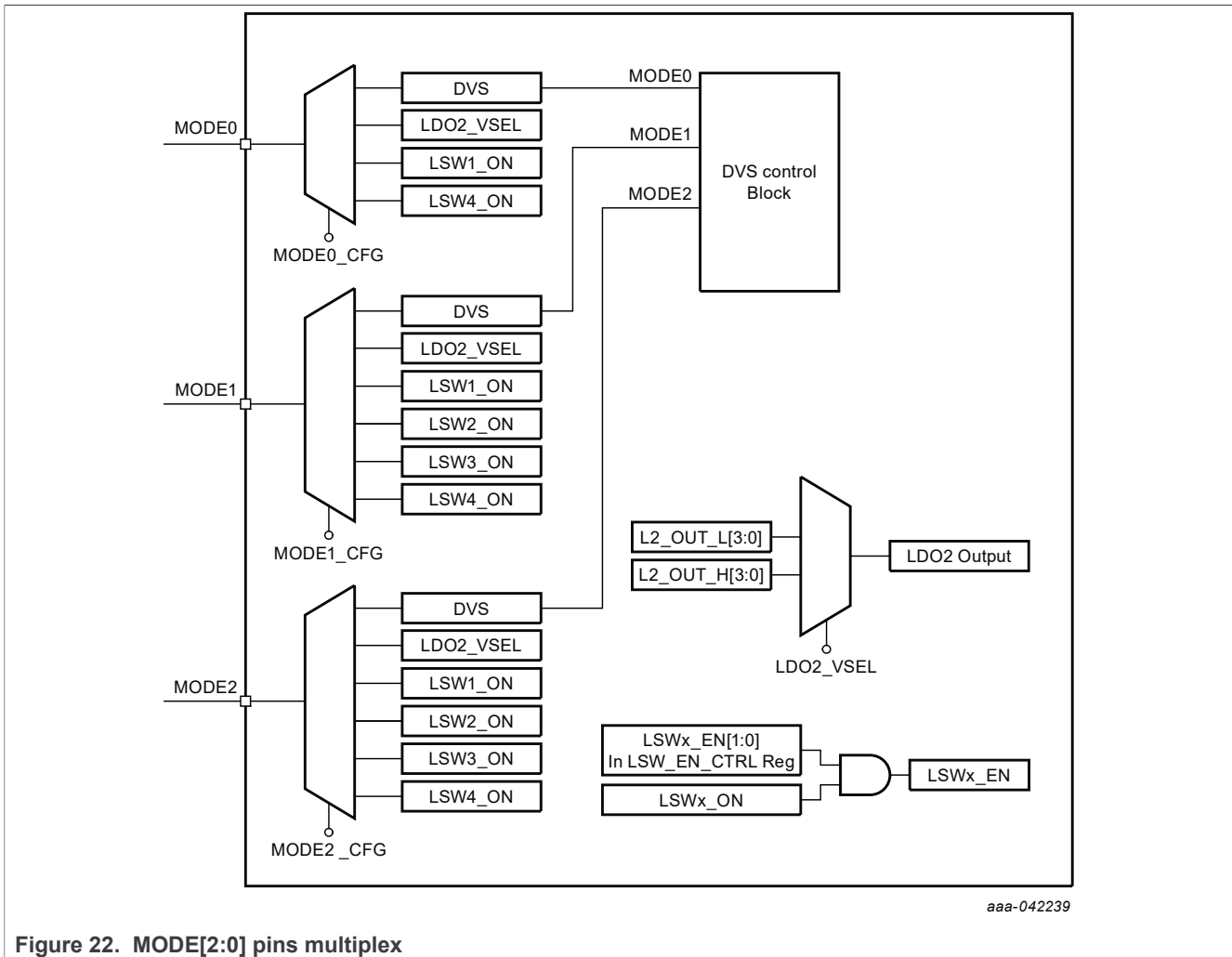


Figure 22. MODE[2:0] pins multiplex

### 7.9 Interrupt management

The IRQ\_B pin is an interface to the software-controlled system that indicates any interrupt bit status change of INT1 register. The IRQ\_B pin is pulled low when any unmasked interrupt bit status is changed, and it is released high once application processor read INT1 register.

The INT1 bits are latched to 1 whenever corresponding INT1\_STATUS1 bit is changed and the latch is cleared when the INT1 register is read. The INT1\_MASK bits are used to enable or disable individual interrupt bits of INT1 register. The INT1\_STATUS1 register indicates the current status and is not latched.

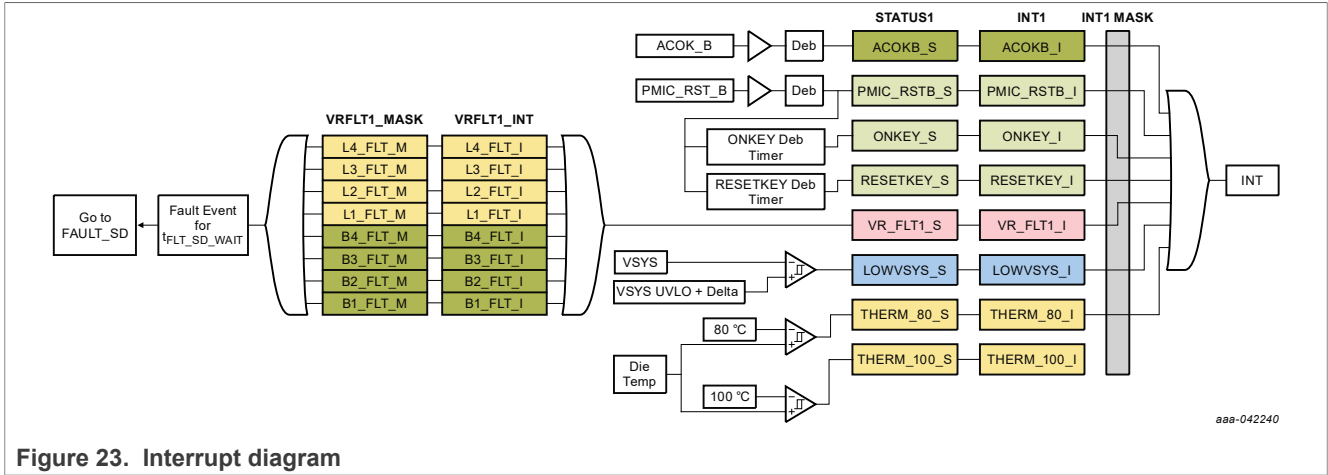


Figure 23. Interrupt diagram

## 8 Software interface

PCA9460 implements I<sup>2</sup>C-bus slave interface and it interfaces with the host system. The host processor can issue commands, monitor status and receive response through this bus. A detailed description of the I<sup>2</sup>C-bus specification, with applications, is given in UM10204, <https://www.nxp.com/docs/en/user-guide/UM10204.pdf>[Ref. 4]. PCA9460 supports I<sup>2</sup>C-bus data transfers in Standard-mode (100 kbit/s), Fast-mode (400 kbit/s) and Fast-mode plus (1 Mbit/s). See [Table 17](#).

Table 17. I<sup>2</sup>C address at Power-On Reset

	7-bit Slave Address	8-bit Write Address	8-bit Read Address
Default	0x32, 0b 011 0010	0x64, 0b 0110 0100	0x65, 0b 0110 0101
OTP1	0x33, 0b 011 0011	0x66, 0b 0110 0110	0x67, 0b 0110 0111
OTP2	0x36, 0b 011 0110	0x6C, 0b 0110 1100	0x6D, 0b 0110 1101
OTP3	0x37, 0b 011 0111	0x6E, 0b 0110 1110	0x6F, 0b 0110 1111

### I<sup>2</sup>C register reset type

There are two type of registers: type O and type S. The differences between them relates to the different conditions that RESET the contents and its corresponding functionality to the default values for those specific registers. Those conditions are shown below for each register type. For more details on whether a register is type S or O refer to [Table 18](#).

Type S : ( VSYS < V<sub>SYSTUVLO</sub> ) || ( VINT\_POK ) || ( SW\_RST\_KEY = 0x09 )

Type O : ( VSYS < V<sub>SYSTUVLO</sub> ) || ( VINT\_POK ) || ( Cold Reset ) || ( Warm Reset ) || ( Falling edge of PMIC\_ON\_SRC ) || ( SW\_RST\_KEY=0x05 ) || ( SW\_RST\_KEY=0x09 ) || ( FAULT\_SD ) || ( Thermal SD )

### 8.1 Register map

Table 18. Register map

Add	Name	Description								R/W	Reset Type	Reset Value <sup>[1]</sup>		
		B7	B6	B5	B4	B3	B2	B1	B0			A	B	C
00h	Device_ID	CHIP_ID				REV_ID				R	S	0x30	0x30	0x30
01h	OTP_Ver	OTP_VER								R	S	0x00	0x10	0x20
02h	INT1	ACOKB_I	PMIC_RS_TB_I	ONKEY_I	RESETKEY_I	VR_FLT1_I	LOWVSY_S_I	THERM_80_I	THERM_100_I	R/C	S	0x00	0x00	0x00

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Table 18. Register map...continued

Add	Name	Description								R/W	Reset Type	Reset Value <sup>[1]</sup>			
		B7	B6	B5	B4	B3	B2	B1	B0			A	B	C	
03h	INT1_MSK	ACOKB_M	PMIC_RS_TB_M	ONKEY_M	RESETKE_Y_M	VR_FLT1_M	LOWVSY_S_M	THERM_80_M	THERM_100_M	R/W	S	0xFF	0xFF	0xFF	
04h	INT1_STATUS	ACOKB_S	PMIC_RS_TB_S	ONKEY_S	RESETKE_Y_S	VR_FLT12S	LOWVSY_S_S	THERM_80_S	THERM_100_S	R	S	0x00	0x00	0x00	
05h	VRFLT1_INT	L4_FLT_I	L3_FLT_I	L2_FLT_I	L1_FLT_I	B4_FLT_I	B3_FLT_I	B2_FLT_I	B1_FLT_I	R/W/C	S	0x00	0x00	0x00	
06h	VRFLT1_MASK	L4_FLT_M	L3_FLT_M	L2_FLT_M	L1_FLT_M	B4_FLT_M	B3_FLT_M	B2_FLT_M	B1_FLT_M	R/W	S	0xFF	0xFF	0xFF	
07h	PWR_STATE	PWR_STAT				PWR_MODE				R	S	0x00	0x00	0x00	
08h	RESET_CTRL	WDOGB_CFG		PMIC_RST_CFG		TRE_START	RSVD	RSVD	RSVD	R/W	S	0x20	0x20	0x20	
09h	SW_RST	SWRST								R/W	O	0x00	0x00	0x00	
0Ah	PWR_SEQ_CTRL	PMIC_RST_B_ON	ACOK_B_ON	PMIC_RST_B_DEB	ACOK_B_O_STMR	PSQ_TON_STEP		PSQ_TOFF_STEP		R/W	S	0x06	0x06	0x06	
0Bh	SYS_CFG1	LOW_VSYS		STANDBY_CFG	RESETKEY_TIMER			TFLT_SD_WAIT	THERM_SD_DIS	R/W	O	0x54	0x54	0x54	
0Ch	SYS_CFG2	ONKEY_TIMER		PWR_SAVE		RSVD	POK_PU	VSYS_UVLO		R/W	S	0x71	0x71	0x71	
0Dh	MODEPIN_CFG	MODE0_CFG		MODE1_CFG			MODE2_CFG			R/W	O	0x00	0x00	0x00	
0Eh-0Fh	RESERVED	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD			0x00	0x00	0x00	
10h	BUCK1CTRL	RSVD	RSVD	B1_LPMODE		B1_AD	B1_FPWM	B1_ENMODE		R/W	O	0x39	0x39	0x39	
11h	BUCK1OUT	RSVD	B1_OUT								R/W	O	0x30	0x30	X030
12h	BUCK23_D_VS_CFG1	B2_DVS_UP	B2_DVS_DN	B3_DVS_UP	B3_DVS_DN	MODE_PULSE	SMART_MODE	MODE2_EN	BUCK_SEL	R/W	O	0x00	0x00	0x00	
13h	BUCK23_D_VS_CFG2	B2_DVS_CTRL		B3_DVS_CTRL		RSVD	RSVD	RSVD	RSVD	R/W	O	0x00	0x00	0x00	
14h	BUCK2CTRL	B2_RAMP		B2_LPMODE		B2_AD	B2_FPWM	B2_ENMODE		R/W	O	0x79	0x79	0x79	
15h	BUCK2OUT_DVS0	RSVD	B2_DVS0								R/W	O	0x20	0x20	0x20
16h	BUCK2OUT_DVS1	RSVD	B2_DVS1								R/W	O	0x18	0x18	0x18
17h	BUCK2OUT_DVS2	RSVD	B2_DVS2								R/W	O	0x18	0x18	0x18
18h	BUCK2OUT_DVS3	RSVD	B2_DVS3								R/W	O	0x18	0x18	0x18
19h	BUCK2OUT_DVS4	RSVD	B2_DVS4								R/W	O	0x18	0x18	0x18
1Ah	BUCK2OUT_DVS5	RSVD	B2_DVS5								R/W	O	0x18	0x18	0x18
1Bh	BUCK2OUT_DVS6	RSVD	B2_DVS6								R/W	O	0x18	0x18	0x18
1Ch	BUCK2OUT_DVS7	RSVD	B2_DVS7								R/W	O	0x18	0x18	0x18
1Dh	BUCK2OUT_STBY	RSVD	B2_DVS_STBY								R/W	O	0x18	0x18	0x18
1Eh	RESERVED	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD			0x00	0x00	0x00	
1Fh	BUCK2OUT	RSVD	B2_MAX_LIMIT								R/W	O	0x38	0x38	X038

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Table 18. Register map...continued

Add	Name	Description								R/W	Reset Type	Reset Value <sup>[1]</sup>				
		B7	B6	B5	B4	B3	B2	B1	B0			A	B	C		
	_MAX_LIMIT															
20h	BUCK2OUT_MIN_LIMIT	RSVD	B2_MIN_LIMIT								R/W	O	0x08	0x08	0x08	
21h	BUCK3CTRL	B3_RAMP		B3_LPmode		B3_AD	B3_FPWM	B3_ENMODE			R/W	O	0x79	0x79	0x79	
22h	BUCK3OUT_DVS0	RSVD	B3_DVS0								R/W	O	0x20	0x20	0x20	
23h	BUCK3OUT_DVS1	RSVD	B3_DVS1								R/W	O	0x20	0x20	0x20	
24h	BUCK3OUT_DVS2	RSVD	B3_DVS2								R/W	O	0x20	0x20	0x20	
25h	BUCK3OUT_DVS3	RSVD	B3_DVS3								R/W	O	0x20	0x20	0x20	
26h	BUCK3OUT_DVS4	RSVD	B3_DVS4								R/W	O	0x20	0x20	0x20	
27h	BUCK3OUT_DVS5	RSVD	B3_DVS5								R/W	O	0x20	0x20	0x20	
28h	BUCK3OUT_DVS6	RSVD	B3_DVS6								R/W	O	0x20	0x20	0x20	
29h	BUCK3OUT_DVS7	RSVD	B3_DVS7								R/W	O	0x20	0x20	0x20	
2Ah	BUCK3OUT_STBY	RSVD	B3_DVS_STBY								R/W	O	0x20	0x20	0x20	
2Bh	RESERVED	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD			0x00	0x00	0x00	
2Ch	BUCK3OUT_MAX_LIMIT	RSVD	B3_MAX_LIMIT								R/W	O	0x38	0x38	0x38	
2Dh	BUCK3OUT_MIN_LIMIT	RSVD	B3_MIN_LIMIT								R/W	O	0x08	0x08	0x08	
2Eh	BUCK4_CTRL		RSVD	B4_LPmode		B4_AD	B4_FPWM	B4_ENMODE			R/W	O	0x39	0x39	0x39	
2Fh	BUCK4OUT	RSVD	B4_OUT								R/W	O	0x14	0x14	0x18	
30h	LDO1_CFG	L1_CSEL		L1_LLSEL		L1_LPmode		L1_ENMODE			R/W	O	0x9D	0x9D	0x9D	
31h	LDO1_OUT	L1_AD	L1_INL1_MDET	L1_INL1_VSEL	L1_OUT						R/W	O	0x8A	0x80	0x8C	
32h	LDO2_CFG	RSVD	RSVD	RSVD	L2_AD	RSVD	RSVD	L2_ENMODE			R/W	O	0x11	0x11	0x11	
33h	LDO2_OUT_L				L2_OUT_L						R/W	O	0x32	0x32	0x32	
34h	LDO2_OUT_H				L2_OUT_H						R/W	O	0x14	0x14	X014	
35h	LDO3_CFG	RSVD	RSVD	RSVD	L3_AD	RSVD	RSVD	L3_ENMODE			R/W	O	0x11	0x11	0x11	
36h	LDO3_OUT				L3_OUT						R/W	O	0x32	0x32	X032	
37h	LDO4_CFG	RSVD	RSVD	RSVD	L4_AD	RSVD	RSVD	L4_ENMODE			R/W	O	0x11	0x11	X011	
38h	LDO4_OUT				L4_OUT						R/W	O	0x14	0x14	0x14	
39h	LDO3_OUT_CFG	LSNVS_AD	LS_ENMODE	L_SNVS_OUT								R/W	O	0xEC	0xEC	0xEC
3Ah-3Fh	RESERVED	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD			0x00	0x00	0x00	
40h	LSW1_CTRL	LSW1_CFG	RSVD	RSVD	LSW1_AD	RSVD	RSVD	LSW1_EN			R/W	O	0x11	0x11	0x11	
41h	LSW2_CTRL	LSW2_CFG	RSVD	RSVD	LSW2_AD	RSVD	RSVD	LSW2_EN			R/W	O	0x11	0x11	0x11	
42h	LSW3_CTRL	LSW3	RSVD	RSVD	LSW3_AD	RSVD	RSVD	LSW3_EN			R/W	O	0x11	0x11	0x11	



Table 18. Register map...continued

Add	Name	Description								R/W	Reset Type	Reset Value <sup>[1]</sup>		
		B7	B6	B5	B4	B3	B2	B1	B0			A	B	C
		_CFG												
43h	LSW4_CTRL	LSW4_CFG	RSVD	RSVD	LSW4_AD	RSVD	RSVD	LSW4_EN		R/W	O	0x11	0x11	0x11
44h	LED1_CTRL	LED1_EN		RSVD	LED1_BRT					R/W	O	0x00	0x00	0x00
45h	LED2_CTRL	LED2_EN		RSVD	LED2_BRT					R/W	O	0x00	0x00	0x00
46h	LED3_CTRL	LED3_EN		RSVD	LED3_BRT					R/W	O	0x00	0x00	0x00
47h	LED4_CTRL	LED4_EN		RSVD	LED4_BRT					R/W	O	0x00	0x00	0x00
48h	LED_P1_RAMP	P1_UP_STEP		P1_UP_DLY		P1_DN_STEP		P1_DN_DLY		R/W	O	0x00	0x00	0x00
49h	LED_P1_BLNK	LEDTON1				LEDOFF1				R/W	O	0x00	0x00	0x00
4Ah	LED_P2_RAMP	P2_UP_STEP		P2_UP_DLY		P2_DN_STEP		P2_DN_DLY		R/W	O	0x00	0x00	0x00
4Bh	LED_P2_BLNK	LEDTON2				LEDOFF2				R/W	O	0x00	0x00	0x00
4Ch-4Dh	RESERVED	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD			0x00	0x00	0x00
4Eh	REG_LOCK	UNLOCK_KEY								R/W	O	0x00	0x00	0x00

Note1. A = PCA9460A, B = PCA9460B, C = PCA9460C

[1] A = PCA9460, B = PCA9460B, C = PCA9460C

## 8.2 Register details

### 8.2.1 Device\_ID

The device identification code stores a unique identifier for each version and/or revision of a PCA9460, so that the connected processor recognizes it automatically.

Table 19. Device\_ID register (address 00h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	CHIP_ID				CHIP_REV			
Reset	0	0	1	1	0	0	0	0
Access	R	R	R	R	R	R	R	R

Table 20. Device\_ID register (address 00h) bit descriptions

Bit	Symbol	Description
7 to 4	CHIP_ID	Chip ID <b>0011</b> — PCA9460 (default)
3 to 0	CHIP_REV	Chip Revision <b>0000</b> — revision 0 (default)

### 8.2.2 OTP\_VER

OTP version information

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Table 21. OTP\_VER register (address 01h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	OTP_VER				OTP_REV			
Reset <sup>[1]</sup>	—	—	—	—	—	—	—	—
Access	R	R	R	R	R	R	R	R

[1] The reset value depends on the specific otp version as shown in [Table 22](#).

Table 22. OTP\_VER register (address 01h) bit descriptions

Bit	Symbol	Description
7 to 4	OTP_VER	OTP version for each PCA9460 variance <b>0000</b> — PCA9460A <b>0001</b> — PCA9460B <b>0010</b> — PCA9460C ... <b>1111</b> — Reserved
3 to 0	OTP_REV	OTP minor change update <b>0000</b> — revision 0 <b>0001</b> — revision 1 ... <b>1111</b> — Reserved

8.2.3 INT1

Interrupt source register. Either of unmasked register bits is set to 1, IRQB pin is pulled low. This register is Read and Clear.

Table 23. INT1 register (address 02h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	ACOKB_I	PMIC_RSTB_I	ONKEY_I	RESETKEY_I	VR_FLT1_I	LOWVSYS_I	THERM_80_I	THERM_100_I
Reset	0	0	0	0	0	0	0	0
Access	R/C	R/C	R/C	R/C	R/C	R/C	R/C	R/C

Table 24. INT1 register (address 02h) bit descriptions

Bit	Symbol	Description
7	ACOKB_I	ACOKB interrupt <b>0</b> — ACOKB_S bit has not been changed (default) <b>1</b> — ACOKB_S bit has been changed
6	PMIC_RSTB_I	PMIC_RSTB_I interrupt <b>0</b> — PMIC_RSTB_S bit has not been changed (default) <b>1</b> — PMIC_RSTB_S bit has been changed
5	ONKEY_I	ON Key timer interrupt <b>0</b> — ONKEY_S bit has not been changed (default) <b>1</b> — ONKEY_S bit has been changed
4	RESETKEY_I	RESET Key timer interrupt <b>0</b> — RESETKEY_S bit has not been changed (default) <b>1</b> — RESETKEY_S bit has been changed

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Table 24. INT1 register (address 02h) bit descriptions...continued

Bit	Symbol	Description
3	VR_FLT1_I	Voltage regulator Group1 Fault <b>0</b> — VR_FLT1_S bit has not been changed (default) <b>1</b> — VR_FLT1_S bit has been changed
2	LOWVSYS_I	Low-SYS Voltage interrupt <b>0</b> — LOWVSYS_S bit has not been changed (default) <b>1</b> — LOWVSYS_S bit has been changed
1	THERM_80_I	Die temperature 80 °C interrupt <b>0</b> — THERM_80_S bit has not been changed (default) <b>1</b> — THERM_80_S bit has been changed
0	THERM_100_I	Die temperature 100 °C interrupt <b>0</b> — THERM_100_S bit has not been changed (default) <b>1</b> — THERM_100_S bit has been changed

8.2.4 INT1\_MASK

Table 25. INT1\_MASK register (address 03h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	ACOKB_M	PMIC_RSTB_M	ONKEY_M	RESETKEY_M	VR_FLT1_M	LOWVSYS_M	THERM_80_M	THERM_100_M
Reset	1	1	1	1	1	1	1	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 26. INT1\_MASK register (address 03h) bit descriptions

Bit	Symbol	Description
7	ACOKB_M	ACOKB_I interrupt mask bit <b>0</b> — Enable ACOKB_I interrupt <b>1</b> — Mask ACOKB_I interrupt (default)
6	PMIC_RSTB_M	PMIC_RSTB_I interrupt mask bit <b>0</b> — Enable PMIC_RSTB_I interrupt <b>1</b> — Mask PMIC_RSTB_I interrupt (default)
5	ONKEY_M	ONKEY_I interrupt mask bit <b>0</b> — Enable ONKEY_I interrupt <b>1</b> — Mask ONKEY_I interrupt (default)
4	RESETKEY_M	RESETKEY_I interrupt mask bit <b>0</b> — Enable RESETKEY_I interrupt <b>1</b> — Mask RESETKEY_I interrupt (default)
3	VR_FLT1_M	VR_FLT1I interrupt mask bit <b>0</b> — Enable VR_FLT1I interrupt <b>1</b> — Mask VR_FLT1I interrupt (default)
2	LOWVSYS_M	LOWVINI interrupt mask bit <b>0</b> — Enable LOWVINI interrupt <b>1</b> — Mask LOWVINI interrupt (default)
1	THERM_80_M	THERM_80 interrupt mask bit <b>0</b> — Enable THERM_80 interrupt <b>1</b> — Mask THERM_80 interrupt (default)
0	THERM_100_M	THERM_100 interrupt mask bit <b>0</b> — Enable THERM_100 interrupt

Table 26. INT1\_MASK register (address 03h) bit descriptions...continued

Bit	Symbol	Description
		1 — Mask THERM_100 interrupt (default)

### 8.2.5 INT1\_STATUS

STATUS register shows current status. Any status bit change sets corresponding interrupt bit to 1.

Table 27. INT1\_STATUS register (address 04h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	ACOKB_S	PMIC_RSTB_S	ONKEY_S	RESETKEY_S	VR_FLT1_S	LOWVSYS_S	THERM_80_S	THERM_100_S
Reset	—	—	—	—	—	—	—	—
Access	R	R	R	R	R	R	R	R

Table 28. INT1\_STATUS register (address 04h) bit descriptions

Bit	Symbol	Description
7	ACOKB_S	ACOK_B pin status after debounce time 0 — ACOK_B pin is low 1 — ACOK_B pin is high
6	PMIC_RSTB_S	PMIC_RST_B pin status 0 — PMIC_RST_B pin is low 1 — PMIC_RST_B pin is high
5	ONKEY_S	ONKEY status bit 0 — PMIC_RST_B pin is not low for ONKEY timer 1 — PMIC_RST_B pin is low for ONKEY timer
4	RESETKEY_S	RESETKEY status bit 0 — PMIC_RST_B pin is not low for RESETKEY timer 1 — PMIC_RST_B pin is low for RESETKEY timer
3	VR_FLT1_S	Voltage Regulator Fault status, See 0x40 Register. 0 — All voltage regulators are OK 1 — Either of voltage regulators is in Fault state
2	LOWVSYS_S	VSYS low voltage status 0 — Enable LOWVINI interrupt 1 — Mask LOWVINI interrupt
1	THERM_80_S	Die temperature 80 °C status 0 — Die temperature is below 80 °C 1 — Die temperature is above 80 °C
0	THERM_100_S	Die temperature 100 °C status 0 — Die temperature is below 100 °C 1 — Die temperature is above 100 °C

### 8.2.6 VRFLT1\_INT

Voltage regulator fault interrupt register. It is latched to 1 once corresponding regulator is detected until overwriting "1" to the register. If "1" is overwritten, the corresponding bit is newly updated by current status.

Table 29. VRFLT1\_INT register (address 05h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	L4_FLT_I	L3_FLT_I	L2_FLT_I	L1_FLT_I	B4_FLT_I	B3_FLT_I	B2_FLT_I	B1_FLT_I
Reset	0	0	0	0	0	0	0	0
Access	R/W/C	R/W/C	R/W/C	R/W/C	R/W/C	R/W/C	R/W/C	R/W/C

Table 30. VRFLT1\_INT register (address 05h) bit descriptions

Bit	Symbol	Description
7	L4_FLT_I	LDO4 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — LDO4 output is good or LDO4 is OFF (default) <b>1</b> — LDO4 output falls below 80 % of target
6	L3_FLT_I	LDO3 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — LDO3 output is good or LDO3 is OFF (default) <b>1</b> — LDO3 output falls below 80 % of target
5	L2_FLT_I	LDO2 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — LDO2 output is good or LDO2 is OFF (default) <b>1</b> — LDO2 output falls below 80 % of target
4	L1_FLT_I	LDO1 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — LDO1 output is good or LDO1 is OFF (default) <b>1</b> — LDO1 output falls below 80 % of target
3	B4_FLT_I	BUCK4 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — BUCK4 output is good or BUCK4 is OFF (default) <b>1</b> — BUCK4 output is below 80 %
2	B3_FLT_I	BUCK3 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — BUCK3 output is good or BUCK3 is OFF (default) <b>1</b> — BUCK3 output falls below 80 % of target
1	B2_FLT_I	BUCK2 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — BUCK2 output is good or BUCK2 is OFF (default) <b>1</b> — BUCK2 output falls below 80 % of target
0	B1_FLT_I	BUCK1 Fault interrupt, deglitched with $t_{DEB\_POKB}$ <b>0</b> — BUCK1 output is good or BUCK1 is OFF (default) <b>1</b> — BUCK1 output falls below 80 % of target

### 8.2.7 VRFLT1\_MASK

VR fault mask bit. Once the bit is masked, PCA9460 doesn't enter Fault shutdown even if fault condition of corresponding regulator happens

Table 31. VRFLT1\_MASK register (address 06h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	L4_FLT_M	L3_FLT_M	L2_FLT_M	L1_FLT_M	B4_FLT_M	B3_FLT_M	B2_FLT_M	B1_FLT_M
Reset	1	1	1	1	1	1	1	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 32. VRFLT1\_MASK register (address 06h) bit descriptions

Bit	Symbol	Description
7	L4_FLT_M	LDO4 FLT mask

Table 32. VRFLT1\_MASK register (address 06h) bit descriptions...continued

Bit	Symbol	Description
		<b>0</b> — Unmask <b>1</b> — Masked (default)
6	L3_FLT_M	LDO3 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
5	L2_FLT_M	LDO2 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
4	L1_FLT_M	LDO1 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
3	B4_FLT_M	BUCK4 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
2	B3_FLT_M	BUCK3 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
1	B2_FLT_M	BUCK2 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)
0	B1_FLT_M	BUCK1 FLT mask <b>0</b> — Unmask <b>1</b> — Masked (default)

### 8.2.8 PWR\_STATE

Power state register shows current PCA9460 power states and modes.

Table 33. PWR\_STATE register (address 07h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	PWR_STAT				PWR_MODE			
Reset	0	0	0	0	0	0	0	0
Access	R	R	R	R	R	R	R	R

Table 34. PWR\_STATE register (address 07h) bit descriptions

Bit	Symbol	Description
7 to 4	PWR_STAT	Current PCA9460 STATES <b>0000</b> — OFF (default) <b>0100</b> — SNVS <b>0101</b> — PWRUP <b>1000</b> — RUN <b>1100</b> — PWRDN <b>1110</b> — FAULT_SD <b>others</b> — Reserved
3 to 0	PWR_MODE	Current PCA9460 MODE, only effective at RUN state <b>0000</b> — Active mode – DVS0 (default) <b>0001</b> — Active mode – DVS1 <b>0010</b> — Active mode – DVS2

Table 34. PWR\_STATE register (address 07h) bit descriptions...continued

Bit	Symbol	Description
		<b>0011</b> — Active mode – DVS3 <b>0100</b> — Active mode – DVS4 <b>0101</b> — Active mode – DVS5 <b>0110</b> — Active mode – DVS6 <b>0111</b> — Active mode – DVS7 <b>1000</b> — STANDBY MODE <b>1010</b> — DP_STANDBYMODE <b>others</b> — Reserved

8.2.9 RESET\_CTRL

Reset behavior configuration register

Table 35. RESET\_CTRL register (address 08h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	WDOGB_CFG		PMIC_RST_CFG		TRESTART	RSVD		
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 36. RESET\_CTRL register (address 08h) bit descriptions

Bit	Symbol	Description
7 to 6	WDOGB_CFG	When WDOG_B is asserted to low, PMIC reset behavior <b>00</b> — WDOG_B reset is disabled (default) <b>01</b> — Warm reset, POR_B pin is asserted low for 20 ms <b>10 and 11</b> — Cold Reset, all voltage regulators are recycled
5 to 4	PMIC_RST_CFG	When PMIC_RST_B is asserted to low, PMIC reset behavior <b>00</b> — PMIC_RST_B reset is disabled <b>01</b> — Warm Reset, POR_B pin is asserted low for 20 ms <b>10 and 11</b> — Cold Reset, all voltage regulators are recycled (default)
3	TRESTART	Time to stay regulators off during Cold reset <b>0</b> — 250 ms (default) <b>1</b> — 500 ms
2 to 0	RSVD	Reserved

8.2.10 SW\_RST

Software reset register

Table 37. SW\_RST register (address 09h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	SW_RST_KEY							
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 38. SW\_RST register (address 09h) bit descriptions

Bit	Symbol	Description
7 to 0	SW_RST_KEY	Software reset register. This register is read back to "0x00" right after writing the value. <b>0000 0000</b> — No action (default) <b>0000 0101</b> — Reset O-type registers to default value <b>0000 1001</b> — Reset O-type registers and S-type registers <b>0000 1110</b> — Cold reset (Power recycle all regulators) <b>0010 0011</b> — Warm Reset (Toggle POR_B for 20 ms) <b>1110 1110</b> — PMIC digital reset (Debug purpose only) <b>others</b> — Forbidden

### 8.2.11 PWR\_SEQ\_CTRL

Debounce timer configuration register

Table 39. PWR\_SEQ\_CTRL register (address 0Ah) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	PMIC_RST_B_ON	ACOK_B_ON	PMIC_RST_B_DEB	ACOK_B_OSTMR	PSQ_TON_STEP		PSQ_TOFF_STEP	
Reset	0	0	0	0	0	1	1	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 40. PWR\_SEQ\_CTRL register (address 0Ah) bit descriptions

Bit	Symbol	Description
7	PMIC_RST_B_ON	Configure PMIC_RST_B pin as Power ON source <b>0</b> — Mask (default) <b>1</b> — Power ON Source
6	ACOK_B_ON	Configure ACOK_B pin as Power ON source <b>0</b> — Mask (default) <b>1</b> — Power ON Source
5	PMIC_RST_B_DEB	Debounce time for PMIC_RST_B pin for falling edge. ( rising edge doesn't have debounce time) <b>0</b> — 20 ms (default) <b>1</b> — 100 ms
4	ACOK_B_OSTMR	Oneshot timer for ACOK_B, Oneshot timer works only at SNVS state <b>0</b> — 2.5 sec (default) <b>1</b> — 5 sec
3 to 2	PSQ_TON_STEP	Time step configuration during power on sequence <b>00</b> — 1 ms <b>01</b> — 2 ms (default) <b>10</b> — 4 ms <b>11</b> — 8 ms
1 to 0	PSQ_TOFF_STEP	Time step configuration during power down sequence <b>00</b> — 2 ms <b>01</b> — 4 ms <b>10</b> — 8 ms (default) <b>11</b> — 16 ms

### 8.2.12 SYS\_CFG1

VSYS\_UVLO and LOW VSYS configuration register



Table 41. SYS\_CFG1 register (address 0Bh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LOW_VSYS		STANDBY_CFG	RESETKEY_TIMER			TFLT_SD_WAIT	THERM_SD_DIS
Reset	0	1	0	1	0	1	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 42. SYS\_CFG1 register (address 0Bh) bit descriptions

Bit	Symbol	Description
7 to 6	LOW_VSYS	Low VSYS threshold above $V_{SYS\_UVLO}$ <b>00</b> — 100 mV <b>01</b> — 200 mV (default) <b>10</b> — 300 mV <b>11</b> — 400 mV
5	STANDBY_CFG	Mode configuration bit when PMIC_STBY_REQ pin is High <b>0</b> — STANDBY mode (default) <b>1</b> — DPSTANDBY mode
4 to 2	RESETKEY_TIMER	RESETKEY timer configuration after PMIC_RST_B pin falls low <b>000</b> — 100 ms <b>001</b> — 1 sec <b>010</b> — 2 sec <b>011</b> — 4 sec <b>100</b> — 6 sec <b>101</b> — 8 sec (default) <b>110</b> — 10 sec <b>111</b> — 12 sec
1	TFLT_SD_WAIT	Wait time for AP action when regulator fault occurs <b>0</b> — 100 ms (default) <b>1</b> — 20 $\mu$ s
0	THERM_SD_DIS	Thermal shutdown disable bit <b>0</b> — Enable Thermal shutdown (default) <b>1</b> — Disable Thermal shutdown

### 8.2.13 SYS\_CFG2

ONKEY timer, power save mode and VSYS UVLO configuration register

Table 43. SYS\_CFG2 register (address 0Ch) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	ONKEY_TIMER		PWR_SAVE		RSVD	POK_PU	VSYS_UVLO	
Reset	0	1	1	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 44. SYS\_CFG2 register (address 0Ch) bit descriptions

Bit	Symbol	Description
7 to 6	ONKEY_TIMER	ONKEY timer configuration after PMIC_RST_B pin falls low <b>00</b> — 1 sec <b>01</b> — 2 sec (default)

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Table 44. SYS\_CFG2 register (address 0Ch) bit descriptions...continued

Bit	Symbol	Description
		<b>10</b> — 4 sec <b>11</b> — 8 sec
5 to 4	PWR_SAVE	Power save mode (Disabling High accuracy BG and Thermal shutdown) <b>00</b> — Use Low Iq BG and enable Thermal shutdown <b>01</b> — Power save mode at STANDBY/DPSTANDBY mode <b>10</b> — Power save mode at DPSTANDBY mode <b>11</b> — Normal Power mode (default)
3	RSVD	Reserved
2	POK_PU	POK reference during power up <b>0</b> — POK is reference to turn on next power group (default) <b>1</b> — POK is ignored during power up
1 to 0	VSYS_UVLO	VSYS UVLO threshold, rising threshold <b>00</b> — 2.65 V <b>01</b> — 2.85 V (default) <b>10</b> — 3.0 V <b>11</b> — 3.3V

8.2.14 MODEPIN\_CFG

MODE0, MODE1, MODE2 pin control configuration

Table 45. MODEPIN\_CFG register (address 0Dh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	MODE0_CFG		MODE1_CFG			MODE2_CFG		
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 46. MODEPIN\_CFG register (address 0Dh) bit descriptions

Bit	Symbol	Description
7 to 6	MODE0_CFG	MODE0 pin configuration <b>00</b> — DVS control (default) <b>01</b> — LDO2 voltage selection <b>10</b> — LSW1 ON/OFF control <b>11</b> — LSW4 ON/OFF control
5 to 3	MODE1_CFG	MODE1 pin configuration <b>000</b> — DVS control (default) <b>001</b> — LDO2 voltage selection <b>010</b> — LSW1 ON/OFF control <b>011</b> — LSW2 ON/OFF control <b>100</b> — LSW3 ON/OFF control <b>101 and 111</b> — LSW4 ON/OFF control
2 to 0	MODE2_CFG	MODE2 pin configuration <b>000</b> — DVS control (default) <b>001</b> — LDO2 voltage selection <b>010</b> — LSW1 ON/OFF control <b>011</b> — LSW2 ON/OFF control <b>100</b> — LSW3 ON/OFF control <b>101 and 111</b> — LSW4 ON/OFF control

8.2.15 BUCK1CTRL

BUCK1 control register for Active discharge, FPWM and Enable.

Table 47. BUCK1CTRL register (address 10h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD		B1_LPMODE		B1_AD	B1_FPWM	B1_ENMODE	
Reset	0	0	1	1	1	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 48. BUCK1CTRL register (address 10h) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Reserved
5 to 4	B1_LPMODE	BUCK1 Low power mode <b>00</b> — Automatic transition mode <b>01</b> — Low power mode at STANDBY mode and DPSTANDBY mode <b>10</b> — Low power mode at DPSTANDBY mode <b>11</b> — Normal mode (default)
3	B1_AD	Buck1 Active discharge <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF(default)
2	B1_FPWM	Forced PWM mode <b>0</b> — Automatic PFM and PWM mode transition (default) <b>1</b> — Forced PWM mode
1 to 0	B1_ENMODE	Buck1 enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.16 BUCK1OUT

BUCK1 output voltage configuration register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 49. BUCK1OUT register (address 11h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B1_OUT						
Reset	0	0	1	1	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 50. BUCK1OUT register (address 11h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B1_OUT	BUCK1 Output voltage Programmable from 0.60 V to 3.40 V in 25 mV steps <b>011 0000</b> — 1.8 V (default)

Table 50. BUCK1OUT register (address 11h) bit descriptions...continued

Bit	Symbol	Description
		See <a href="#">Table 108</a>

### 8.2.17 BUCK23\_DVS\_CFG1

BUCK2, BUCK3 DVS control configuration register

Table 51. BUCK23\_DVS\_CFG1 register (address 12h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	B2_DVS_UP	B2_DVS_DN	B3_DVS_UP	B3_DVS_DN	MODE_PULSE	SMART_MODE	MODE2_EN	BUCK_SEL
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 52. BUCK23\_DVS\_CFG1 register (address 12h) bit descriptions

Bit	Symbol	Description
7	B2_DVS_UP	BUCK2 increment step from MODE[1:0] pins pulse <b>0</b> — 12.5 mV (default) <b>1</b> — 25 mV
6	B2_DVS_DN	BUCK2 decrement step from MODE[1:0] pins pulse <b>0</b> — 12.5 mV (default) <b>1</b> — 25 mV
5	B3_DVS_UP	BUCK3 increment step from MODE[1:0] pins pulse <b>0</b> — 12.5 mV (default) <b>1</b> — 25 mV
4	B3_DVS_DN	BUCK3 decrement step from MODE[1:0] pins pulse <b>0</b> — 12.5 mV (default) <b>1</b> — 25 mV
3	MODE_PULSE	Mode pin pulse width configuration <b>0</b> — 0 μs (default) <b>1</b> — 2 μs
2	SMART_MODE	DVS smart mode configuration <b>0</b> — Smart mode disabled. BUCK2/3 output voltage is determined by BUCKx_OUT_DVSx from MODE[2:0] pin logic combination (default) <b>1</b> — Smart mode enabled
1	MODE2_EN	MODE2 pin enable bit ( Only when SMART_MODE bit = 1b ) <b>0</b> — Mode2 pin is ignored (default) <b>1</b> — Mode2 pin is used to select BUCK2 or BUCK3 for DVS control
0	BUCK_SEL	BUCK selection in Smart DVS mode when MODE2_EN bit = 0b. <b>0</b> — BUCK2 (default) <b>1</b> — BUCK3

### 8.2.18 BUCK23\_DVS\_CFG2

BUCK2, BUCK3 DVS control configuration register

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Table 53. BUCK23\_DVS\_CFG2 register (address 13h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	B2_DVS_CTRL		B3_DVS_CTRL		RSVD			
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 54. BUCK23\_DVS\_CFG2 register (address 13h) bit descriptions

Bit	Symbol	Description
7 to 6	B2_DVS_CTRL	BUCK2 DVS Control <b>00</b> — DVS control BUCK2OUT_DVS0 Reg through I2C (default) <b>01</b> — DVS control through PMIC_STBY_REQ pin <b>10</b> — DVS control through MODE[2:0] pins in Active mode and the voltage set to BUCK2OUT_STBY when PMIC_STBY_REQ = H <b>11</b> — DVS control through MODE[2:0] pins in RUN state
5 to 4	B3_DVS_CTRL	BUCK3 DVS Control <b>00</b> — DVS control BUCK3OUT_DVS0 Reg through I2C (default) <b>01</b> — DVS control through PMIC_STBY_REQ pin <b>10</b> — DVS control through MODE[2:0] pins in Active mode and the voltage set to BUCK3OUT_STBY when PMIC_STBY_REQ = H <b>11</b> — DVS control through MODE[2:0] pins in RUN state
3 to 0	RSVD	Reserved

## 8.2.19 BUCK2CTRL

BUCK2 control register for Ramp, DVS control, Active discharge, FPWM and Enable.

Table 55. BUCK2CTRL register (address 14h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	B2_RAMP		B2_LPMODE		B2_AD	B2_FPWM	B2_ENMODE	
Reset	0	1	1	1	1	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 56. BUCK2CTRL register (address 14h) bit descriptions

Bit	Symbol	Description
7 to 6	B2_RAMP	BUCK2 DVS speed <b>00</b> — 25 mV / 1 $\mu$ s <b>01</b> — 25 mV / 2 $\mu$ s (default) <b>10</b> — 25 mV / 4 $\mu$ s <b>11</b> — 25 mV / 8 $\mu$ s
5 to 4	B2_LPMODE	BUCK2 power mode <b>00</b> — Automatic transition mode <b>01</b> — Low power mode at STANDBY mode and DPSTANDBY mode <b>10</b> — Low power mode at DPSTANDBY mode <b>11</b> — Normal mode (default)
3	B2_AD	BUCK2 Active discharge <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
2	B2_FPWM	Forced PWM mode

Table 56. BUCK2CTRL register (address 14h) bit descriptions...continued

Bit	Symbol	Description
		<b>0</b> — Automatic PFM and PWM mode transition (default) <b>1</b> — Forced PWM mode
1 to 0	B2_ENMODE	BUCK2 enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.20 BUCK2OUT\_DVS0

BUCK2 DVS output voltage when MODE[2:0] = 000 && PMIC\_STBY\_REQ = L

Table 57. BUCK2OUT\_DVS0 register (address 15h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS0						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 58. BUCK2OUT\_DVS0 register (address 15h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS0	BUCK2 DVS0 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

8.2.21 BUCK2OUT\_DVS1

BUCK2 DVS output voltage when MODE[2:0] = 001 && PMIC\_STBY\_REQ = L

Table 59. BUCK2OUT\_DVS1 register (address 16h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS1						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 60. BUCK2OUT\_DVS1 register (address 16h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS1	BUCK2 DVS1 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.22 BUCK2OUT\_DVS2

BUCK2 DVS output voltage when MODE[2:0] = 010 && PMIC\_STBY\_REQ = L

Table 61. BUCK2OUT\_DVS2 register (address 17h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS2						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 62. BUCK2OUT\_DVS2 register (address 17h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS2	BUCK1 DVS2 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.23 BUCK2OUT\_DVS3

BUCK2 DVS output voltage when MODE[2:0] = 011 && PMIC\_STBY\_REQ = L

Table 63. BUCK2OUT\_DVS3 register (address 18h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS3						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 64. BUCK2OUT\_DVS3 register (address 18h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS3	BUCK2 DVS3 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.24 BUCK2OUT\_DVS4

BUCK2 DVS output voltage when MODE[2:0] = 100 && PMIC\_STBY\_REQ = L

Table 65. BUCK2OUT\_DVS4 register (address 19h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS4						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 66. BUCK2OUT\_DVS4 register (address 19h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS4	BUCK2 DVS4 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.25 BUCK2OUT\_DVS5

BUCK2 DVS output voltage when MODE[2:0] = 101 && PMIC\_STBY\_REQ = L

Table 67. BUCK2OUT\_DVS5 register (address 1Ah) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS5						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 68. BUCK2OUT\_DVS5 register (address 1Ah) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS5	BUCK2 DVS5 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.26 BUCK2OUT\_DVS6

BUCK2 DVS output voltage when MODE[2:0] = 110 && PMIC\_STBY\_REQ = L

Table 69. BUCK2OUT\_DVS6 register (address 1Bh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS6						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 70. BUCK2OUT\_DVS6 register (address 1Bh) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS6	BUCK2 DVS6 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

8.2.27 BUCK2OUT\_DVS7

BUCK2 DVS output voltage when MODE[2:0] = 111 && PMIC\_STBY\_REQ = L



Table 71. BUCK2OUT\_DVS7 register (address 1Ch) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS7						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 72. BUCK2OUT\_DVS7 register (address 1Ch) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS7	BUCK2 DVS7 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

### 8.2.28 BUCK2OUT\_STDBY

BUCK2 DVS output voltage PMIC\_STBY\_REQ = H

Table 73. BUCK2OUT\_STDBY register (address 1Dh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_DVS_STBY						
Reset	0	0	0	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 74. BUCK2OUT\_STDBY register (address 1Dh) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_DVS_STBY	BUCK2 Output voltage at Standby mode Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>001 1000</b> — 0.9 V (default) See <a href="#">Table 107</a>

### 8.2.29 BUCK2OUT\_MAX\_LIMIT

BUCK2 output voltage max limit register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 75. BUCK2OUT\_MAX\_LIMIT register (address 1Fh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_MAX_LIMIT						
Reset	0	0	1	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 76. BUCK2OUT\_MAX\_LIMIT register (address 1Fh) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_MAX_LIMIT	BUCK2 output voltage maximum limit Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>011 1000</b> — 1.3 V (default) See <a href="#">Table 107</a>

### 8.2.30 BUCK2OUT\_MIN\_LIMIT

BUCK2 output voltage Lower limit register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 77. BUCK2OUT\_MIN\_LIMIT register (address 20h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B2_MIN_LIMIT						
Reset	0	0	0	0	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 78. BUCK2OUT\_MIN\_LIMIT register (address 20h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B2_MIN_LIMIT	BUCK2 output voltage minimum limit Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>000 1000</b> — 0.7 V (default) See <a href="#">Table 107</a>

### 8.2.31 BUCK3CTRL

BUCK3 control register for Ramp, DVS control, Active discharge, FPWM and Enable.

Table 79. BUCK3CTRL register (address 21h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	B3_RAMP		B3_LPMODE		B3_AD	B3_FPWM	B3_ENMODE	
Reset	0	1	1	1	1	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 80. BUCK3CTRL register (address 21h) bit descriptions

Bit	Symbol	Description
7 to 6	B3_RAMP	BUCK3 DVS speed <b>00</b> — 25 mV / 1 $\mu$ s <b>01</b> — 25 mV / 2 $\mu$ s (default) <b>10</b> — 25 mV / 4 $\mu$ s <b>11</b> — 25 mV / 8 $\mu$ s
5 to 4	B3_LPMODE	BUCK3 power mode <b>00</b> — Automatic transition mode <b>01</b> — Low power mode at STANDBY mode and DPSTANDBY mode

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Table 80. BUCK3CTRL register (address 21h) bit descriptions...continued

Bit	Symbol	Description
		<b>10</b> — Low power mode at DPSTANDBY mode <b>11</b> — Normal mode (default)
3	B3_AD	BUCK3 Active discharge <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
2	B3_FPWM	Forced PWM mode <b>0</b> — Automatic PFM and PWM mode transition (default) <b>1</b> — Forced PWM mode
1 to 0	B3_ENMODE	BUCK3 enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.32 BUCK3OUT\_DVS0

BUCK3 DVS output voltage when MODE[2:0] = 000 && PMIC\_STBY\_REQ = L

Table 81. BUCK3OUT\_DVS0 register (address 22h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS0						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 82. BUCK3OUT\_DVS0 register (address 22h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS0	BUCK3 DVS0 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

8.2.33 BUCK3OUT\_DVS1

BUCK3 DVS output voltage when MODE[2:0] = 001 && PMIC\_STBY\_REQ = L

Table 83. BUCK3OUT\_DVS1 register (address 23h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS1						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 84. BUCK3OUT\_DVS1 register (address 23h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved

Table 84. BUCK3OUT\_DVS1 register (address 23h) bit descriptions...continued

Bit	Symbol	Description
6 to 0	B3_DVS1	BUCK3 DVS1 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

8.2.34 BUCK3OUT\_DVS2

BUCK3 DVS output voltage when MODE[2:0] = 010 && PMIC\_STBY\_REQ = L

Table 85. BUCK3OUT\_DVS2 register (address 24h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS2						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 86. BUCK3OUT\_DVS2 register (address 24h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS2	BUCK1 DVS2 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

8.2.35 BUCK3OUT\_DVS3

BUCK3 DVS output voltage when MODE[2:0] = 011 && PMIC\_STBY\_REQ = L

Table 87. BUCK3OUT\_DVS3 register (address 25h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS3						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 88. BUCK3OUT\_DVS3 register (address 25h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS3	BUCK3 DVS3 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

8.2.36 BUCK3OUT\_DVS4

BUCK3 DVS output voltage when MODE[2:0] = 100 && PMIC\_STBY\_REQ = L

Table 89. BUCK3OUT\_DVS4 register (address 26h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS4						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 90. BUCK3OUT\_DVS4 register (address 26h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS4	BUCK3 DVS4 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

### 8.2.37 BUCK3OUT\_DVS5

BUCK3 DVS output voltage when MODE[2:0] = 101 && PMIC\_STBY\_REQ = L

Table 91. BUCK3OUT\_DVS5 register (address 27h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS5						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 92. BUCK3OUT\_DVS5 register (address 27h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS5	BUCK3 DVS5 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

### 8.2.38 BUCK3OUT\_DVS6

BUCK3 DVS output voltage when MODE[2:0] = 110 && PMIC\_STBY\_REQ = L

Table 93. BUCK3OUT\_DVS6 register (address 28h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS6						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 94. BUCK3OUT\_DVS6 register (address 28h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved

Table 94. BUCK3OUT\_DVS6 register (address 28h) bit descriptions...continued

Bit	Symbol	Description
6 to 0	B3_DVS6	BUCK3 DVS6 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

### 8.2.39 BUCK3OUT\_DVS7

BUCK3 DVS output voltage when MODE[2:0] = 111 && PMIC\_STBY\_REQ = L

Table 95. BUCK3OUT\_DVS7 register (address 29h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS7						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 96. BUCK3OUT\_DVS7 register (address 29h) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS7	BUCK3 DVS7 Output voltage Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

### 8.2.40 BUCK3OUT\_STDBY

BUCK3 DVS output voltage PMIC\_STBY\_REQ = H

Table 97. BUCK3OUT\_STDBY register (address 2Ah) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_DVS_STBY						
Reset	0	0	1	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 98. BUCK3OUT\_STDBY register (address 2Ah) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_DVS_STBY	BUCK3 Output voltage at Standby mode Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>010 0000</b> — 1.0 V (default) See <a href="#">Table 107</a>

### 8.2.41 BUCK3OUT\_MAX\_LIMIT

BUCK3 output voltage max limit register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 99. BUCK3OUT\_MAX\_LIMIT register (address 2Ch) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_MAX_LIMIT						
Reset	0	0	1	1	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 100. BUCK3OUT\_MAX\_LIMIT register (address 2Ch) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_MAX_LIMIT	BUCK3 output voltage max limit Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>011 1000</b> — 1.3 V (default) See <a href="#">Table 107</a>

### 8.2.42 BUCK3OUT\_MIN\_LIMIT

BUCK3 output voltage lower limit register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 101. BUCK3OUT\_MIN\_LIMIT register (address 2Dh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B3_MIN_LIMIT						
Reset	0	0	0	0	1	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 102. BUCK3OUT\_MIN\_LIMIT register (address 2Dh) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B3_MIN_LIMIT	BUCK3 output voltage minimum limit Programmable from 0.60 V to 2.1875 V in 12.5 mV steps <b>000 1000</b> — 0.7 V (default) See <a href="#">Table 107</a>

### 8.2.43 BUCK4CTRL

BUCK4 control register for Active discharge, FPWM and Enable.

Table 103. BUCK4CTRL register (address 2Eh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD		B4_LPMODE		B4_AD	B4_FPWM	B4_ENMODE	
Reset	0	0	1	1	1	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

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Table 104. BUCK4CTRL register (address 2Eh) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Reserved
5 to 4	B4_LPMODE	BUCK4 power mode <b>00</b> — Automatic transition mode <b>01</b> — Low power mode at STANDBY mode and DPSTANDBY mode <b>10</b> — Low power mode at DPSTANDBY mode <b>11</b> — Normal mode (default)
3	B4_AD	Buck4 Active discharge <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
2	B4_FPWM	Forced PWM mode <b>0</b> — Automatic PFM and PWM mode transition (default) <b>1</b> — Forced PWM mode
1 to 0	B4_ENMODE	Buck4 enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.44 BUCK4OUT

BUCK4 output voltage configuration register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 105. BUCK4OUT register (address 2Fh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD	B4_OUT						
Reset <sup>[1]</sup>	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

[1] The reset value depends on the specific otp version as shown in [Table 106](#).

Table 106. BUCK4OUT register (address 2Fh) bit descriptions

Bit	Symbol	Description
7	RSVD	Reserved
6 to 0	B4_OUT	BUCK4 Output voltage Programmable from 0.60 V to 3.4 V in 25 mV steps <b>Note:</b> PCA9460A and PCA9450B: 001 0100b (1.1 V), PCA9460C: 001 1000b (1.2 V) See <a href="#">Table 108</a>

Table 107. BUCK2, BUCK3 Output voltage table

Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
0x00	0.6000 V	0x20	1.0000 V	0x40	1.4000 V	0x60	1.8000 V
0x01	0.6125 V	0x21	1.0125 V	0x41	1.4125 V	0x61	1.8125 V
0x02	0.6250 V	0x22	1.0250 V	0x42	1.4250 V	0x62	1.8250 V
0x03	0.6375 V	0x23	1.0375 V	0x43	1.4375 V	0x63	1.8375 V



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Table 107. BUCK2, BUCK3 Output voltage table...continued

Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
0x04	0.6500 V	0x24	1.0500 V	0x44	1.4500 V	0x64	1.8500 V
0x05	0.6625 V	0x25	1.0625 V	0x45	1.4625 V	0x65	1.8625 V
0x06	0.6750 V	0x26	1.0750 V	0x46	1.4750 V	0x66	1.8750 V
0x07	0.6875 V	0x27	1.0875 V	0x47	1.4875 V	0x67	1.8875 V
0x08	0.7000 V	0x28	1.1000 V	0x48	1.5000 V	0x68	1.9000 V
0x09	0.7125 V	0x29	1.1125 V	0x49	1.5125 V	0x69	1.9125 V
0x0A	0.7250 V	0x2A	1.1250 V	0x4A	1.5250 V	0x6A	1.9250 V
0x0B	0.7375 V	0x2B	1.1375 V	0x4B	1.5375 V	0x6B	1.9375 V
0x0C	0.7500 V	0x2C	1.1500 V	0x4C	1.5500 V	0x6C	1.9500 V
0x0D	0.7625 V	0x2D	1.1625 V	0x4D	1.5625 V	0x6D	1.9625 V
0x0E	0.7750 V	0x2E	1.1750 V	0x4E	1.5750 V	0x6E	1.9750 V
0x0F	0.7875 V	0x2F	1.1875 V	0x4F	1.5875 V	0x6F	1.9875 V
0x10	0.8000 V	0x30	1.2000 V	0x50	1.6000 V	0x70	2.0000 V
0x11	0.8125 V	0x31	1.2125 V	0x51	1.6125 V	0x71	2.0125 V
0x12	0.8250 V	0x32	1.2250 V	0x52	1.6250 V	0x72	2.0250 V
0x13	0.8375 V	0x33	1.2375 V	0x53	1.6375 V	0x73	2.0375 V
0x14	0.8500 V	0x34	1.2500 V	0x54	1.6500 V	0x74	2.0500 V
0x15	0.8625 V	0x35	1.2625 V	0x55	1.6625 V	0x75	2.0625 V
0x16	0.8750 V	0x36	1.2750 V	0x56	1.6750 V	0x76	2.0750 V
0x17	0.8875 V	0x37	1.2875 V	0x57	1.6875 V	0x77	2.0875 V
0x18	0.9000 V	0x38	1.3000 V	0x58	1.7000 V	0x78	2.1000 V
0x19	0.9125 V	0x39	1.3125 V	0x59	1.7125 V	0x79	2.1125 V
0x1A	0.9250 V	0x3A	1.3250 V	0x5A	1.7250 V	0x7A	2.1250 V
0x1B	0.9375 V	0x3B	1.3375 V	0x5B	1.7375 V	0x7B	2.1375 V
0x1C	0.9500 V	0x3C	1.3500 V	0x5C	1.7500 V	0x7C	2.1500 V
0x1D	0.9625 V	0x3D	1.3625 V	0x5D	1.7625 V	0x7D	2.1625 V
0x1E	0.9750 V	0x3E	1.3750 V	0x5E	1.7750 V	0x7E	2.1750 V
0x1F	0.9875 V	0x3F	1.3875 V	0x5F	1.7875 V	0x7F	2.1875 V

Table 108. BUCK1, BUCK4 Output voltage table

Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
0x00	0.600 V	0x20	1.400 V	0x40	2.200 V	0x60	3.000 V
0x01	0.625 V	0x21	1.425 V	0x41	2.225 V	0x61	3.025 V
0x02	0.650 V	0x22	1.450 V	0x42	2.250 V	0x62	3.050 V
0x03	0.675 V	0x23	1.475 V	0x43	2.275 V	0x63	3.075 V
0x04	0.700 V	0x24	1.500 V	0x44	2.300 V	0x64	3.100 V

Table 108. BUCK1, BUCK4 Output voltage table...continued

Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
0x05	0.725 V	0x25	1.525 V	0x45	2.325 V	0x65	3.125 V
0x06	0.750 V	0x26	1.550 V	0x46	2.350 V	0x66	3.150 V
0x07	0.775 V	0x27	1.575 V	0x47	2.375 V	0x67	3.175 V
0x08	0.800 V	0x28	1.600 V	0x48	2.400 V	0x68	3.200 V
0x09	0.825 V	0x29	1.625 V	0x49	2.425 V	0x69	3.225 V
0x0A	0.850 V	0x2A	1.650 V	0x4A	2.450 V	0x6A	3.250 V
0x0B	0.875 V	0x2B	1.675 V	0x4B	2.475 V	0x6B	3.275 V
0x0C	0.900 V	0x2C	1.700 V	0x4C	2.500 V	0x6C	3.300 V
0x0D	0.925 V	0x2D	1.725 V	0x4D	2.525 V	0x6D	3.325 V
0x0E	0.950 V	0x2E	1.750 V	0x4E	2.550 V	0x6E	3.350 V
0x0F	0.975 V	0x2F	1.775 V	0x4F	2.575 V	0x6F	3.375 V
0x10	1.000 V	0x30	1.800 V	0x50	2.600 V	0x70	3.400 V
0x11	1.025 V	0x31	1.825 V	0x51	2.625 V	0x71	3.400 V
0x12	1.050 V	0x32	1.850 V	0x52	2.650 V	0x72	3.400 V
0x13	1.075 V	0x33	1.875 V	0x53	2.675 V	0x73	3.400 V
0x14	1.100 V	0x34	1.900 V	0x54	2.700 V	0x74	3.400 V
0x15	1.125 V	0x35	1.925 V	0x55	2.725 V	0x75	3.400 V
0x16	1.150 V	0x36	1.950 V	0x56	2.750 V	0x76	3.400 V
0x17	1.175 V	0x37	1.975 V	0x57	2.775 V	0x77	3.400 V
0x18	1.200 V	0x38	2.000 V	0x58	2.800 V	0x78	3.400 V
0x19	1.225 V	0x39	2.025 V	0x59	2.825 V	0x79	3.400 V
0x1A	1.250 V	0x3A	2.050 V	0x5A	2.850 V	0x7A	3.400 V
0x1B	1.275 V	0x3B	2.075 V	0x5B	2.875 V	0x7B	3.400 V
0x1C	1.300 V	0x3C	2.100 V	0x5C	2.900 V	0x7C	3.400 V
0x1D	1.325 V	0x3D	2.125 V	0x5D	2.925 V	0x7D	3.400 V
0x1E	1.350 V	0x3E	2.150 V	0x5E	2.950 V	0x7E	3.400 V
0x1F	1.375 V	0x3F	2.175 V	0x5F	2.975 V	0x7F	3.400 V

## 8.2.45 LDO1\_CFG

LDO1 enable control and active discharge resistor configuration register

Table 109. LDO1\_CFG register (address 30h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	L1_CSEL		L1_LLSEL		L1_LPMODE		L1_ENMODE	
Reset	1	0	0	1	1	1	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 110. LDO1\_CFG register (address 30h) bit descriptions

Bit	Symbol	Description
7 to 6	L1_CSEL	Total Output capacitor selection <b>00</b> — Setting for Cout < 5 µF <b>01</b> — Setting for Cout < 5 µF <b>10 and 11</b> — Auto Cout detection (default)
5 to 4	L1_LLSEL	Output trace resistance compensation <b>00</b> — No Compensation <b>01</b> — 15 mΩ (default) <b>10</b> — 30 mΩ <b>11</b> — 45 mΩ
3 to 2	L1_LPMODE	LDO1 power mode <b>00</b> — Low power mode at RUN state <b>01</b> — Low power mode at STANDBY mode and DPSTANDBY mode <b>10</b> — Low power mode at DPSTANDBY mode <b>11</b> — Normal mode (default)
1 to 0	L1_ENMODE	LDO1 Enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.46 LDO1\_OUT

LDO1 output voltage register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 111. LDO1\_OUT register (address 31h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	L1_AD	L1_INL1_MDET	L1_INL1_VSEL	L1_OUT				
Reset	1	0	0					
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 112. LDO1\_OUT register (address 31h) bit descriptions

Bit	Symbol	Description
7	L1_AD	LDO1 Active discharge enable <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
6	L1_INL1_MDET	Manual detection for INL1 supply <b>0</b> — Auto detection (default) <b>1</b> — Manual configuration
5	L1_INL1_VSEL	INL1 voltage selection, effective only when L1_INL1_MDET = 1b <b>0</b> — (VSYS – VINL1) ≤ 0.7 (default) <b>1</b> — (VSYS – VINL1) > 0.7
4 to 0	L1_OUT	LDO1 output voltage Programmable from 0.6 V to 1.95 V in 50 mV steps See <a href="#">Table 113</a> <sup>[1]</sup>

[1] • PCA9460A: 0 1010 (1.1 V)  
 • PCA9460B: 0 0000 (0.6 V)  
 • PCA9460C: 0 1100 (1.2 V)

Table 113. L1\_OUT values

0x00 : 0.60 V	0x8 : 1.00 V	0x10 : 1.40 V	0x18 : 1.80 V
0x01 : 0.65 V	0x9 : 1.05 V	0x11 : 1.45 V	0x19 : 1.85 V
0x02 : 0.70 V	<b>0xA : 1.10 V</b>	0x12 : 1.50 V	0x1A : 1.90 V
0x03 : 0.75 V	0xB : 1.15 V	0x13 : 1.55 V	0x1B : 1.95 V
0x04 : 0.80 V	<b>0xC : 1.20 V</b>	0x14 : 1.60 V	0x1C : 1.95 V
0x05 : 0.85 V	0xD : 1.25 V	0x15 : 1.65 V	0x1D : 1.95 V
0x06 : 0.90 V	0xE : 1.30 V	0x16 : 1.70 V	0x1E : 1.95 V
0x07 : 0.95 V	0xF : 1.35 V	0x17 : 1.75 V	0x1F : 1.95 V

### 8.2.47 LDO2\_CFG

LDO2 enable control and active discharge resistor configuration register

Table 114. LDO2\_CFG register (address 32h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L2_AD	RSVD		L2_ENMODE	
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 115. LDO2\_CFG register (address 32h) bit descriptions

Bit	Symbol	Description
7 to 5	L4_FLT_M	Reserved
4	L1_FLT_M	LDO2 Active discharge enable <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
3 to 2	B4_FLT_M	Reserved
1 to 0	B2_FLT_M	LDO2 Enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

### 8.2.48 LDO2\_OUT\_L

LDO2 output voltage register when LDO2\_VSEL is low. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 116. LDO2\_OUT\_L register (address 33h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L2_OUT_L				
Reset	0	0	Reset value is 11 0010 (3.3 V) <a href="#">Table 118</a>					
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

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Table 117. LDO2\_OUT\_L register (address 33h) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Total Output capacitor selection <b>00</b> — Setting for Cout < 5 µF <b>01</b> — Setting for Cout < 5 µF <b>10 and 11</b> — Auto Cout detection (default)
5 to 0	L2_OUT_L	LDO2 output voltage when LDO2_VSEL = Low Programmable from 0.8 V to 3.3 V in 50 mV steps <b>11 0010</b> — 3.3 V (default) See <a href="#">Table 118</a>

Table 118. L2\_OUT\_L values

0x00 : 0.80 V	0x10 : 1.60 V	0x20 : 2.40 V	0x30 : 3.20 V
0x01 : 0.85 V	0x11 : 1.65 V	0x21 : 2.45 V	0x31 : 3.25 V
0x02 : 0.90 V	0x12 : 1.70 V	0x22 : 2.50 V	<b>0x32 : 3.30 V</b>
0x03 : 0.95 V	0x13 : 1.75 V	0x23 : 2.55 V	0x33 : 3.30 V
0x04 : 1.00 V	0x14 : 1.80 V	0x24 : 2.60 V	0x34 : 3.30 V
0x05 : 1.05 V	0x15 : 1.85 V	0x25 : 2.65 V	0x35 : 3.30 V
0x06 : 1.10 V	0x16 : 1.90 V	0x26 : 2.70 V	0x36 : 3.30 V
0x07 : 1.15 V	0x17 : 1.95 V	0x27 : 2.75 V	0x37 : 3.30 V
0x08 : 1.20 V	0x18 : 2.00 V	0x28 : 2.80 V	0x38 : 3.30 V
0x09 : 1.25 V	0x19 : 2.05 V	0x29 : 2.85 V	0x39 : 3.30 V
0x0A : 1.30 V	0x1A : 2.10 V	0x2A : 2.90 V	0x3A : 3.30 V
0x0B : 1.35 V	0x1B : 2.15 V	0x2B : 2.95 V	0x3B : 3.30 V
0x0C : 1.40 V	0x1C : 2.20 V	0x2C : 3.00 V	0x3C : 3.30 V
0x0D : 1.45 V	0x1D : 2.25 V	0x2D : 3.05 V	0x3D : 3.30 V
0x0E : 1.50 V	0x1E : 2.30 V	0x2E : 3.10 V	0x3E : 3.30 V
0x0F : 1.55 V	0x1F : 2.35 V	0x2F : 3.15 V	0x3F : 3.30 V

8.2.49 LDO2\_OUT\_H

LDO2 output voltage register when LDO2\_VSEL is High. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 119. LDO2\_OUT\_H register (address 34h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L2_OUT_H				
Reset	0	0	0	1	0	1	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 120. LDO2\_OUT\_H register (address 34h) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Reserved
5 to 0	L2_OUT_H	LDO2 output voltage when LDO2_VSEL = High Programmable from 0.8 V to 3.3 V in 50 mV steps <b>01 0100</b> — 1.8 V (default) See <a href="#">Table 118</a>

### 8.2.50 LDO3\_CFG

LDO3 enable control and active discharge resistor configuration register

Table 121. LDO3\_CFG register (address 35h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L3_AD	RSVD		L3_ENMODE	
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 122. LDO3\_CFG register (address 35h) bit descriptions

Bit	Symbol	Description
7 to 5	RSVD	Reserved
4	L3_AD	LDO3 Active discharge enable <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
3 to 2	RSVD	Reserved
1 to 0	L3_ENMODE	LDO3 Enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

### 8.2.51 LDO3\_OUT

LDO3 output voltage register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 123. LDO3\_OUT register (address 36h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L3_OUT				
Reset	0	0	1	1	0	0	1	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 124. LDO3\_OUT register (address 36h) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Reserved
5 to 0	L3_AD	LDO3 output voltage Programmable from 0.8 V to 3.3 V in 50 mV steps

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Table 124. LDO3\_OUT register (address 36h) bit descriptions...continued

Bit	Symbol	Description
		<b>11 0010</b> — 3.3 V (default) See <a href="#">Table 125</a>

Table 125. L3\_OUT values

0x00 : 0.80 V	0x10 : 1.60 V	0x20 : 2.40 V	0x30 : 3.20 V
0x01 : 0.85 V	0x11 : 1.65 V	0x21 : 2.45 V	0x31 : 3.25 V
0x02 : 0.90 V	0x12 : 1.70 V	0x22 : 2.50 V	<b>0x32 : 3.30 V</b>
0x03 : 0.95 V	0x13 : 1.75 V	0x23 : 2.55 V	0x33 : 3.30 V
0x04 : 1.00 V	0x14 : 1.80 V	0x24 : 2.60 V	0x34 : 3.30 V
0x05 : 1.05 V	0x15 : 1.85 V	0x25 : 2.65 V	0x35 : 3.30 V
0x06 : 1.10 V	0x16 : 1.90 V	0x26 : 2.70 V	0x36 : 3.30 V
0x07 : 1.15 V	0x17 : 1.95 V	0x27 : 2.75 V	0x37 : 3.30 V
0x08 : 1.20 V	0x18 : 2.00 V	0x28 : 2.80 V	0x38 : 3.30 V
0x09 : 1.25 V	0x19 : 2.05 V	0x29 : 2.85 V	0x39 : 3.30 V
0x0A : 1.30 V	0x1A : 2.10 V	0x2A : 2.90 V	0x3A : 3.30 V
0x0B : 1.35 V	0x1B : 2.15 V	0x2B : 2.95 V	0x3B : 3.30 V
0x0C : 1.40 V	0x1C : 2.20 V	0x2C : 3.00 V	0x3C : 3.30 V
0x0D : 1.45 V	0x1D : 2.25 V	0x2D : 3.05 V	0x3D : 3.30 V
0x0E : 1.50 V	0x1E : 2.30 V	0x2E : 3.10 V	0x3E : 3.30 V
0x0F : 1.55 V	0x1F : 2.35 V	0x2F : 3.15 V	0x3F : 3.30 V

8.2.52 LDO4\_CFG

LDO4 enable control and active discharge resistor configuration register

Table 126. LDO4\_CFG register (address 37h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L4_AD	RSVD		L4_ENMODE	
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 127. LDO4\_CFG register (address 37h) bit descriptions

Bit	Symbol	Description
7 to 5	RSVD	Reserved
4	L4_AD	LDO4 Active discharge enable <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
3 to 2	RSVD	Reserved
1 to 0	L4_ENMODE	LDO4 Enable mode <b>00</b> — OFF

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Table 127. LDO4\_CFG register (address 37h) bit descriptions...continued

Bit	Symbol	Description
		<b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.53 LDO4\_OUT

LDO4 output voltage register. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 128. LDO4\_OUT register (address 38h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	RSVD			L4_OUT				
Reset	0	0	0	1	0	1	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 129. LDO4\_OUT register (address 38h) bit descriptions

Bit	Symbol	Description
7 to 6	RSVD	Reserved
5 to 0	L4_OUT	LDO4 output voltage Programmable from 0.8 V to 3.3 V in 50 mV steps <b>01 0100</b> — 1.8 V (default) See <a href="#">Table 130</a>

Table 130. L4\_OUT values

0x00 : 0.80 V	0x10 : 1.60 V	0x20 : 2.40 V	0x30 : 3.20 V
0x01 : 0.85 V	0x11 : 1.65 V	0x21 : 2.45 V	0x31 : 3.25 V
0x02 : 0.90 V	0x12 : 1.70 V	0x22 : 2.50 V	0x32 : 3.30 V
0x03 : 0.95 V	0x13 : 1.75 V	0x23 : 2.55 V	0x33 : 3.30 V
0x04 : 1.00 V	<b>0x14 : 1.80 V</b>	0x24 : 2.60 V	0x34 : 3.30 V
0x05 : 1.05 V	0x15 : 1.85 V	0x25 : 2.65 V	0x35 : 3.30 V
0x06 : 1.10 V	0x16 : 1.90 V	0x26 : 2.70 V	0x36 : 3.30 V
0x07 : 1.15 V	0x17 : 1.95 V	0x27 : 2.75 V	0x37 : 3.30 V
0x08 : 1.20 V	0x18 : 2.00 V	0x28 : 2.80 V	0x38 : 3.30 V
0x09 : 1.25 V	0x19 : 2.05 V	0x29 : 2.85 V	0x39 : 3.30 V
0x0A : 1.30 V	0x1A : 2.10 V	0x2A : 2.90 V	0x3A : 3.30 V
0x0B : 1.35 V	0x1B : 2.15 V	0x2B : 2.95 V	0x3B : 3.30 V
0x0C : 1.40 V	0x1C : 2.20 V	0x2C : 3.00 V	0x3C : 3.30 V
0x0D : 1.45 V	0x1D : 2.25 V	0x2D : 3.05 V	0x3D : 3.30 V
0x0E : 1.50 V	0x1E : 2.30 V	0x2E : 3.10 V	0x3E : 3.30 V
0x0F : 1.55 V	0x1F : 2.35 V	0x2F : 3.15 V	0x3F : 3.30 V



8.2.54 LDOSNVS\_CFG

LDO\_SNVS control register for enable and voltage. This register is protected by Lock key, 0x4E register should be written with unlock key before updating this register.

Table 131. LDOSNVS\_CFG register (address 39h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LSNVS_AD	LS_ENMODE	L_SNVS_OUT					
Reset	1	1	1	0	1	1	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 132. LDOSNVS\_CFG register (address 39h) bit descriptions

Bit	Symbol	Description
7	LSNVS_AD	SNVS LDO Active discharge enable <b>0</b> — Always disable Active discharge resistor <b>1</b> — Enable Active discharge resistor when regulator is OFF (default)
6	LS_ENMODE	LDO_SNVS Enable mode <b>0</b> — OFF <b>1</b> — Always ON (default)
5 to 0	L_SNVS_OUT	LDO_SNVS output voltage Programmable from 0.8 V to 3.3 V in 50 mV steps <b>10 1100</b> — 3.0 V (default) See <a href="#">Table 133</a>

Table 133. L\_SNVS\_OUT values

0x00 : 0.80 V	0x10 : 1.60 V	0x20 : 2.40 V	0x30 : 3.20 V
0x01 : 0.85 V	0x11 : 1.65 V	0x21 : 2.45 V	0x31 : 3.25 V
0x02 : 0.90 V	0x12 : 1.70 V	0x22 : 2.50 V	0x32 : 3.30 V
0x03 : 0.95 V	0x13 : 1.75 V	0x23 : 2.55 V	0x33 : 3.30 V
0x04 : 1.00 V	0x14 : 1.80 V	0x24 : 2.60 V	0x34 : 3.30 V
0x05 : 1.05 V	0x15 : 1.85 V	0x25 : 2.65 V	0x35 : 3.30 V
0x06 : 1.10 V	0x16 : 1.90 V	0x26 : 2.70 V	0x36 : 3.30 V
0x07 : 1.15 V	0x17 : 1.95 V	0x27 : 2.75 V	0x37 : 3.30 V
0x08 : 1.20 V	0x18 : 2.00 V	0x28 : 2.80 V	0x38 : 3.30 V
0x09 : 1.25 V	0x19 : 2.05 V	0x29 : 2.85 V	0x39 : 3.30 V
0x0A : 1.30 V	0x1A : 2.10 V	0x2A : 2.90 V	0x3A : 3.30 V
0x0B : 1.35 V	0x1B : 2.15 V	0x2B : 2.95 V	0x3B : 3.30 V
0x0C : 1.40 V	0x1C : 2.20 V	<b>0x2C : 3.00 V</b>	0x3C : 3.30 V
0x0D : 1.45 V	0x1D : 2.25 V	0x2D : 3.05 V	0x3D : 3.30 V
0x0E : 1.50 V	0x1E : 2.30 V	0x2E : 3.10 V	0x3E : 3.30 V
0x0F : 1.55 V	0x1F : 2.35 V	0x2F : 3.15 V	0x3F : 3.30 V

### 8.2.55 LSW1\_CTRL

Load switch 1 configuration register

Table 134. LSW1\_CTRL register (address 40h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LSW1_CFG	RSVD		LSW1_AD	RSVD		LSW1_EN	
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 135. LSW1\_CTRL register (address 40h) bit descriptions

Bit	Symbol	Description
7	LSW1_CFG	Load SW 1 Configuration <b>0</b> — Load switch (default) <b>1</b> — LED driver
6 to 5	RSVD	Reserved
4	LSW1_AD	Load SW 1 active discharge, if it is configured to LED, active discharge resistor is always off. <b>0</b> — Disabled <b>1</b> — Enabled when Load SW1 is off (default)
3 to 2	RSVD	Reserved
1 to 0	LSW1_EN	Load SW 1 Enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

### 8.2.56 LSW2\_CTRL

Load switch 2 configuration register

Table 136. LSW2\_CTRL register (address 41h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LSW2_CFG	RSVD		LSW2_AD	RSVD		LSW2_EN	
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 137. LSW2\_CTRL register (address 41h) bit descriptions

Bit	Symbol	Description
7	LSW2_CFG	Load SW 2 Configuration <b>0</b> — Load switch (default) <b>1</b> — LED driver
6 to 5	RSVD	Reserved
4	LSW2_AD	Load SW 2 active discharge, if it is configured to LED, active discharge resistor is always off. <b>0</b> — Disabled <b>1</b> — Enabled when Load SW1 is off (default)
3 to 2	RSVD	Reserved
1 to 0	LSW2_EN	Load SW 2 Enable mode

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Table 137. LSW2\_CTRL register (address 41h) bit descriptions...continued

Bit	Symbol	Description
		<b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.57 LSW3\_CTRL

Load switch 3 configuration register

Table 138. LSW3\_CTRL register (address 42h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LSW3_CFG	RSVD			LSW3_AD	RSVD		LSW3_EN
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 139. LSW3\_CTRL register (address 42h) bit descriptions

Bit	Symbol	Description
7	LSW3_CFG	Load SW 3 Configuration <b>0</b> — Load switch (default) <b>1</b> — LED driver
6 to 5	RSVD	Reserved
4	LSW3_AD	Load SW 3 active discharge, if it is configured to LED, active discharge resistor is always off. <b>0</b> — Disabled <b>1</b> — Enabled when Load SW1 is off (default)
3 to 2	RSVD	Reserved
1 to 0	LSW3_EN	Load SW 3 Enable mode <b>00</b> — OFF <b>01</b> — ON at RUN State (default) <b>10</b> — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY <b>11</b> — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.58 LSW4\_CTRL

Load switch 4 configuration register

Table 140. LSW4\_CTRL register (address 43h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LSW4_CFG	RSVD			LSW4_AD	RSVD		LSW4_EN
Reset	0	0	0	1	0	0	0	1
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 141. LSW4\_CTRL register (address 43h) bit descriptions

Bit	Symbol	Description
7	LSW4_CFG	Load SW 4 Configuration <b>0</b> — Load switch (default)

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Table 141. LSW4\_CTRL register (address 43h) bit descriptions...continued

Bit	Symbol	Description
		1 — LED driver
6 to 5	RSVD	Reserved
4	LSW4_AD	Load SW 4 active discharge, if it is configured to LED, active discharge resistor is always off. 0 — Disabled 1 — Enabled when Load SW1 is off (default)
3 to 2	RSVD	Reserved
1 to 0	LSW4_EN	Load SW 4 Enable mode 00 — OFF 01 — ON at RUN State (default) 10 — ON at ACTIVE mode or STANDBY mode, OFF at DPSTANDBY 11 — ON at ACTIVE mode, OFF at STANDBY or DPSTANDBY

8.2.59 LED1\_CTRL

LED1 Enable and brightness configuration

Table 142. LED1\_CTRL register (address 44h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LED1_EN		RSVD	LED1_BRT				
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 143. LED1\_CTRL register (address 44h) bit descriptions

Bit	Symbol	Description
7 to 6	LED1_EN	Load SW1 LED enable mode only when LSW1_CFG is set to 01b. 00 — OFF (default) 01 — Enable with Constant current 10 — Enable with Pattern 1 BLINK mode 11 — Enable with Pattern 2 BLINK mode
5	RSVD	Reserved
4 to 0	LED1_BRT	LED1 brightness setting Programmable from 0.625 mA to 20 mA in 0.625 mA steps See <a href="#">Table 144</a>

Table 144. LED1\_BRT values

0x00 : 0.625 mA	0x08 : 5.625 mA	0x10 : 10.625 mA	0x18 : 15.625 mA
0x01 : 1.250 mA	0x09 : 6.250 mA	0x11 : 11.250 mA	0x19 : 16.250 mA
0x02 : 1.875 mA	0x0A : 6.875 mA	0x12 : 11.875 mA	0x1A : 16.875 mA
0x03 : 2.500 mA	0x0B : 7.500 mA	0x13 : 12.500 mA	0x1B : 17.500 mA
0x04 : 3.125 mA	0x0C : 8.125 mA	0x14 : 13.125 mA	0x1C : 18.125 mA
0x05 : 3.750 mA	0x0D : 8.750 mA	0x15 : 13.750 mA	0x1D : 18.750 mA
0x06 : 4.375 mA	0x0E : 9.375 mA	0x16 : 14.375 mA	0x1E : 19.375 mA
0x07 : 5.000 mA	0x0F : 10.000 mA	0x17 : 15.000 mA	0x1F : 20.000 mA

### 8.2.60 LED2\_CTRL

LED2 Enable and brightness configuration

Table 145. LED2\_CTRL register (address 45h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LED2_EN		RSVD	LED2_BRT				
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 146. LED2\_CTRL register (address 45h) bit descriptions

Bit	Symbol	Description
7 to 6	LED2_EN	Load SW2 LED enable mode only when LSW2_CFG is set to 01b. <b>00</b> — OFF (default) <b>01</b> — Enable with Constant current <b>10</b> — Enable with Pattern 1 BLINK mode <b>11</b> — Enable with Pattern 2 BLINK mode
5	RSVD	Reserved
4 to 0	LED2_BRT	LED2 brightness setting Programmable from 0.625 mA to 20 mA in 0.625 mA steps See <a href="#">Table 147</a>

Table 147. LED2\_BRT values

<b>0x00 : 0.625 mA</b>	0x08 : 5.625 mA	0x10 : 10.625 mA	0x18 : 15.625 mA
0x01 : 1.250 mA	0x09 : 6.250 mA	0x11 : 11.250 mA	0x19 : 16.250 mA
0x02 : 1.875 mA	0x0A : 6.875 mA	0x12 : 11.875 mA	0x1A : 16.875 mA
0x03 : 2.500 mA	0x0B : 7.500 mA	0x13 : 12.500 mA	0x1B : 17.500 mA
0x04 : 3.125 mA	0x0C : 8.125 mA	0x14 : 13.125 mA	0x1C : 18.125 mA
0x05 : 3.750 mA	0x0D : 8.750 mA	0x15 : 13.750 mA	0x1D : 18.750 mA
0x06 : 4.375 mA	0x0E : 9.375 mA	0x16 : 14.375 mA	0x1E : 19.375 mA
0x07 : 5.000 mA	0x0F : 10.000 mA	0x17 : 15.000 mA	0x1F : 20.000 mA

### 8.2.61 LED3\_CTRL

LED3 Enable and brightness configuration

Table 148. LED3\_CTRL register (address 46h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LED3_EN		RSVD	LED3_BRT				
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 149. LED3\_CTRL register (address 46h) bit descriptions

Bit	Symbol	Description
7 to 6	LED3_EN	Load SW3 LED enable mode only when LSW3_CFG is set to 01b. <b>00</b> — OFF (default) <b>01</b> — Enable with Constant current <b>10</b> — Enable with Pattern 1 BLINK mode <b>11</b> — Enable with Pattern 2 BLINK mode
5	RSVD	Reserved
4 to 0	LED3_BRT	LED3 brightness setting Programmable from 0.625 mA to 20 mA in 0.625 mA steps See <a href="#">Table 150</a>

Table 150. LED3\_BRT values

<b>0x00 : 0.625 mA</b>	0x08 : 5.625 mA	0x10 : 10.625 mA	0x18 : 15.625 mA
0x01 : 1.250 mA	0x09 : 6.250 mA	0x11 : 11.250 mA	0x19 : 16.250 mA
0x02 : 1.875 mA	0x0A : 6.875 mA	0x12 : 11.875 mA	0x1A : 16.875 mA
0x03 : 2.500 mA	0x0B : 7.500 mA	0x13 : 12.500 mA	0x1B : 17.500 mA
0x04 : 3.125 mA	0x0C : 8.125 mA	0x14 : 13.125 mA	0x1C : 18.125 mA
0x05 : 3.750 mA	0x0D : 8.750 mA	0x15 : 13.750 mA	0x1D : 18.750 mA
0x06 : 4.375 mA	0x0E : 9.375 mA	0x16 : 14.375 mA	0x1E : 19.375 mA
0x07 : 5.000 mA	0x0F : 10.000 mA	0x17 : 15.000 mA	0x1F : 20.000 mA

### 8.2.62 LED4\_CTRL

LED4 Enable and brightness configuration

Table 151. LED4\_CTRL register (address 47h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LED4_EN		RSVD	LED4_BRT				
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 152. LED4\_CTRL register (address 47h) bit descriptions

Bit	Symbol	Description
7 to 6	LED4_EN	Load SW4 LED enable mode only when LSW4_CFG is set to 01b. <b>00</b> — OFF (default) <b>01</b> — Enable with Constant current <b>10</b> — Enable with Pattern 1 BLINK mode <b>11</b> — Enable with Pattern 2 BLINK mode
5	RSVD	Reserved
4 to 0	LED4_BRT	LED4 brightness setting Programmable from 0.625 mA to 20 mA in 0.625 mA steps See <a href="#">Table 153</a>

Table 153. LED4\_BRT values

0x00 : 0.625 mA	0x08 : 5.625 mA	0x10 : 10.625 mA	0x18 : 15.625 mA
0x01 : 1.250 mA	0x09 : 6.250 mA	0x11 : 11.250 mA	0x19 : 16.250 mA
0x02 : 1.875 mA	0x0A : 6.875 mA	0x12 : 11.875 mA	0x1A : 16.875 mA
0x03 : 2.500 mA	0x0B : 7.500 mA	0x13 : 12.500 mA	0x1B : 17.500 mA
0x04 : 3.125 mA	0x0C : 8.125 mA	0x14 : 13.125 mA	0x1C : 18.125 mA
0x05 : 3.750 mA	0x0D : 8.750 mA	0x15 : 13.750 mA	0x1D : 18.750 mA
0x06 : 4.375 mA	0x0E : 9.375 mA	0x16 : 14.375 mA	0x1E : 19.375 mA
0x07 : 5.000 mA	0x0F : 10.000 mA	0x17 : 15.000 mA	0x1F : 20.000 mA

### 8.2.63 LED\_P1\_RAMP

Pattern 1 LED ramp up down configuration

Table 154. LED\_P1\_RAMP register (address 48h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	P1_UP_STEP		P1_UP_DLY		P1_DN_STEP		P1_DN_DLY	
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 155. LED\_P1\_RAMP register (address 48h) bit descriptions

Bit	Symbol	Description
7 to 6	P1_UP_STEP	Pattern 1 LED Ramp Up PWM duty step size from 0 % to 100 % <b>00</b> — 128 steps (default) <b>01</b> — 64 steps <b>10</b> — 32 steps <b>11</b> — 16 step
5 to 4	P1_UP_DLY	Pattern 1 LED Ramp Up delay per step <b>00</b> — 4.096 ms (default) <b>01</b> — 8.192 ms <b>10</b> — 12.288 ms <b>11</b> — 16.384 ms
3 to 2	P1_DN_STEP	Pattern 1 LED Ramp Down PWM duty step size from 0 % to 100 % <b>00</b> — 128 steps (default) <b>01</b> — 64 steps <b>10</b> — 32 steps <b>11</b> — 16 step
1 to 0	P1_DN_DLY	Pattern 1 LED Ramp Down delay per step <b>00</b> — 4.096 ms (default) <b>01</b> — 8.192 ms <b>10</b> — 12.288 ms <b>11</b> — 16.384 ms

### 8.2.64 LED\_P1\_BLNK

Pattern 1 LED blink time configuration

Table 156. LED\_P1\_BLNK register (address 49h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LEDTON1				LEDTOFF1			
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 157. LED\_P1\_BLNK register (address 49h) bit descriptions

Bit	Symbol	Description
7 to 6	LEDTON1	Pattern 1 LED ON Time Settings See <a href="#">Table 158</a>
5 to 4	LEDTOFF1	Pattern 1 LED OFF Time Settings See <a href="#">Table 159</a>

Table 158. LEDTON1 values

<b>0x0 : 0.10 s</b>	0x4 : 0.50 s	0x8 : 1.50 s	0xC : 2.50 s
0x1 : 0.20 s	0x5 : 0.75 s	0x9 : 1.75 s	0xD : 2.75 s
0x2 : 0.30 s	0x6 : 1.00 s	0xA : 2.00 s	0xE : 3.00 s
0x3 : 0.40 s	0x7 : 1.25 s	0xB : 2.25 s	0xF : 3.25 s

Table 159. LEDTOFF1 values

<b>0x0 : 0.10 s</b>	0x4 : 0.50 s	0x8 : 1.50 s	0xC : 2.50 s
0x1 : 0.20 s	0x5 : 0.75 s	0x9 : 1.75 s	0xD : 2.75 s
0x2 : 0.30 s	0x6 : 1.00 s	0xA : 2.00 s	0xE : 3.00 s
0x3 : 0.40 s	0x7 : 1.25 s	0xB : 2.25 s	0xF : 3.25 s

### 8.2.65 LED\_P2\_RAMP

Pattern 2 LED ramp up down configuration

Table 160. LED\_P2\_RAMP register (address 4Ah) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	P2_UP_STEP		P2_UP_DLY		P2_DN_STEP		P2_DN_DLY	
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 161. LED\_P2\_RAMP register (address 4Ah) bit descriptions

Bit	Symbol	Description
7 to 6	P2_UP_STEP	Pattern 2 LED Ramp Up PWM duty step size from 0 % to 100 % <b>00</b> — 128 steps (default) <b>01</b> — 64 steps <b>10</b> — 32 steps <b>11</b> — 16 step



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Table 161. LED\_P2\_RAMP register (address 4Ah) bit descriptions...continued

Bit	Symbol	Description
5 to 4	P2_UP_DLY	Pattern 2 LED Ramp Up delay per step <b>00</b> — 4.096 ms (default) <b>01</b> — 8.192 ms <b>10</b> — 12.288 ms <b>11</b> — 16.384 ms
3 to 2	P2_DN_STEP	Pattern 2 LED Ramp Down PWM duty step size from 0 % to 100 % <b>00</b> — 128 steps (default) <b>01</b> — 64 steps <b>10</b> — 32 steps <b>11</b> — 16 step
1 to 0	P2_DN_DLY	Pattern 2 LED Ramp Down delay per step <b>00</b> — 4.096 ms (default) <b>01</b> — 8.192 ms <b>10</b> — 12.288 ms <b>11</b> — 16.384 ms

8.2.66 LED\_P2\_BLNK

Pattern 2 LED blink time configuration

Table 162. LED\_P2\_BLNK register (address 4Bh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	LEDTON2				LEDTOFF2			
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 163. LED\_P2\_BLNK register (address 4Bh) bit descriptions

Bit	Symbol	Description
7 to 4	LEDTON2	Pattern 2 LED ON Time Settings See <a href="#">Table 164</a>
3 to 0	LEDTOFF2	Pattern 2 LED OFF Time Settings See <a href="#">Table 165</a>

Table 164. LEDTON2

<b>0x0 : 0.10 s</b>	0x4 : 0.50 s	0x8 : 1.50 s	0xC : 2.50 s
0x1 : 0.20 s	0x5 : 0.75 s	0x9 : 1.75 s	0xD : 2.75 s
0x2 : 0.30 s	0x6 : 1.00 s	0xA : 2.00 s	0xE : 3.00 s
0x3 : 0.40 s	0x7 : 1.25 s	0xB : 2.25 s	0xF : 3.25 s

Table 165. LEDTOFF2

<b>0x0 : 0.10 s</b>	0x4 : 0.50 s	0x8 : 1.50 s	0xC : 2.50 s
0x1 : 0.20 s	0x5 : 0.75 s	0x9 : 1.75 s	0xD : 2.75 s

Table 165. LEDTOFF2...continued

0x2 : 0.30 s	0x6 : 1.00 s	0xA : 2.00 s	0xE : 3.00 s
0x3 : 0.40 s	0x7 : 1.25 s	0xB : 2.25 s	0xF : 3.25 s

### 8.2.67 REG\_LOCK

Output voltage configuration unlock key

Table 166. REG\_LOCK register (address 4Eh) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	UNLOCK_KEY							
Reset	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 167. REG\_LOCK register (address 4Eh) bit descriptions

Bit	Symbol	Description
7 to 0	UNLOCK_KEY	Unlock key is written to change regulator output configuration. <b>01011100</b> — Unlock regulator output configuration registers <b>Others</b> — Lock regulator output configuration registers

## 9 Application design-in information

### 9.1 Reference schematic

PCA9460 reference schematic with 8ULP is illustrated in [Figure 24](#).

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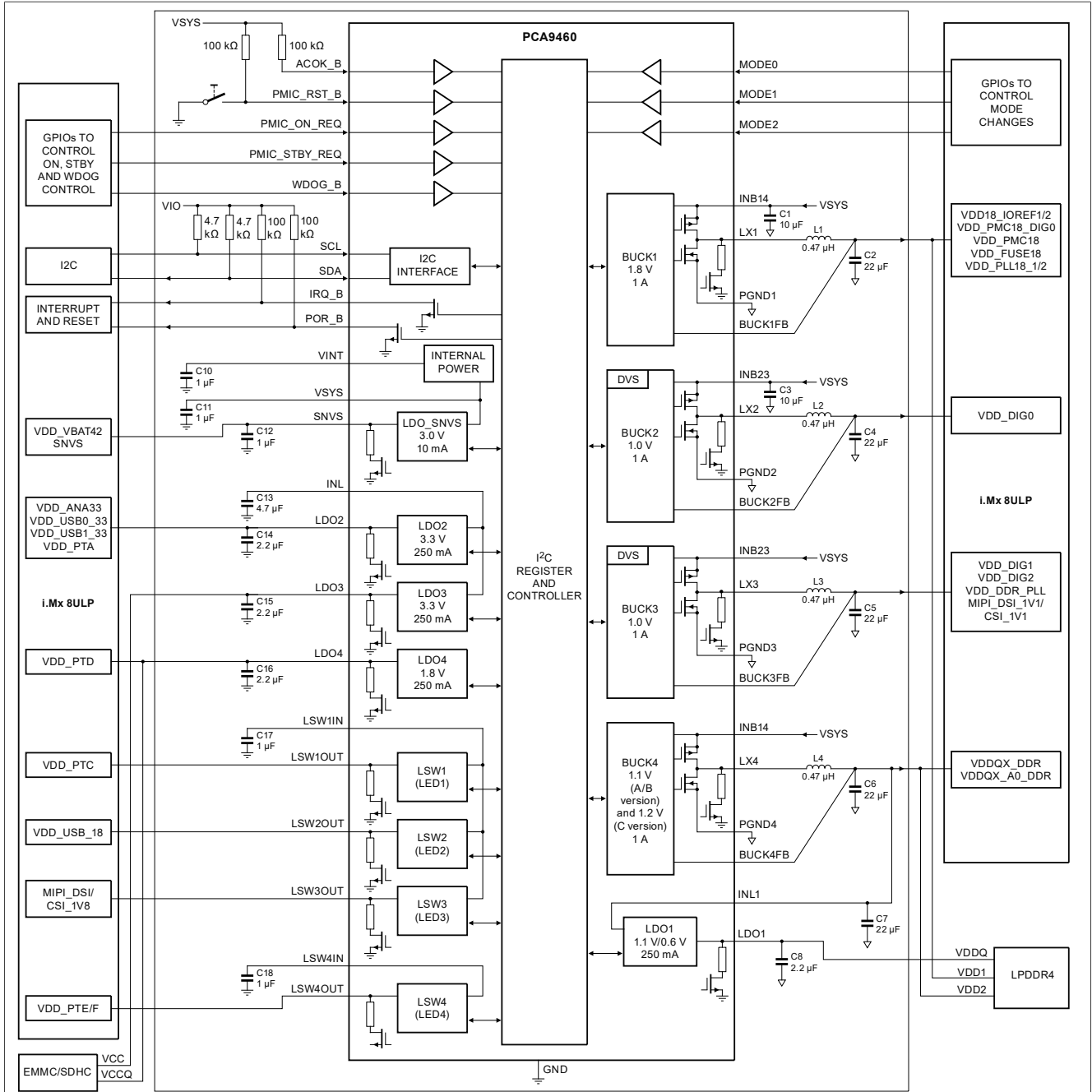


Figure 24. PCA9460 i.Mx 8ULP application schematic

9.1.1 External BOM in reference schematic

Table 168 shows external BOM in reference schematic

Table 168. External BOM

Ref	Block	Pin	Part number	Size [mm]	Value
L1	BUCK	LX1	WPN252012ER47MT	2012	0.47 μH

Table 168. External BOM...continued

Ref	Block	Pin	Part number	Size [mm]	Value
L2	BUCK	LX2	WPN252012ER47MT	2012	0.47 µH
L3	BUCK	LX3	WPN252012ER47MT	2012	0.47 µH
L4	BUCK	LX4	WPN252012ER47MT	2012	0.47 µH
C1	BUCK	INB14	GRM188R60J106ME	1608	10 µF
C2	BUCK	Buck Output	GRM158C80G226ME	1005	22 µF
C3	BUCK	INB23	GRM188R60J106ME	1608	10 µF
C4	BUCK	BUCK Output	GRM158C80G226ME	1005	22 µF
C5	BUCK	BUCK Output	GRM158C80G226ME	1005	22 µF
C6	BUCK	BUCK Output	GRM158C80G226ME	1005	22 µF
C7	LDO	INL1	GRM155R61C225KE	1005	2.2 µF
C8	LDO	LDO1	GRM155R61C225KE	1005	2.2 µF
C10	VINT	VINT	GRM155R61C105KA	1005	1 µF
C11	VSYS	VSYS	GRM155R61C105KA	1005	1 µF
C12	LDO	LDOSNVS	GRM155R61C105KA	1005	1 µF
C13	LDO	INL	GRM155R60J475ME	1005	4.7 µF
C14	LDO	LDO2	GRM155R61C225KE	1005	2.2 µF
C15	LDO	LDO3	GRM155R61C225KE	1005	2.2 µF
C16	LDO	LDO4	GRM155R61C225KE	1005	2.2 µF
C17	LSW	LSW1IN	GRM155R61C105KA	1005	1 µF
C18	LSW	LSW4IN	GRM155R61C105KA	1005	1 µF

## 9.2 Typical application

The PCA9460 devices have only a few design requirements. Use the following parameters for the design

- 1 µF bypass capacitor on VINT and VSYS, located as close as possible to those pins to ground
- Input capacitors must be present on the INB and INL supplies if used
- Output inductors and capacitors must be used on the outputs of the BUCK converters if used
- Output capacitors must be used on the outputs of the LDOs

### 9.2.1 Detailed design procedure

#### 9.2.2 Inductor selection for buck converters

Each of the converters in the PCA9460 typically use a 0.47 µH output inductor which has to be rated for its DC resistance and saturation current. The DC resistance of the inductance influences directly the efficiency of the converter. Therefore, an inductor with lowest DC resistance must be selected for highest efficiency.

Equation 1 calculates the peak-to-peak inductor ripple current under static load conditions. The saturation current of the inductor must be rated higher than the maximum inductor current as calculated with Equation 2. This is needed because during heavy load transient the inductor current rises above the calculated value.

$$\Delta I_L = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in,max}}}{L \times f} \quad (1)$$

$$I_{L,max} = I_{out,max} + \frac{\Delta I_L}{2} \quad (2)$$

Where

f = switching frequency ( 2 MHz )

L = Inductance

$\Delta I_L$  = Peak to peak inductor ripple current

$I_{L,max}$  = Maximum inductor current

$I_{out,max}$  = Maximum output DC current

A conservative approach is to select the inductor current rating just for the maximum switch current of the PCA9460

### 9.2.3 Output capacitor selection for buck converters

The fast response adaptive constant ON time control scheme of the buck converters implemented in the PCA9460 allow the use of small ceramic capacitors with a typical value of 22  $\mu$ F for each converter without having large output voltage under and overshoots during heavy load transients. Ceramic capacitors having low ESR values have the lowest output voltage ripple and are recommended. See Table 19 for recommended.

If ceramic output capacitors are used, the capacitor RMS ripple current rating always meets the application requirements. Just for completeness, the RMS ripple current is calculated in Equation 3.

$$I_{RMS,COUT} = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \times \frac{1}{2\sqrt{3}} \quad (3)$$

At nominal load current, the inductive converters operate in PWM mode. The overall output voltage ripple is the sum of the voltage spike caused by the output capacitor ESR plus the voltage ripple caused by charging and discharging the output capacitor:

$$\Delta V_{out} = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \times \left( \frac{1}{8 \times C_{out} \times f} + ESR \right) \quad (4)$$

Where

The highest output voltage ripple occurs at the highest input voltage  $V_{in}$ .

At light load currents, the converters operate in PFM mode and the output voltage ripple is dependent on the output capacitor value. The output voltage ripple is set by the internal comparator delay and the external capacitor. The typical output voltage ripple is less than 1 % of the nominal output voltage.

### 9.2.4 Input capacitor selection for buck converters

Low ESR input capacitor is highly recommended for best input voltage filtering and minimizing the interference with other circuits caused by high input voltage spikes because of the nature of buck converter. Each DC-DC

converter requires a 10 µF ceramic input capacitor on its input pins. The input capacitor could be increased without any limit for better input voltage filtering.

### 9.3 Layout guide

Figure 25 shows layout guidance.

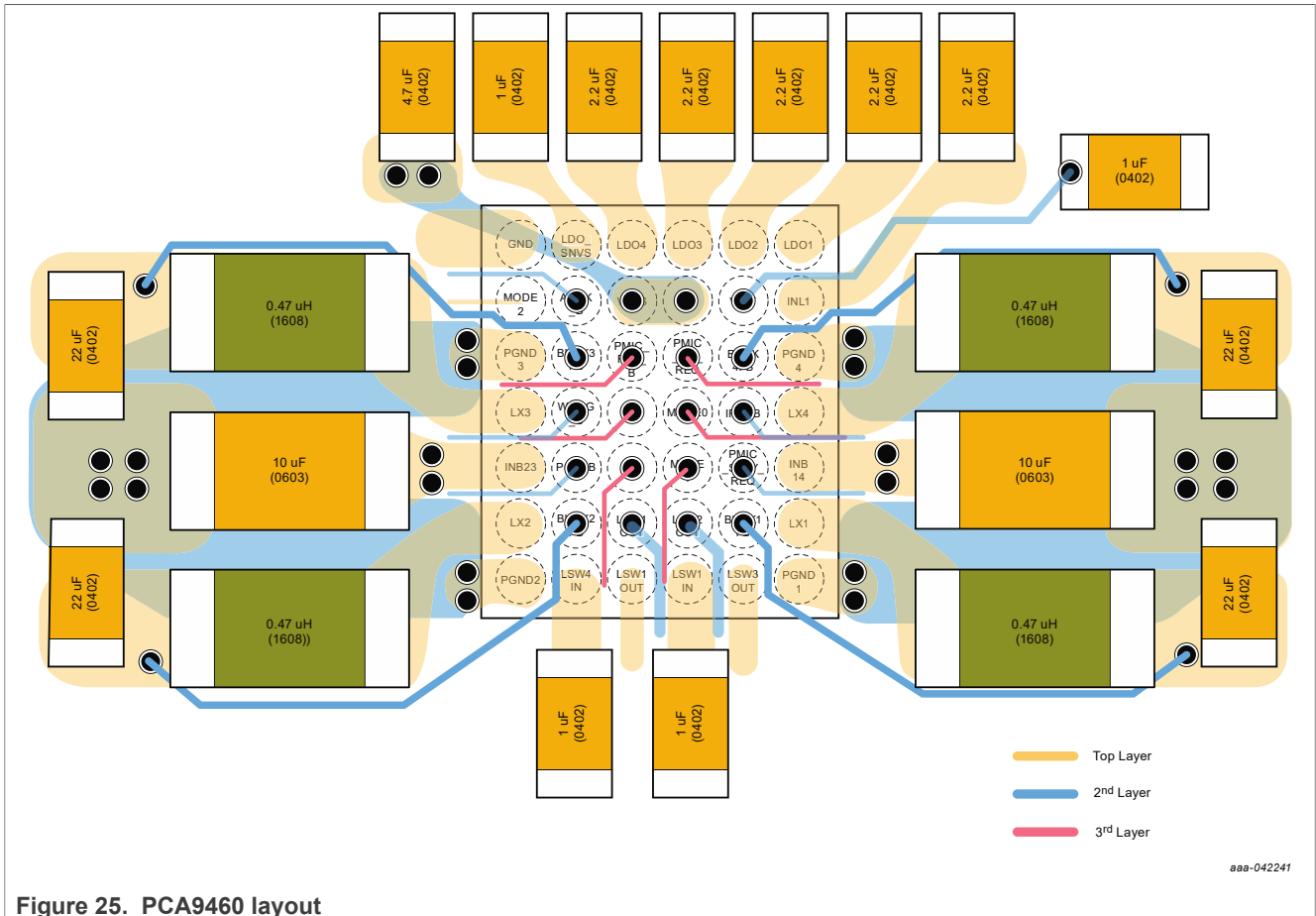


Figure 25. PCA9460 layout

## 10 Limiting values

Table 169. Limiting values (Absolute Maximum Ratings)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>range(gnd)</sub>	voltage range (with respect to GND)	pins VSYS, INL	-0.5	+6.0	V
		pins INB14, INB23, INL1	-0.5	VSYS + 0.5	V
		pins LX1, LX4	-0.5	INB14 + 0.5	V
		pins LX2, LX3	-0.5	INB23 + 0.5	V
		pins BUCK1FB, BUCK2FB, BUCK3FB, BUCK4FB	-0.5	VSYS + 0.5	V
		pin LDO1	-0.5	V <sub>INL1</sub> +0.5	V
		pins LDO2, LDO3, LDO4	-0.5	V <sub>INL</sub> +0.5	V

Table 169. Limiting values (Absolute Maximum Ratings)...continued

Symbol	Parameter	Conditions	Min	Max	Unit
		pin VINT	-0.5	+1.8	V
		pins LSWx_CFG = 0, LSW; LSW1IN, LSW4IN	-0.5	VSYS + 0.5	V
		pins LSWx_CFG = 1, LED; LSW1IN, LSW4IN	-0.5	+6.0	V
		pins LSW1OUT, LSW2 OUT, LSW3OUT	-0.5	V <sub>LSW1IN</sub> +0.5	V
		pins LSW4OUT	-0.5	V <sub>LSW4IN</sub> +0.5	V
		pins PMIC_ON_REQ, POR_B PMIC_STBY_REQ, WDOG_B, IRQ_B, SCL, SDA, MODE0, MODE1, MODE2	-0.5	VSYS + 0.5	V
		pins ACOK_B, PMIC_RST_B	-0.5	VSYS + 0.5	V
I <sub>O</sub>	output current	pins LX1, LX2, LX3, LX4; RMS current		1.5	A
		pins LSW1OUT, LSW2 OUT, LSW3OUT, LSW4OUT		0.3	A
T <sub>j</sub>	junction temperature		-40	+150	°C
V <sub>ESD</sub>	electrostatic discharge voltage - all pins	HBM (JESD22-001)	-2	+2	kV
		CDM (JESD22-C101E)	-500	500	V

## 11 Recommended operating conditions

Table 170. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>range(gnd)</sub>	voltage range (with respect to GND)	on pins VSYS, INL1, INL	2.7	5.5	V
		on pins INB14, INB23	2.7	5.5	V
		on pins LSW1IN, LSW4IN	1.2	5.5	V
T <sub>j</sub>	junction temperature		-40	+125	°C
T <sub>amb</sub>	ambient temperature		-40	+85	°C
T <sub>stg</sub>	storage temperature		-55	+85	°C

## 12 Thermal characteristics

Table 171. Thermal characteristics

Symbol	Parameter	Board Type <sup>[1]</sup>	Typ	Unit
R <sub>θJA</sub>	Thermal resistance from junction to ambient <sup>[2]</sup>	JESD51-9, 2s2p	46	°C/W

Table 171. Thermal characteristics...continued

Symbol	Parameter	Board Type <sup>[1]</sup>	Typ	Unit
$\Psi_{JT}$	Junction to Top of package Thermal Characterization Parameter <sup>[2]</sup>	JESD51-9, 2s2p	2	°C/W

[1] Thermal test board meets JEDEC specification for this package (JESD51-9)

[2] Determined in accordance to JEDEC JESD51-2A natural convection environment. Thermal resistance data in this report is solely for a thermal performance comparison of one package to another in a standardized specified environment. It is not meant to predict the performance of a package in an application-specific environment

## 12.1 Rating data

Junction to ambient thermal resistance nomenclature: the JEDEC specification reserves the symbol R $\theta$ JA or  $\theta$ JA (Theta-JA) strictly for junction-to-ambient thermal resistance on a 1s test board in a natural convection environment. R $\theta$ JMA or  $\theta$ JMA (Theta-JMA) is used for both junction-to-ambient on a 2s2p test board in natural convection and for junction-to-ambient with forced convection on both 1s and 2s2p test boards. It is anticipated the generic name, Theta-JA, continues to be commonly used. The JEDEC standards can be consulted at <http://www.jedec.org>.

## 12.2 Estimation of junction temperature

An estimation of the chip junction temperature T<sub>J</sub> can be obtained from the equation:

$$T_J = T_A + (R_{\theta JA} \times P_D)$$

with:

T<sub>A</sub> = Ambient temperature for the package in °C

R $\theta$ JA = Junction to ambient thermal resistance in °C/W

P<sub>D</sub> = Power dissipation in the package in W

The junction-to-ambient thermal resistance is an industry standard value providing a quick and easy estimation of thermal performance. Unfortunately, there are two values in common usage: the value determined on a single-layer board R $\theta$ JA and the value obtained on a four-layer board R $\theta$ JMA. Actual application PCBs show a performance close to the simulated four-layer board value, although this may be somewhat degraded in case of significant power dissipated by other components placed close to the device.

At a known board temperature, the junction temperature T<sub>J</sub> is estimated using the following equation:

$$T_J = T_B + (R_{\theta JB} \times P_D)$$

with:

T<sub>B</sub> = Board temperature at the package perimeter in °C

R $\theta$ JB = Junction to board thermal resistance in °C/W

P<sub>D</sub> = Power dissipation in the package in W



### 13 Electrical characteristics

#### 13.1 Top level parameter

Table 172. Top level parameter description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Quiescent Current</b>							
$I_{Q\_Shutdown}$	Shutdown Current	LDOSNVS are ON and no load, PMIC_ON_REQ = L	25 °C	1.4	3	μA	
			-40 °C ~ 85 °C	1.4	20		
$I_{Q\_STDBY\_1}$	System Standby current at low power mode	LDOSNVS and BUCK1 are ON and no load. PWR_SAVE = 01b, Bx_LPMODE = 01b, PMIC_STBY_REQ= H	25 °C	3.5	7	μA	
			-40 °C ~ 85 °C	3.5	22		
$I_{Q\_STDBY\_2}$	System Standby current	All Regulators are ON and no load. PWR_SAVE = 01b, Bx_LPMODE = 01b, PMIC_STBY_REQ= H	25 °C	8.8	20	μA	
			-40 °C ~ 85 °C	8.8	35		
		All Regulators are ON and no load. PWR_SAVE = 11b, Bx_LPMODE = 01b, PMIC_STBY_REQ= H	25 °C	20	32	μA	
			-40 °C ~ 85 °C	20	55		
$I_{Q\_ACTIVE}$	System Active current	All Regulators are ON and no load. PWR_SAVE = 01b, Bx_LPMODE = 11b, PMIC_STBY_REQ= L	-40 °C ~ 85 °C	20	35	85	μA
<b>VSYS</b>							
$V_{SYS\_UVLO}$	VSYS UVLO	Rising – OTP Programmable 00b = 2.65 V <b>01b = 2.85 V</b> 10b = 3.0 V 11b = 3.3 V	2.7	2.85	3.0	V	
$V_{SYS\_UVLO\_H}$	VSYS UVLO Hysteresis	Falling		200		mV	
<b>VINT</b>							
VINT	Internal Power supply	$V_{SYS} = 3.8\text{ V}$	1.4	1.5	1.6	V	
<b>Low VSYS</b>							
$V_{LOW\_VSYS}$	Low VSYS	Low VSYS threshold above $V_{SYS\_UVLO}$ , LOW_VSYS [7:6] = 01b	150	200	250	mV	
$V_{LOW\_VSYS\_HYS}$	Low VSYS Hysteresis			100		mV	
<b>Thermal Shutdown</b>							
$T_{JSHDN}$	Thermal Shutdown	$T_j$ Rising, 15°C hysteresis		150		°C	
$T_{J80}$	Thermal interrupt1	$T_j$ Rising, 15°C hysteresis		80		°C	
$T_{J100}$	Thermal interrupt2	$T_j$ Rising, 15°C hysteresis		100		°C	
$T_{JHYS}$	Thermal Hysteresis			15		°C	
<b>Logic and Control signals</b>							
$V_{IL}$	Input Low level	PMIC_ON_REQ, PMIC_STBY_REQ, WDOG_B, MODE0, MODE1, MODE2, PMIC_RST_B, ACOK_B			0.4	V	

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Table 172. Top level parameter description...continued

Unless otherwise specified, VSYS = 3.8 V, VINB14 = VINB23 = 3.8 V, VINL = 3.8 V, VINL1 = VBUCK4, TA = -40 °C ~ +85 °C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>IH</sub>	Input High level	PMIC_ON_REQ, PMIC_STBY_REQ, WDOG_B, MODE0, MODE1, MODE2, PMIC_RST_B, ACOKB	1.4			V
I <sub>LEAK</sub>	Logic Input leakage current	PMIC_ON_REQ, PMIC_STBY_REQ, WDOG_B, MODE0, MODE1, MODE2, PMIC_RST_B, ACOKB V <sub>Logic</sub> = 5.5 V, VSYS = 5.5 V	-1		+1	µA
V <sub>OL</sub>	Output Low level	IRQ_B, POR_B, I <sub>OL</sub> = 6mA			0.4	V
I <sub>LEAK</sub>	Output high leakage current	IRQ_B, POR_B, V <sub>Logic</sub> = 5.5 V, VSYS = 5.5 V	-1		+1	µA
<b>Timing spec</b>						
t <sub>SNVS</sub>	Maximum time to enable LDO_SNVs from VSYS UVLO detected			20		ms
t <sub>ON_DEB</sub>	PMIC_ON_REQ debounce time		40	50	60	µs
t <sub>ACOK_B_DEB</sub>	ACOK_B debounce time	Falling	40	50	60	ms
t <sub>ACOK_ONESHOT</sub>	ACOK_B Oneshot timer	Programmable, ACOK_B_OSTMR = 0b		2.5		sec
t <sub>DEB_PMIC_RST_B</sub>	Debounce time of PMIC_RST_B	Programmable, PMIC_RST_B_DEB = 0b	16	20	24	ms
t <sub>ONKEY</sub>	ON KEY timer of PMIC_RST_B	Programmable, ONKEY_TIMER = 01b	1.6	2	2.4	sec
t <sub>RESETKEY</sub>	RESET KEY timer of PMIC_RST_B	Programmable, RESETKEY_TIMER = 101b	7.2	8	9.6	sec
t <sub>RESET_WAIT</sub>	Wait time from RESETKEY detection to perform reset		80	100	120	ms
t <sub>ON_STEP</sub>	Time step to turn on each regulator	Programmable, PSQ_TON_STEP = 01b	1.6	2	2.4	ms
t <sub>POK_EXP</sub>	POK wait timeout during power ON sequence		8	10	12	ms
t <sub>OFF_STEP</sub>	Time step to turn off each regulator	Programmable, PSQ_TOFF_STEP = 10b	6	8	10	ms
t <sub>RSTB</sub>	Time from PUD_T16 Gr POK to POR_B release during Power on seq		16	20	24	ms
t <sub>FLT_THSD_DEB</sub>	Debounce Time for Thermal fault		16	20	24	µs
t <sub>DEB_POKB</sub>	Debounce time of regulator POKB		240	300	360	µs
t <sub>FLT_SD_WAIT</sub>	Wait time to enter FAULT_SD after fault interrupt	At Standby and Run mode, programmable, t <sub>FLT_SD_WAIT</sub> = 0b	80	100	120	ms
t <sub>FLT_SD_STAY</sub>	Time to stay at FAULT_SD to move other mode		80	100	120	ms
t <sub>RESTART</sub>	Wait time to start power up after power down at cold reset	Programmable, T <sub>restart</sub> = 0b	200	250	300	ms
t <sub>PWR_HOLD_RST</sub>	Power Hold time after reset is performed		80	100	120	ms
t <sub>RESET</sub>	POR_B low time at Warm reset		16	20	24	ms
t <sub>DEB_WDOGB</sub>	Debounce time of WDOG_B		40	50	60	µs
t <sub>FLT_POK_MSK</sub>	POK mask time when regulator is enabled at RUN/Standby mode		2.4	3	3.6	ms

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Table 172. Top level parameter description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>DVS Timing spec</b>						
$t_{MAX\_DIFF}$	Maximum latency of MODE pins	SMART_MODE = 0b			0.1	$\mu\text{s}$
$t_{DVS\_EFF}$		SMART_MODE = 0b		3	4	$\mu\text{s}$
$t_{SETUP\_MODE2}$	MODE2 pin Setup time to select BUCK regulator	SMART_MODE = 1b	3			$\mu\text{s}$
$t_{MIN\_H}$	MODE0, MODE1 pin Minimum High time	SMART_MODE = 1b	3			$\mu\text{s}$
$t_{MIN\_L}$	MODE0, MODE1 pin Minimum Low time	SMART_MODE = 1b	2			$\mu\text{s}$
$t_{MIN\_GAP}$	Minimum time to start MODE1 from falling edge of MODE0, vice versa	SMART_MODE = 1b	3			$\mu\text{s}$

13.2 BUCK1

Table 173. BUCK1 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{INB1}$	Input voltage range	INB14 pin <sup>[1]</sup>	2.7		5.5	V
$I_Q$	Quiescent current	Low power mode, $I_{OUT} = 0\text{ A}$ , $25\text{ °C}$		1.3	2.5	$\mu\text{A}$
		Normal mode, $I_{OUT} = 0\text{ A}$ <sup>[1]</sup>		5.2	11	$\mu\text{A}$
$I_{OUT\_MAX}$	Max Output Current	Low power mode, $V_{BUCK1} = 1.8\text{ V}$			100	mA
		Normal mode	1000			mA
$V_{BUCK1\_RANGE}$	Programmable Output voltage range	$I^2C$ programmable, 25 mV/step	0.6		3.4	V
$V_{BUCK1}$	DC Output Voltage Accuracy	$V_{INB1} = 3.8\text{ V}$ , $V_{BUCK1} = 1.8\text{ V}$ , $I_{OUT} = 0\text{ A}$ , FPWM mode, Normal mode	-2		2	%
		$V_{INB1} = 3.8\text{ V}$ , $V_{BUCK1} = 1.8\text{ V}$ , $I_{OUT} = 10\text{ mA}$ , Low power mode	-3		3	%
$\Delta V_{OUT(\Delta V_{INB})}$	DC Line regulation	$V_{INB1} = 3\text{ V}$ to $5\text{ V}$ , $I_{OUT} = I_{OUT\_MAX}$ <sup>[1]</sup>		2		mV/V
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$0\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $V_{BUCK1} = 1.8\text{ V}$ <sup>[1]</sup>		3		mV/A
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$I_{OUT}$ changes 0 to $I_{OUT\_MAX}$ ( $1\text{ A}/\mu\text{s}$ slope ), $V_{BUCK1} = 1.8\text{ V}$ <sup>[1]</sup>		50		mV
$\Delta V_{OUT}$	Output voltage Ripple	FPWM mode <sup>[1]</sup>		10		mV
$f_{SW}$	Switching Frequency in CCM			2		MHz
$R_{DS(on)}$	High Side P-FET $R_{DS(on)}$	$V_{INB1} = 3.8\text{ V}$		200		m $\Omega$
	Low Side N-FET $R_{DS(on)}$	$V_{INB1} = 3.8\text{ V}$		90		m $\Omega$
$I_{LIM}$	High side current limit	$V_{INB1} = 3.8\text{ V}$	2.2	2.4	2.6	A
	Low side current limit	$V_{INB1} = 3.8\text{ V}$	0.8	1	1.2	A
$t_{START}$	Startup time	EN rising to 90 % of output voltage <sup>[1]</sup>		500	700	$\mu\text{s}$
$V_{RAMP}$	Output voltage slew rate	Programmable, RAMP[1:0] = 01b <sup>[1]</sup>		12.5		mV/ $\mu\text{s}$
$V_{soft\_strp}$	Soft-start slew rate	<sup>[1]</sup>		12.5		mV/ $\mu\text{s}$
$R_{DIS}$	Output Active Discharge Resistance			100	150	$\Omega$

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**Table 173. BUCK1 description...continued**

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
POK	Output Power good			85	95	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
L	Inductor value	[1]		0.47		$\mu\text{H}$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance [1]	22			$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

13.3 BUCK2

**Table 174. BUCK2 description**

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{INB2}$	Input voltage range	INB23 pin [1]	2.7		5.5	V
$I_Q$	Quiescent current	Low power mode, $I_{OUT} = 0\text{ A}$ , $25\text{ °C}$		1.3	2.5	$\mu\text{A}$
		Normal mode, $I_{OUT} = 0\text{ A}$ [1]		5.2	11	$\mu\text{A}$
$I_{OUT\_MAX}$	Max Output Current	Low power mode			100	mA
		Normal mode	1000			mA
$V_{BUCK2\_RANGE}$	Programmable Output voltage range	$I^2\text{C}$ programmable, 12.5 mV/step	0.6		2.1875	V
$V_{BUCK2}$	DC Output Voltage Accuracy	$V_{INB2} = 3.8\text{ V}$ , $V_{BUCK2} = 1.0\text{ V}$ , $I_{OUT} = 0\text{ A}$ , FPWM mode, Normal mode	-2		2	%
		$V_{INB2} = 3.8\text{ V}$ , $V_{BUCK2} = 1.0\text{ V}$ , $I_{OUT} = 10\text{ mA}$ , Low power mode	-3		3	%
$\Delta V_{OUT(\Delta V_{INB})}$	DC Line regulation	$V_{INB2} = 3\text{ V to }5\text{ V}$ , $I_{OUT} = I_{OUT\_MAX}$ [1]		2		mV/V
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$0\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $V_{BUCK2} = 1.0\text{ V}$ [1]		3		mV/A
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$I_{OUT}$ changes 0 to $I_{OUT\_MAX}$ ( 1A/ $\mu\text{s}$ slope ), $V_{BUCK2} = 1.0\text{ V}$ [1]		50		mV
$\Delta V_{OUT}$	Output voltage Ripple	FPWM mode [1]		10		mV
$f_{SW}$	Switching Frequency in CCM			2		MHz
$R_{DS(on)}$	High Side P-FET $R_{DS(on)}$	$V_{INB2} = 3.8\text{ V}$		200		m $\Omega$
	Low Side N-FET $R_{DS(on)}$	$V_{INB2} = 3.8\text{ V}$		90		m $\Omega$
$I_{LIM}$	High side current limit	$V_{INB2} = 3.8\text{ V}$	2.2	2.4	2.6	A
	Low side current limit	$V_{INB2} = 3.8\text{ V}$	0.8	1	1.2	A
$t_{START}$	Startup time	EN rising to 90 % of output voltage [1]		500	700	$\mu\text{s}$
$V_{RAMP}$	Output voltage slew rate	Programmable, RAMP[1:0] = 01b [1]		12.5		mV/ $\mu\text{s}$

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Table 174. BUCK2 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{soft\_strup}$	Soft-start slew rate	[1]		12.5		mV/us
POK	Output Power good		75	85	95	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		μs
$R_{DIS}$	Output Active Discharge Resistance			100	150	Ω
L	Inductor value	[1]		0.47		μH
$C_{OUT}$	Output capacitance	Minimum nominal capacitance [1]	20			μF

[1] Not tested in production. Guaranteed by design

13.4 BUCK3

Table 175. BUCK3 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{INB3}$	Input voltage range	INB23 pin [1]	2.7		5.5	V
$I_Q$	Quiescent current	Low power mode, $I_{OUT} = 0\text{ A}$ , $25\text{ °C}$		1.3	2.5	μA
		Normal mode, $I_{OUT} = 0\text{ A}$ [1]		5.2	11	μA
$I_{OUT\_MAX}$	Max Output Current	Low power mode			100	mA
		Normal mode	1000			mA
$V_{BUCK3\_RANGE}$	Programmable Output voltage range	i <sup>2</sup> C programmable, 12.5 mV/step	0.6		2.1875	V
$V_{BUCK3}$	DC Output Voltage Accuracy	$V_{INB3} = 3.8\text{ V}$ , $V_{BUCK3} = 1.0\text{ V}$ , $I_{OUT} = 0\text{ A}$ , FPWM mode, Normal mode				
		• $-40\text{ °C}$ to $85\text{ °C}$	-1.0		+3.0	%
		• $0\text{ °C}$ to $85\text{ °C}$	-0.5		2.25	%
		$V_{INB3} = 3.8\text{ V}$ , $V_{BUCK3} = 1.0\text{ V}$ , $I_{OUT} = 10\text{ mA}$ , Low power mode				
	• $-40\text{ °C}$ to $85\text{ °C}$	-2.0		+4.0	%	
$\Delta V_{OUT(\Delta V_{INB})}$	DC Line regulation	$V_{INB3} = 3\text{ V}$ to $5\text{ V}$ , $I_{OUT} = I_{OUT\_MAX}$ [1]		2		mV/V
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$0\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $V_{BUCK3} = 1.0\text{ V}$ [1]		3		mV/A
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$I_{OUT}$ changes 0 to $I_{OUT\_MAX}$ ( $1\text{ A}/\mu\text{s}$ slope ), $V_{BUCK3} = 1.0\text{ V}$ [1]		50		mV
$\Delta V_{OUT}$	Output voltage Ripple	FPWM mode [1]		10		mV
$f_{SW}$	Switching Frequency in CCM			2		MHz
$R_{DS(on)}$	High Side P-FET $R_{DS(on)}$	$V_{INB3} = 3.8\text{ V}$		200		mΩ

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Table 175. BUCK3 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	Low Side N-FET $R_{DS(ON)}$	$V_{INB3} = 3.8\text{ V}$		90		mΩ
$I_{LIM}$	High side current limit	$V_{INB3} = 3.8\text{ V}$	2.2	2.4	2.6	A
	Low side current limit	$V_{INB3} = 3.8\text{ V}$	0.8	1	1.2	A
$t_{START}$	Startup time	EN rising to 90 % of output voltage <sup>[1]</sup>		500	700	μs
$V_{RAMP}$	Output voltage slew rate	Programmable, RAMP[1:0] = 01b <sup>[1]</sup>		12.5		mV/us
$V_{soft\_strup}$	Soft-start slew rate	<sup>[1]</sup>		12.5		mV/us
POK	Output Power good		75	85	95	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		μs
$R_{DIS}$	Output Active Discharge Resistance			100	150	Ω
L	Inductor value	<sup>[1]</sup>		0.47		μH
$C_{OUT}$	Output capacitance	Minimum nominal capacitance <sup>[1]</sup>	20			μF

[1] Not tested in production. Guaranteed by design

13.5 BUCK4

Table 176. BUCK4 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{INB4}$	Input voltage range	INB14 pin <sup>[1]</sup>	2.7		5.5	V
$I_Q$	Quiescent current	Low power mode, $I_{OUT} = 0\text{ A}$ , $25\text{ °C}$		1.3	2.5	μA
		Normal mode, $I_{OUT} = 0\text{ A}$ <sup>[1]</sup>		5.2	11	μA
$I_{OUT\_MAX}$	Max Output Current	Low power mode			100	mA
		Normal mode	1000			mA
$V_{BUCK4\_RANGE}$	Programmable Output voltage range	i <sup>2</sup> C programmable, 25 mV/step	0.6		3.4	V
$V_{BUCK4}$	DC Output Voltage Accuracy	$V_{INB4} = 3.8\text{ V}$ , $V_{BUCK3} = 1.1\text{ V}$ , $I_{OUT} = 0\text{ A}$ , FPWM mode, Normal mode	-2		2	%
		$V_{INB4} = 3.8\text{ V}$ , $V_{BUCK3} = 1.1\text{ V}$ , $I_{OUT} = 10\text{ mA}$ , Low power mode	-3		3	%
$\Delta V_{OUT(\Delta V_{INB})}$	DC Line regulation	$V_{INB4} = 3\text{ V to }5\text{ V}$ , $I_{OUT} = I_{OUT\_MAX}$ <sup>[1]</sup>		2		mV/V
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$0\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $V_{BUCK4} = 1.8\text{ V}$ <sup>[1]</sup>		3		mV/A
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$I_{OUT}$ changes 0 to $I_{OUT\_MAX}$ ( 1A/us slope ), $V_{BUCK4} = 1.1\text{ V}$ <sup>[1]</sup>		50		mV

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Table 176. BUCK4 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta V_{OUT}$	Output voltage Ripple	FPWM mode <sup>[1]</sup>		10		mV
$f_{SW}$	Switching Frequency in CCM			2		MHz
$R_{DSON}$	High Side P-FET $R_{DSON}$	$V_{INB4} = 3.8\text{ V}$		200		mΩ
	Low Side N-FET $R_{DSON}$	$V_{INB4} = 3.8\text{ V}$		90		mΩ
$I_{LIM}$	High side current limit	$V_{INB4} = 3.8\text{ V}$	2.2	2.4	2.6	A
	Low side current limit	$V_{INB4} = 3.8\text{ V}$	0.8	1	1.2	A
$t_{START}$	Startup time	EN rising to 90 % of output voltage <sup>[1]</sup>		500	700	μs
$V_{RAMP}$	Output voltage slew rate	Programmable, RAMP[1:0] = 01b <sup>[1]</sup>		12.5		mV/us
$V_{soft\_strup}$	Soft-start slew rate	<sup>[1]</sup>		12.5		mV/us
$R_{DIS}$	Output Active Discharge Resistance			100	150	Ω
POK	Output Power good			85	95	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		μs
L	Inductor value	<sup>[1]</sup>		0.47		μH
$C_{OUT}$	Output capacitance	Minimum nominal capacitance <sup>[1]</sup>	20			μF

[1] Not tested in production. Guaranteed by design

### 13.6 LDO\_SNVS

Table 177. LDO\_SNVS description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LDOSNVS} = 3.0\text{ V}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IN}$	Input voltage range	$V_{SYS}$ pin <sup>[1]</sup>	2.7		5.5	V
$I_Q$	Quiescent current	Regulator enabled, No load		0.23	0.5	μA
$I_{OUT\_MAX}$	Maximum Output DC Current	$V_{LDOSNVS} = 3.3\text{ V}$	10			mA
$I_{LIMIT}$	Short Current Limit	Output shorted to GND	20			mA
$V_{DO}$	Dropout Voltage	$I_{OUT} = I_{OUT\_MAX}$ , $V_{SYS} = 3.2\text{ V}$ , $V_{LDOSNVS} = 3.3\text{ V}$		25	50	mV
$V_{LDOSNVS}$	Nominal output voltage	I <sup>2</sup> C Programmable, 100mV step	0.8		3.3	V
	Default voltage			3.0		V
	DC accuracy	$V_{LDOSNVS} = 3.0\text{ V}$ , $I_{Load} = 5\text{ mA}$	-3		3	%
$V_{NOISE}$	Output noise	$f = 10\text{ Hz to }10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{MAX}$ , $V_{LDOSNVS} = 3.0\text{ V}$ <sup>[1]</sup>		450		μV
$\Delta V_{OUT(\Delta VINL)}$	DC Line regulation	$V_{LDOSNVS} + 0.3\text{ V} < V_{SYS} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$		0.2		%/V

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Table 177. LDO\_SNVs description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LDOSNVs} = 3.0\text{ V}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$V_{SYS} = V_{LDOSNVs} + 0.3\text{ V}$ to $5.5\text{ V}$ , $0\text{ mA} < I_{OUT} < I_{OUT\_MAX}$		0.25		%
$\Delta V_{OUT(\Delta V_{INL})}$	Transient Line Response	$V_{LDOSNVs} + 0.3\text{ V} < V_{SYS} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ [1]		3		%/V
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$V_{SYS} = V_{LDOSNVs} + 0.3\text{ V}$ to $5.5\text{ V}$ , [1] $1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ , $V_{LDOSNVs} = 3.3\text{ V}$ , $T_A = 25\text{ °C}$	-1		1	%
PSRR	Power Supply Rejection ratio	$f = 10\text{ Hz}$ to $10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ [1]		36		dB
$V_{soft\_strup}$	Soft-start slew rate	$I_{OUT} = 0\text{ mA}$ , $10\%$ to $90\%$ of $V_{LDOSNVs}$ [1]		6.0		mV/ $\mu\text{s}$
$V_{ov\_srtup}$	Overshoot at startup	$I_{OUT} = 0\text{ mA}$ [1]			10	mV
$t_{EN}$	Enable time	EN rising to $90\%$ of output voltage [1]		700	1500	$\mu\text{s}$
POK_90	Output Power good	Percentage of $V_{LDOSNVs}$ configuration	86	90	94	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
$R_{DIS}$	Active Discharge Resistance		50	100	150	$\Omega$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance [1]	1			$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

13.7 LDO1

Table 178. LDO1 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = 1.1\text{ V}$  ( $V_{BUCK4}$ ),  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IN}$	Input voltage range	INL1 pin, $V_{SYS} > V_{LDO1} + 1.5\text{ V}$ [1]	$V_{LDO1} + V_{DO}$		5.5	V
$I_Q$	Quiescent current	Regulator enabled, No load, Low power mode		0.35	0.6	$\mu\text{A}$
		Regulator enabled, No load, Normal power mode		0.5	0.8	$\mu\text{A}$
$I_{OUT\_MAX}$	Maximum Output DC Current	$V_{INL1} > V_{LDO1} + 0.2\text{ V}$ , $V_{LDO1} = 0.6\text{ V}$	250			mA
$I_{LIMIT}$	Short Current Limit	Output shorted to GND	260			mA
$V_{DO}$	Dropout Voltage	$I_{OUT} = I_{OUT\_MAX}$ , $V_{INL1} = 1.8\text{ V}$ , $L1\_OUT = 2\text{ V}$ , $V_{SYS} > V_{LDO1} + 1.5\text{ V}$		100	175	mV
$V_{LDO1}$	Nominal output voltage	I <sup>2</sup> C Programmable, 50 mV/step	0.6		1.95	V
	Default voltage			0.6		V



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Table 178. LDO1 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = 1.1\text{ V}$  ( $V_{BUCK4}$ ),  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	DC accuracy	$V_{LDO1} = 0.6\text{ V}$ , $I_{Load} = 5\text{ mA}$	-2		2	%
$V_{NOISE}$	Output noise	$f = 10\text{ Hz to } 10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{MAX}$ , $V_{LDO1} = 0.6\text{ V}$ [1]		66		$\mu\text{V}$
$\Delta V_{OUT}(\Delta V_{INL})$	DC Line regulation	$V_{LDO1} + 0.3\text{ V} < V_{INL1} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$		0.01		%/V
$\Delta V_{OUT}(\Delta I_{OUT})$	DC Load regulation	$V_{INL1} = V_{LDO1} + 0.3\text{ V to } 5.5\text{ V}$ , $0.1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$		0.15		%
$\Delta V_{OUT}(\Delta V_{INL})$	Transient Line Response	$V_{LDO1} + 0.3\text{ V} < V_{INL1} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ [1]		3		%/V
$\Delta V_{OUT}(\Delta I_{OUT})$	Transient Load Response	$V_{INL1} = V_{LDO1} + 0.3\text{ V to } 5.5\text{ V}$ , $1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ , $V_{LDO1} = 1.1\text{ V}$ [1]	-3		5	%
PSRR	Power Supply Rejection ratio	$f = 10\text{ Hz to } 10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ [1]		55		dB
$V_{soft\_strup}$	Soft-start slew rate	$I_{OUT} = 0\text{ mA}$ , $10\%$ to $90\%$ of $V_{LDO1}$ [1]		10		$\text{mV}/\mu\text{s}$
$V_{ov\_srtup}$	Overshoot at startup	$I_{OUT} = 0\text{ mA}$ [1]			18	mV
$t_{EN}$	Enable time	EN rising to $90\%$ of output voltage at $V_{LDO1} = 0.6\text{ V}$ [1]		200	250	$\mu\text{s}$
POK_90	Output Power good	Delta from $V_{LDO1}$ Target	87	90	93	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
$R_{DIS}$	Active Discharge Resistance			100	180	$\Omega$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance [1]	2.2		10	$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

13.8 LDO2

Table 179. LDO2 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IN}$	Input voltage range	INL pin [1]	2.7		5.5	V
$I_Q$	Quiescent current	Regulator enabled, No load		0.23	0.5	$\mu\text{A}$
$I_{OUT\_MAX}$	Maximum Output DC Current	$V_{LDO2} = 3.3\text{ V}$	250			mA
$I_{LIMIT}$	Short Current Limit	Output shorted to GND	260	310		mA
$V_{DO}$	Dropout Voltage	$I_{OUT} = I_{OUT\_MAX}$ , $V_{INL} = 3.2\text{ V}$ , $L2\_OUT = 3.3\text{ V}$		60	100	mV
$V_{LDO2}$	Nominal output voltage	$I^2\text{C}$ Programmable, $50\text{ mV/step}$	0.8		3.3	V
	Default voltage	VSEL = L		3.3		V
	Default voltage	VSEL = H		1.8		V

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Table 179. LDO2 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	DC accuracy	$V_{LDO2} = 3.3\text{ V}$ , $I_{Load} = 5\text{ mA}$	-2		2	%
$V_{NOISE}$	Output noise	$f = 10\text{ Hz to } 10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{MAX}$ , $V_{LDO2} = 1.8\text{ V}$ <sup>[1]</sup>		150		$\mu\text{V}$
$\Delta V_{OUT(\Delta VINL)}$	DC Line regulation	$V_{LDO2} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$		0.15		%/V
$\Delta V_{OUT(\Delta IOUT)}$	DC Load regulation	$V_{INL} = V_{LDO2} + 0.3\text{ V to } 5.5\text{ V}$ , $0.1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$		0.15		%
$\Delta V_{OUT(\Delta VINL)}$	Transient Line Response	$V_{LDO2} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ <sup>[1]</sup>		3		%/V
$\Delta V_{OUT(\Delta IOUT)}$	Transient Load Response	$V_{INL} = V_{LDO2} + 0.3\text{ V to } 5.5\text{ V}$ , $1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ , $V_{LDO2} = 3.3\text{ V}$ <sup>[1]</sup>	-3		3	%
PSRR	Power Supply Rejection ratio	$f = 10\text{ Hz to } 10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ <sup>[1]</sup>		40		dB
$V_{soft\_strup}$	Soft-start slew rate	$I_{OUT} = 0\text{ mA}$ , 10% to 90% of $V_{LDO2}$ <sup>[1]</sup>		6.0		mV/ $\mu\text{s}$
$V_{ov\_srtup}$	Overshoot at startup	$I_{OUT} = 0\text{ mA}$ <sup>[1]</sup>			20	mV
$t_{EN}$	Enable time	EN rising to 90% of output voltage, $V_{LDO2} = 3.3\text{ V}$ <sup>[1]</sup>		800	1800	$\mu\text{s}$
POK_90	Output Power good	Percentage of $V_{LDO2}$ configuration	86	90	94	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
$R_{DIS}$	Active Discharge Resistance			100	200	$\Omega$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance <sup>[1]</sup>	2.2		10	$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

### 13.9 LDO3

Table 180. LDO3 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IN}$	Input voltage range	INL pin <sup>[1]</sup>	2.7		5.5	V
$I_Q$	Quiescent current	Regulator enabled, No load		0.23	0.5	$\mu\text{A}$
$I_{OUT\_MAX}$	Maximum Output DC Current	$V_{LDO3} = 3.3\text{ V}$	250			mA
$I_{LIMIT}$	Short Current Limit	Output shorted to GND	260	310		mA
$V_{DO}$	Dropout Voltage	$I_{OUT} = I_{OUT\_MAX}$ , $V_{INL} = 3.2\text{ V}$ , $L3\_OUT = 3.3\text{ V}$		60	100	mV
$V_{LDO3}$	Nominal output voltage	I <sup>2</sup> C Programmable, 50mV/step	0.8		3.3	V
	Default voltage			3.3		V
	DC accuracy	$V_{LDO3} = 3.3\text{ V}$ , $I_{Load} = 5\text{ mA}$	-2		2	%

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Table 180. LDO3 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{NOISE}$	Output noise	$f = 10\text{ Hz to }10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{MAX}$ , $V_{LDO3} = 3.3\text{ V}$ <sup>[1]</sup>		170		$\mu\text{V}$
$\Delta V_{OUT(\Delta V_{INL})}$	DC Line regulation	$V_{LDO3} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$		0.15		$\%/V$
$\Delta V_{OUT(\Delta I_{OUT})}$	DC Load regulation	$V_{INL} = V_{LDO3} + 0.3\text{ V to }5.5\text{ V}$ , $0.1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$		0.15		$\%$
$\Delta V_{OUT(\Delta V_{INL})}$	Transient Line Response	$V_{LDO3} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ <sup>[1]</sup>		3		$\%/V$
$\Delta V_{OUT(\Delta I_{OUT})}$	Transient Load Response	$V_{INL} = V_{LDO3} + 0.3\text{ V to }5.5\text{ V}$ , $1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ , $V_{LDO3} = 3.3\text{ V}$ <sup>[1]</sup>	-3		3	$\%$
PSRR	Power Supply Rejection ratio	$f = 10\text{ Hz to }10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ <sup>[1]</sup>		40		dB
$V_{soft\_strup}$	Soft-start slew rate	$I_{OUT} = 0\text{ mA}$ , $10\%$ to $90\%$ of $V_{LDO3}$ <sup>[1]</sup>		6.0		$\text{mV}/\mu\text{s}$
$V_{ov\_srtup}$	Overshoot at startup	$I_{OUT} = 0\text{ mA}$ <sup>[1]</sup>			20	mV
$t_{EN}$	Enable time	EN rising to $90\%$ of output voltage, $V_{LDO3} = 3.3\text{ V}$ <sup>[1]</sup>		800	1800	$\mu\text{s}$
POK_90	Output Power good	Percentage of $V_{LDO3}$ configuration	86	90	94	$\%$
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
$R_{DIS}$	Active Discharge Resistance			100	200	$\Omega$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance <sup>[1]</sup>	2.2		10	$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

13.10 LDO4

Table 181. LDO4 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IN}$	Input voltage range	INL pin <sup>[1]</sup>	2.7		5.5	V
$I_Q$	Quiescent current	Regulator enabled, No load		0.23	0.5	$\mu\text{A}$
$I_{OUT\_MAX}$	Maximum Output DC Current	$V_{LDO4} = 1.8\text{ V}$	250			mA
$I_{LIMIT}$	Short Current Limit	Output shorted to GND	260			mA
$V_{DO}$	Dropout Voltage	$I_{OUT} = I_{OUT\_MAX}$ , $V_{INL} = 3.2\text{ V}$ , $L4\_OUT = 3.3\text{ V}$		60	100	mV
$V_{LDO4}$	Nominal output voltage	I <sup>2</sup> C Programmable, 50 mV/step	0.8		3.3	V
	Default voltage			1.8		V
	DC accuracy	$V_{LDO4} = 1.8\text{ V}$ , $I_{Load} = 5\text{ mA}$	-2		2	$\%$
$V_{NOISE}$	Output noise	$f = 10\text{ Hz to }10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{MAX}$ , $V_{LDO4} = 1.8\text{ V}$ <sup>[1]</sup>		150		$\mu\text{V}$

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Table 181. LDO4 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta V_{OUT(\Delta VINL)}$	DC Line regulation	$V_{LDO4} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$		0.15		%/V
$\Delta V_{OUT(\Delta IOUT)}$	DC Load regulation	$V_{INL} = V_{LDO4} + 0.3\text{ V}$ to $5.5\text{ V}$ , $0.1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$		0.15		%
$\Delta V_{OUT(\Delta VINL)}$	Transient Line Response	$V_{LDO4} + 0.3\text{ V} < V_{INL} < 5.5\text{ V}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ [1]		3		%/V
$\Delta V_{OUT(\Delta IOUT)}$	Transient Load Response	$V_{INL} = V_{LDO4} + 0.3\text{ V}$ to $5.5\text{ V}$ , $1\text{ mA} < I_{OUT} < I_{OUT\_MAX}$ , $t_r = 10\text{ }\mu\text{s}$ , $V_{LDO4} = 1.8\text{ V}$ [1]	-3		3	%
PSRR	Power Supply Rejection ratio	$f = 10\text{ Hz}$ to $10\text{ KHz}$ , $I_{OUT} = 10\%$ of $I_{OUT\_MAX}$ [1]		40		dB
$V_{soft\_strup}$	Soft-start slew rate	$I_{OUT} = 0\text{ mA}$ , $10\%$ to $90\%$ of $V_{LDO4}$ [1]		6.0		mV/ $\mu\text{s}$
$V_{ov\_srtup}$	Overshoot at startup	$I_{OUT} = 0\text{ mA}$ [1]			20	mV
$t_{EN}$	Enable time	EN rising to $90\%$ of output voltage, $V_{LDO4} = 1.8\text{ V}$ [1]		300	500	$\mu\text{s}$
POK_90	Output Power good	Percentage of $V_{LDO4}$ configuration	86	90	94	%
$t_{POK\_Deb}$	POK debounce time	POK falling		300		$\mu\text{s}$
$R_{DIS}$	Active Discharge Resistance			100	200	$\Omega$
$C_{OUT}$	Output capacitance	Minimum nominal capacitance [1]	2.2		10	$\mu\text{F}$

[1] Not tested in production. Guaranteed by design

13.11 LSW1

Table 182. LSW1 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{LSW1IN}$	Input voltage range	LSW1IN pin [1]	1.2		5.5	V
$I_Q$	Quiescent current	Switch enabled, No load, $V_{LSW1IN} = 1.8\text{ V}$		0.5	50	nA
$I_{SHDN}$	Shutdown current	$V_{LSW1IN} = 3.3\text{ V}$		5	700	nA
$R_{DSON}$	Switch ON resistance	$V_{LSW1IN} = 1.8\text{ V}$ , $I_{LOAD} = 150\text{ mA}$		150	220	m $\Omega$
$t_{EN}$	Enable time	Time to LSW1OUT $10\%$ from EN, $V_{LSW1IN} = 1.8\text{ V}$ [1]		70	110	$\mu\text{s}$
$t_{RAMP}$	Output rise time	$CL = 10\text{ }\mu\text{F}$ , $V_{SWIN} = 1.8\text{ V}$ , LSW1OUT $10\%$ to $90\%$ [1]	6	12	18	mV/us
$R_{DIS}$	Active Discharge Resistance	Load switch is off		95	150	$\Omega$

[1] Not tested in production. Guaranteed by design

### 13.12 LSW2

Table 183. LSW2 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VLSW1IN	Input voltage range	VLSW1IN pin <sup>[1]</sup>	1.2		5.5	V
I <sub>Q</sub>	Quiescent current	Switch enabled, No load, $V_{LSW1IN} = 1.8\text{ V}$		0.5	50	nA
I <sub>SHDN</sub>	Shutdown current	$V_{LSW1IN} = 3.3\text{ V}$		5	700	nA
R <sub>DSON</sub>	Switch ON resistance	$V_{LSW1IN} = 1.8\text{ V}$ , I <sub>LOAD</sub> = 150 mA		150	220	mΩ
t <sub>EN</sub>	Enable time	Time to LSW2OUT 10 % from EN, $V_{LSW1IN} = 1.8\text{ V}$ <sup>[1]</sup>		70	110	μs
t <sub>RAMP</sub>	Output rise time	CL = 10 μF, $V_{SWIN} = 1.8\text{ V}$ , LSW2OUT 10 % to 90 % <sup>[1]</sup>	6	12	18	mV/us
R <sub>DIS</sub>	Active Discharge Resistance	Load switch is off		95	150	Ω

[1] Not tested in production. Guaranteed by design

### 13.13 LSW3

Table 184. LSW3 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VLSW1IN	Input voltage range	VLSW1IN pin <sup>[1]</sup>	1.2		5.5	V
I <sub>Q</sub>	Quiescent current	Switch enabled, No load, $V_{LSW1IN} = 1.8\text{ V}$		0.5	50	nA
I <sub>SHDN</sub>	Shutdown current	$V_{LSW1IN} = 3.3\text{ V}$		5	700	nA
R <sub>DSON</sub>	Switch ON resistance	$V_{LSW1IN} = 1.8\text{ V}$ , I <sub>LOAD</sub> = 150 mA		150	220	mΩ
t <sub>EN</sub>	Enable time	Time to LSW3OUT 10 % from EN, $V_{LSW1IN} = 1.8\text{ V}$ <sup>[1]</sup>		70	110	μs
t <sub>RAMP</sub>	Output rise time	CL = 10 μF, $V_{SWIN} = 1.8\text{ V}$ , LSW3OUT 10 % to 90 % <sup>[1]</sup>	6	12	18	mV/us
R <sub>DIS</sub>	Active Discharge Resistance	Load switch is off		95	150	Ω

[1] Not tested in production. Guaranteed by design

### 13.14 LSW4

Table 185. LSW4 description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ }^\circ\text{C} \sim +85\text{ }^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>LSW4IN</sub>	Input voltage range	LSW4IN pin <sup>[1]</sup>	1.2		5.5	V

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Table 185. LSW4 description...continued

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_Q$	Quiescent current	Switch enabled, No load, $V_{LSW4IN} = 1.8\text{ V}$		0.5	50	nA
$I_{SHDN}$	Shutdown current	$V_{LSW4IN} = 3.3\text{ V}$		5	700	nA
$R_{DS(ON)}$	Switch ON resistance	$V_{LSW4IN} = 1.8\text{ V}$ , $I_{LOAD} = 150\text{ mA}$		150	220	mΩ
$t_{EN}$	Enable time	Time to LSW4OUT 10 % from EN, $V_{LSWxIN} = 1.8\text{ V}$ <sup>[1]</sup>		70	110	μs
$t_{RAMP}$	Output rise time	$CL = 10\text{ μF}$ , $V_{LSW4IN} = 1.8\text{ V}$ , LSW4OUT 10 % to 90 % <sup>[1]</sup>	6	12	18	mV/us
$R_{DIS}$	Active Discharge Resistance	Load switch is off		95	150	Ω

[1] Not tested in production. Guaranteed by design

13.15 LED driver (LED1/LED2/LED3/LED4)

Table 186. LED driver (LED1/LED2/LED3/LED4) description

Unless otherwise specified,  $V_{SYS} = 3.8\text{ V}$ ,  $V_{INB14} = V_{INB23} = 3.8\text{ V}$ ,  $V_{INL} = 3.8\text{ V}$ ,  $V_{INL1} = V_{BUCK4}$ ,  $V_{LSW1IN} = V_{LSWW4IN} = 3.3\text{ V}$ ,  $T_A = -40\text{ °C} \sim +85\text{ °C}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{LEDIN}$	Input voltage range	LSW1IN, LSW4IN pin <sup>[1]</sup>	3.0		5.5	V
$I_Q$	Quiescent current	$V_{LSW1IN} = V_{LSW4IN} = 3.3\text{ V}$ , All LED channels are enabled, load = 0 mA		80	100	μA
$I_{LED}$	LED current range	Current programmable range	0.625		20	mA
$I_{LED\_STEP}$	LED current step			0.625		mA
$V_{HR}$	Headroom voltage	$V_{LEDIN} - V_{LEDx}$		168	200	mV
$I_{LED\_ACC}$	Current accuracy	$I_{LEDx} = 10\text{ mA}$ , $T_A = 25\text{ °C}$	-1.5	0	1.5	%
		$I_{LEDx} = 10\text{ mA}$ , $T_A = -40 \sim 85\text{ °C}$	-4	0	4	%
$I_{LED\_MIS}$	Current mismatch	$I_{LEDx} = 10\text{ mA}$	-3	0	3	%
$t_{ON}$	LED ON time	BLINK Mode, LED_TON = 0x1	180	200	220	ms
$t_{OFF}$	LED OFF time	BLINK Mode, LED_TOFF = 0x1	180	200	220	ms
$t_{RU}$	LED Ramp Up time	BLINK Mode, P1_UP_STEP = 0x0, P1_UP_DLY = 0x0	470	523	575	ms
$t_{RD}$	LED Ramp Down time	BLINK Mode, P1_DN_STEP = 0x0, P1_DN_DLY = 0x0	470	523	575	ms

[1] Not tested in production. Guaranteed by design

### 13.16 I<sup>2</sup>C interface and logic I/O

Table 187. I<sup>2</sup>C interface and logic I/O description

Unless otherwise specified, VSYS = 3.8 V, VINB14 = VINB23 = 3.8 V, VINL = 3.8 V, VINL1 = VBUCK4, VLSW1IN = VLSWW4IN = 3.3 V, TA = -40 °C ~ +85 °C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>SCL, SDA</b>						
f <sup>2</sup> C	I <sup>2</sup> C Clock frequency		—	—	1	MHz
V <sub>IH</sub>	High-level Input voltage	SCL, SDA; VSYS= 3.0 V to 5.5 V	1.2	—	—	V
V <sub>IL</sub>	Low-level Input voltage	SCL, SDA; VSYS= 3.0 V to 5.5 V	—	—	0.4	V
V <sub>hys</sub>	Hysteresis of Schmitt trigger inputs		0.01	—	—	V
V <sub>OL</sub>	Low-level output voltage	SDA, Iload = 20 mA, VSYS = 3.0 V to 5.5 V	0	—	0.4	V
t <sub>HD,STA</sub>	Hold time (repeated) START condition	Fast mode plus; After this period, the first clock pulse is generated <sup>[1]</sup>	0.26	—	—	μs
t <sub>LOW</sub>	LOW period of I <sup>2</sup> C clock	Fast mode plus <sup>[1]</sup>	0.5	—	—	μs
t <sub>HIGH</sub>	HIGH period of I <sup>2</sup> C clock	Fast mode plus <sup>[1]</sup>	0.26	—	—	μs
t <sub>SU,STA</sub>	Setup time (repeated) START condition	Fast mode plus <sup>[1]</sup>	0.26	—	—	μs
t <sub>HD,DAT</sub>	Data Hold time	Fast mode plus <sup>[1]</sup>	0	—	—	μs
t <sub>SU,DAT</sub>	Data Setup time	Fast mode plus <sup>[1]</sup>	50	—	—	ns
t <sub>r</sub>	Rise time of I2C_SCL and I2C_SDA signals	Fast mode plus <sup>[1]</sup>	—	—	120	ns
t <sub>f</sub>	Fall time of I2C_SCL and I2C_SDA signals	Fast mode plus <sup>[1]</sup>	—	—	120	ns
t <sub>SU,STO</sub>	Setup time for STOP condition	Fast mode plus <sup>[1]</sup>	0.26	—	—	μs
t <sub>BUF</sub>	Bus free time between STOP and START condition	Fast mode plus <sup>[1]</sup>	0.5	—	—	μs
t <sub>VD,DAT</sub>	Data valid time	Fast mode plus <sup>[1]</sup>	—	—	0.45	μs
t <sub>VD,ACK</sub>	Data valid acknowledge time	Fast mode plus <sup>[1]</sup>	—	—	0.45	μs
t <sub>SP</sub>	Pulse width of spikes that must be suppressed by input filter	<sup>[1]</sup>	0	—	50	ns

[1] Not tested in production. Guaranteed by design

14 Package outline

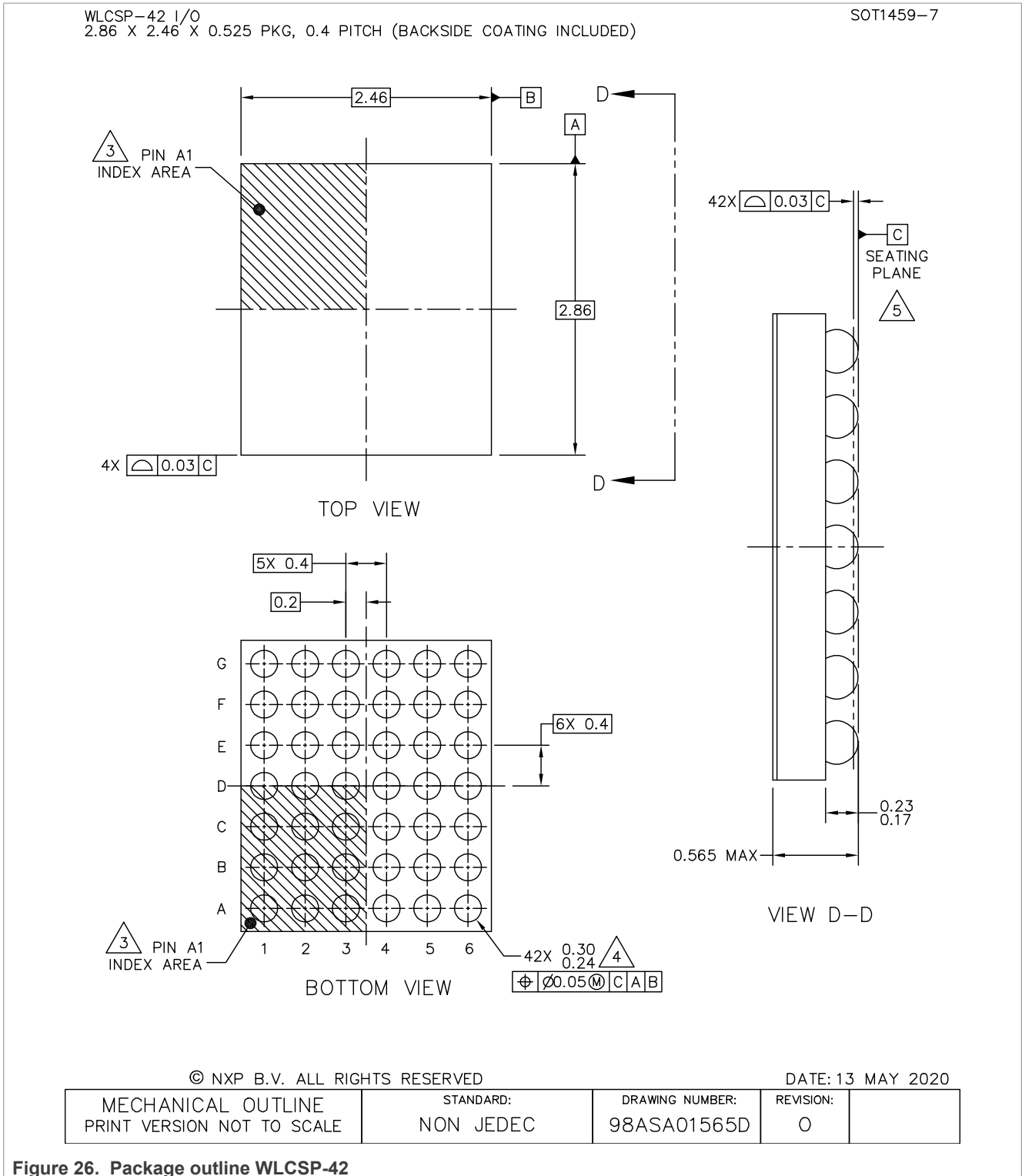
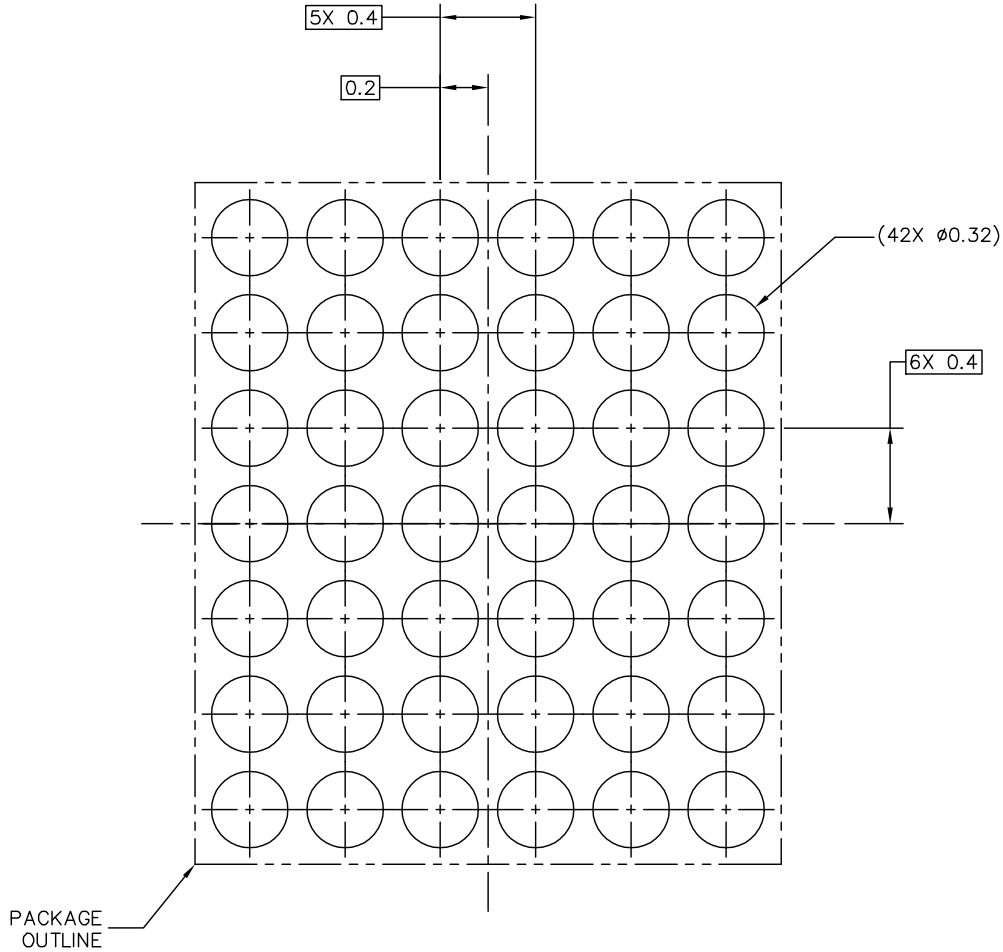


Figure 26. Package outline WLCSP-42



WLCSP-42 I/O  
2.86 X 2.46 X 0.525 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1459-7



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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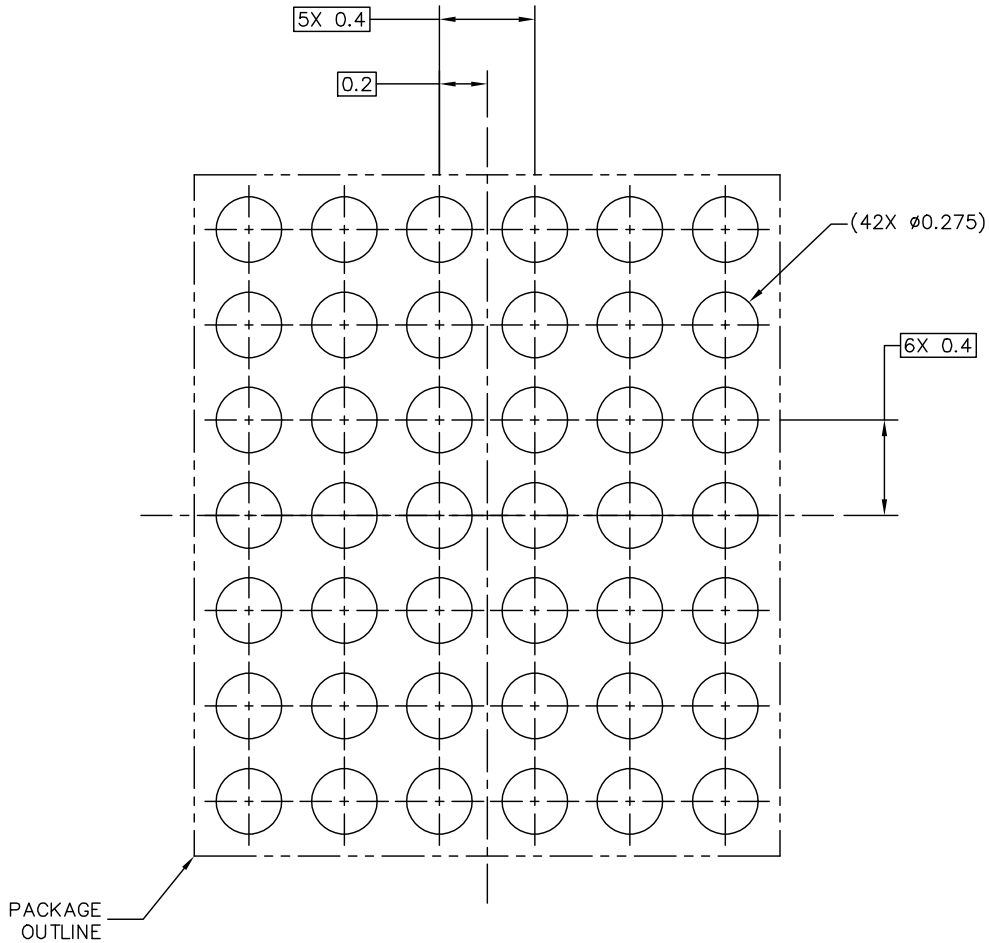
DATE: 13 MAY 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01565D	REVISION: 0	
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Figure 27. PCB Design Guidelines – Solder Mask Opening Pattern

WLCSP-42 I/O  
2.86 X 2.46 X 0.525 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1459-7



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 28. PCB Design Guidelines – Solder Paste Stencil

## 15 Revision history

Table 188. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9460 v.3.4	20240110	Product data sheet	—	PCA9460 v. 3.3
Modifications	<ul style="list-style-type: none"> <li>• <a href="#">Table 169</a>: Updated format of table; no change to min/max values</li> <li>• <a href="#">Table 170</a>: Added characteristics for <math>T_{stg}</math>; updated format of table; no change to min/max values</li> </ul>			
PCA9460 v.3.3	20231006	Product data sheet	—	PCA9460 v. 3.2
PCA9460 v.3.2	20230901	Product data sheet	—	PCA9460 v. 3.1
PCA9460 v.3.1	20230217	Product data sheet	—	PCA9460 v. 3.0
PCA9460 v. 3.0	20221128	Product data sheet	202211037I	PCA9460 v. 2.0
PCA9460 v. 2.0	20220309	Product data sheet	—	PCA9460 v.1.0
PCA9460 v.1.0	20210804	Preliminary data sheet	—	—

## Legal information

### Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <https://www.nxp.com>.

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**13-channel power management integrated circuit (PMIC) for ultra-low power applications**

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